EFM32 Happy Gecko Family
EFM32HG Data Sheet

The EFM32 Happy Gecko MCUs are the world's most energy-friendly microcontrollers.

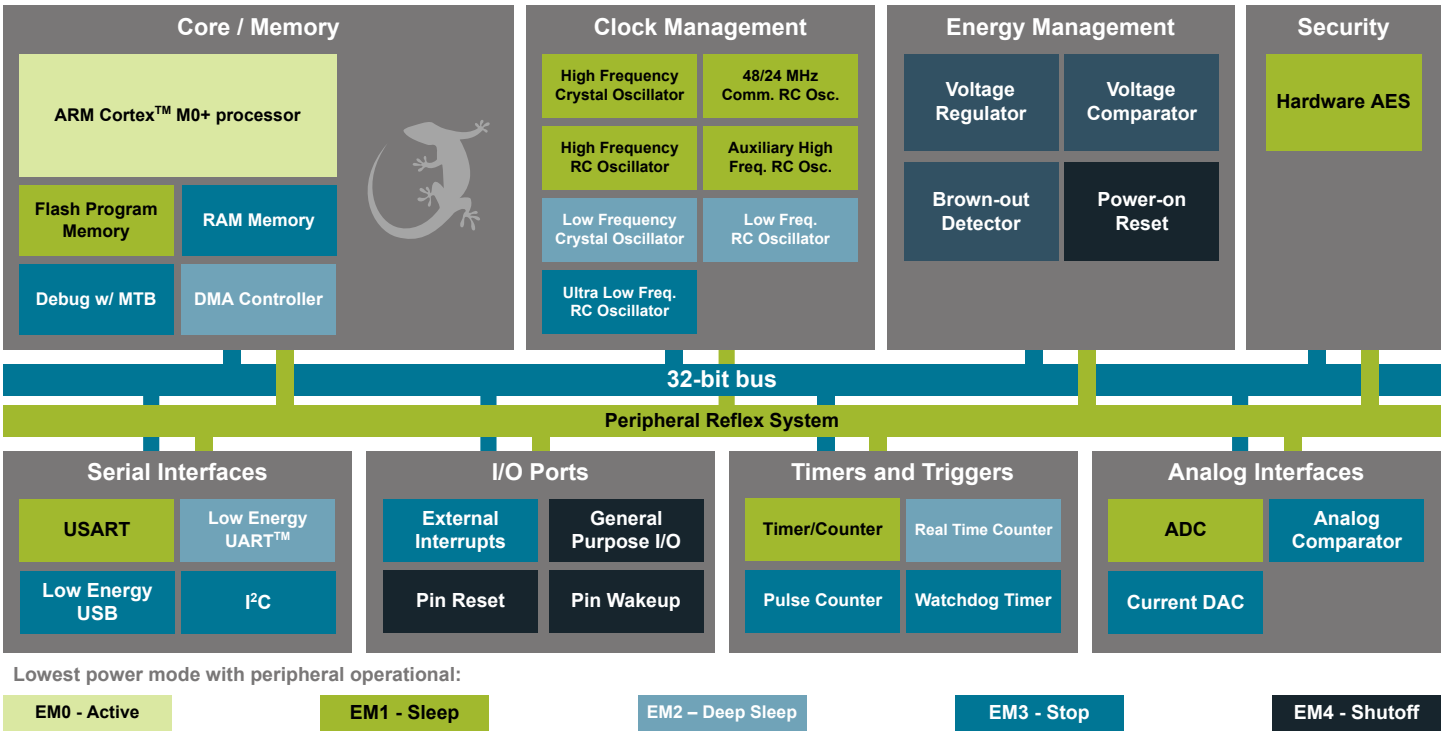
The EFM32HG offers unmatched performance and ultra low power consumption in both active and sleep modes. EFM32HG devices consume as little as 0.6 µA in Stop mode and 127 µA/MHz in Run mode. It also features autonomous peripherals, high overall chip and analog integration, and the performance of the industry standard 32-bit ARM Cortex-M0+ processor, making it perfect for battery-powered systems and systems with high-performance, low-energy requirements.

EFM32HG applications include the following:

- Energy, gas, water and smart metering
- Health and fitness applications
- Smart accessories
- Alarm and security systems
- Industrial and home automation

KEY FEATURES

- ARM Cortex-M0+ at 25 MHz
- Ultra low power operation
  - 0.6 µA current in Stop (EM3), with brown-out detection and RAM retention
  - 51 µA/MHz in EM1
  - 127 µA/MHz in Run mode (EM0)
- Fast wake-up time of 2 µs
- Hardware cryptography (AES)
- Up to 64 kB of Flash and 8 kB of RAM



1. Feature List

- ARM Cortex-M0+ CPU platform
  - High Performance 32-bit processor @ up to 25 MHz
  - Wake-up Interrupt Controller
  - SysTick System Timer
- Flexible Energy Management System
  - 20 nA @ 3 V Shutoff Mode
  - 0.6 µA @ 3 V Stop Mode, including Power-on Reset, Brown-out Detector, RAM and CPU retention
  - 0.9 µA @ 3 V Deep Sleep Mode, including RTC with 32.768 kHz oscillator, Power-on Reset, Brown-out Detector, RAM and CPU retention
  - 51 µA/MHz @ 3 V Sleep Mode
  - 127 µA/MHz @ 3 V Run Mode, with code executed from flash
- 64/32 kB Flash
- 8/4 kB RAM
- Up to 37 General Purpose I/O pins
  - Configurable push-pull, open-drain, pull-up/down, input filter, drive strength
  - Configurable peripheral I/O locations
  - Up to 16 asynchronous external interrupts
  - Output state retention and wake-up from Shutoff Mode
- 6 Channel DMA Controller
- 6 Channel Peripheral Reflex System (PRS) for autonomous inter-peripheral signaling
- Hardware AES with 128-bit keys in 54 cycles
- Timers/Counters
  - 3× 16-bit Timer/Counter
    - 3×3 Compare/Capture/PWM channels
    - Dead-Time Insertion on TIMER0
  - 1× 24-bit Real-Time Counter
  - 1× 16-bit Pulse Counter
  - Watchdog Timer with dedicated RC oscillator @ 50 nA
- Communication interfaces
  - Up to 2× Universal Synchronous/Asynchronous Receiver/Transmitter
    - UART/SPI/SmartCard (ISO 7816)/IrDA/I2S
    - Triple buffered full/half-duplex operation
  - Low Energy UART
    - Autonomous operation with DMA in Deep Sleep Mode
  - I^2C Interface with SMBus support
    - Address recognition in Stop Mode
  - Low Energy Universal Serial Bus (USB) Device
    - Fully USB 2.0 compliant
    - On-chip PHY and embedded 5V to 3.3V regulator
    - Crystal-free operation
- Ultra low power precision analog peripherals
  - 12-bit 1 Msamples/s Analog-to-Digital Converter
    - 4 single-ended channels/2 differential channels
    - On-chip temperature sensor
  - Current Digital-to-Analog Converter
    - Selectable current range between 0.05 and 64 µA
  - 1× Analog Comparator
    - Capacitive sensing with up to 5 inputs
  - Supply Voltage Comparator
- Ultra efficient Power-on Reset and Brown-Out Detector

- Debug Interface
  - 2-pin Serial Wire Debug interface
  - Micro Trace Buffer (MTB)
- Pre-Programmed USB/UART Bootloader
- Temperature range -40 to 85 ºC (EFM32HGxxxFxx) or -40 to 105 ºC (EFM32HGxxxFxxN)
- Single power supply 1.98 to 3.8 V
- Packages:
  - CSP36 (3×3 mm)
  - QFN24 (5×5 mm)
  - QFN32 (6×6 mm)
  - TQFP48 (7×7 mm)

2. Ordering Information

The following table shows the available EFM32HG devices.

Table 2.1. Ordering Information

Ordering Code	Flash (kB)	RAM (kB)	Max Speed (MHz)	Supply Voltage (V)	Temperature (ºC)	Package
EFM32HG108F32-C-QFN24	32	4	25	1.98 - 3.8	-40 - 85	QFN24
EFM32HG108F64-C-QFN24	64	8	25	1.98 - 3.8	-40 - 85	QFN24
EFM32HG110F32-C-QFN24	32	4	25	1.98 - 3.8	-40 - 85	QFN24
EFM32HG110F64-C-QFN24	64	8	25	1.98 - 3.8	-40 - 85	QFN24
EFM32HG210F32-C-QFN32	32	4	25	1.98 - 3.8	-40 - 85	QFN32
EFM32HG210F64-C-QFN32	64	8	25	1.98 - 3.8	-40 - 85	QFN32
EFM32HG222F32-C-QFP48	32	4	25	1.98 - 3.8	-40 - 85	TQFP48
EFM32HG222F64-C-QFP48	64	8	25	1.98 - 3.8	-40 - 85	TQFP48
EFM32HG308F32-C-QFN24	32	8	25	1.98 - 3.8	-40 - 85	QFN24
EFM32HG308F64-C-QFN24	64	8	25	1.98 - 3.8	-40 - 85	QFN24
EFM32HG309F32-C-QFN24	32	8	25	1.98 - 3.8	-40 - 85	QFN24
EFM32HG309F64-C-QFN24	64	8	25	1.98 - 3.8	-40 - 85	QFN24
EFM32HG310F32-C-QFN32	32	8	25	1.98 - 3.8	-40 - 85	QFN32
EFM32HG310F64-C-QFN32	64	8	25	1.98 - 3.8	-40 - 85	QFN32
EFM32HG321F32-C-QFP48	32	8	25	1.98 - 3.8	-40 - 85	TQFP48
EFM32HG321F64-C-QFP48	64	8	25	1.98 - 3.8	-40 - 85	TQFP48
EFM32HG322F32-C-QFP48	32	8	25	1.98 - 3.8	-40 - 85	TQFP48
EFM32HG322F64-C-QFP48	64	8	25	1.98 - 3.8	-40 - 85	TQFP48
EFM32HG350F32-C-CSP36	32	8	25	1.98 - 3.8	-40 - 85	CSP36
EFM32HG350F64-C-CSP36	64	8	25	1.98 - 3.8	-40 - 85	CSP36
EFM32HG108F32N-C-QFN24	32	4	25	1.98 - 3.8	-40 - 105	QFN24
EFM32HG108F64N-C-QFN24	64	8	25	1.98 - 3.8	-40 - 105	QFN24
EFM32HG110F32N-C-QFN24	32	4	25	1.98 - 3.8	-40 - 105	QFN24
EFM32HG110F64N-C-QFN24	64	8	25	1.98 - 3.8	-40 - 105	QFN24
EFM32HG210F32N-C-QFN32	32	4	25	1.98 - 3.8	-40 - 105	QFN32
EFM32HG210F64N-C-QFN32	64	8	25	1.98 - 3.8	-40 - 105	QFN32
EFM32HG222F32N-C-QFP48	32	4	25	1.98 - 3.8	-40 - 105	TQFP48
EFM32HG222F64N-C-QFP48	64	8	25	1.98 - 3.8	-40 - 105	TQFP48
EFM32HG308F32N-C-QFN24	32	8	25	1.98 - 3.8	-40 - 105	QFN24
EFM32HG308F64N-C-QFN24	64	8	25	1.98 - 3.8	-40 - 105	QFN24
EFM32HG309F32N-C-QFN24	32	8	25	1.98 - 3.8	-40 - 105	QFN24
EFM32HG309F64N-C-QFN24	64	8	25	1.98 - 3.8	-40 - 105	QFN24

Ordering Code	Flash (kB)	RAM (kB)	Max Speed (MHz)	Supply Voltage (V)	Temperature (ºC)	Package
EFM32HG310F32N-C-QFN32	32	8	25	1.98 - 3.8	-40 - 105	QFN32
EFM32HG310F64N-C-QFN32	64	8	25	1.98 - 3.8	-40 - 105	QFN32
EFM32HG321F32N-C-QFP48	32	8	25	1.98 - 3.8	-40 - 105	TQFP48
EFM32HG321F64N-C-QFP48	64	8	25	1.98 - 3.8	-40 - 105	TQFP48
EFM32HG322F32N-C-QFP48	32	8	25	1.98 - 3.8	-40 - 105	TQFP48
EFM32HG322F64N-C-QFP48	64	8	25	1.98 - 3.8	-40 - 105	TQFP48

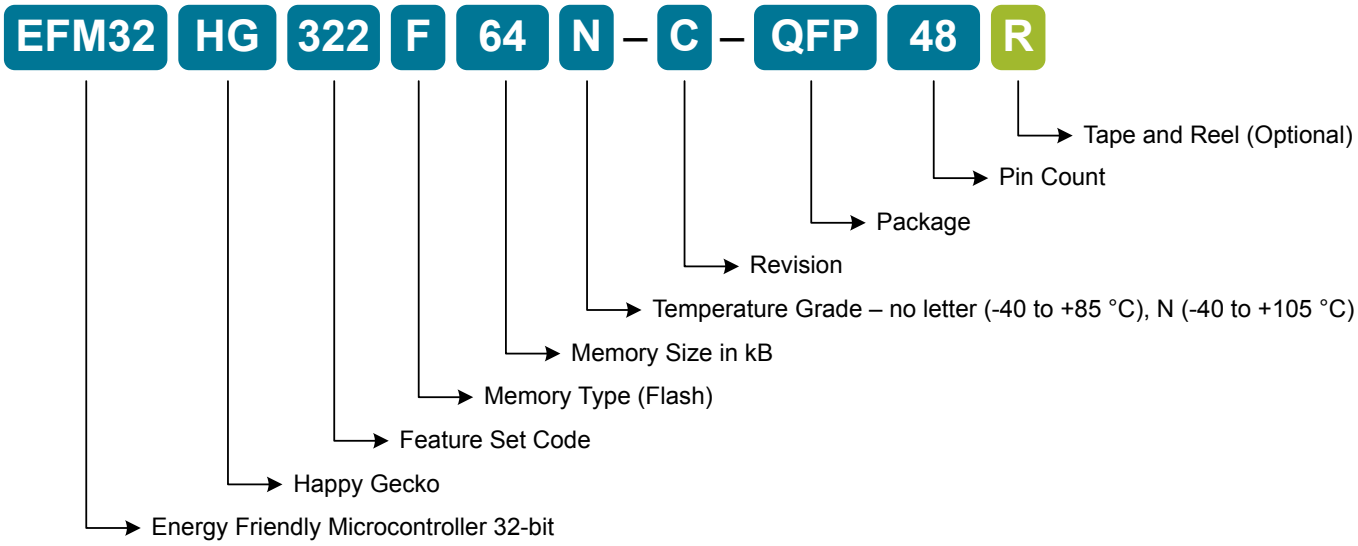


Figure 2.1. Ordering Code Decoder

Adding the suffix 'R' to the part number (e.g. EFM32HG322F64-C-QFP48R) denotes tape and reel.

Adding 'N' after the memory size (e.g. EFM32HG322F64N-C-QFP48) denotes -40 to +105 ºC temperature grade.

Visit http://www.silabs.com for information on global distributors and representatives.

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3. System Summary

3.1 System Introduction

The EFM32 MCUs are the world's most energy friendly microcontrollers. With a unique combination of the powerful 32-bit ARM Cortex-M0+, innovative low energy techniques, short wake-up time from energy saving modes, and a wide selection of peripherals, the EFM32HG microcontroller is well suited for any battery operated application as well as other systems requiring high performance and low-energy consumption. This section gives a short introduction to each of the modules in general terms and also shows a summary of the configuration for the EFM32HG devices. For a complete feature set and in-depth information on the modules, the reader is referred to the EFM32HG Reference Manual.

A block diagram of the EFM32HG is shown in the following figure.

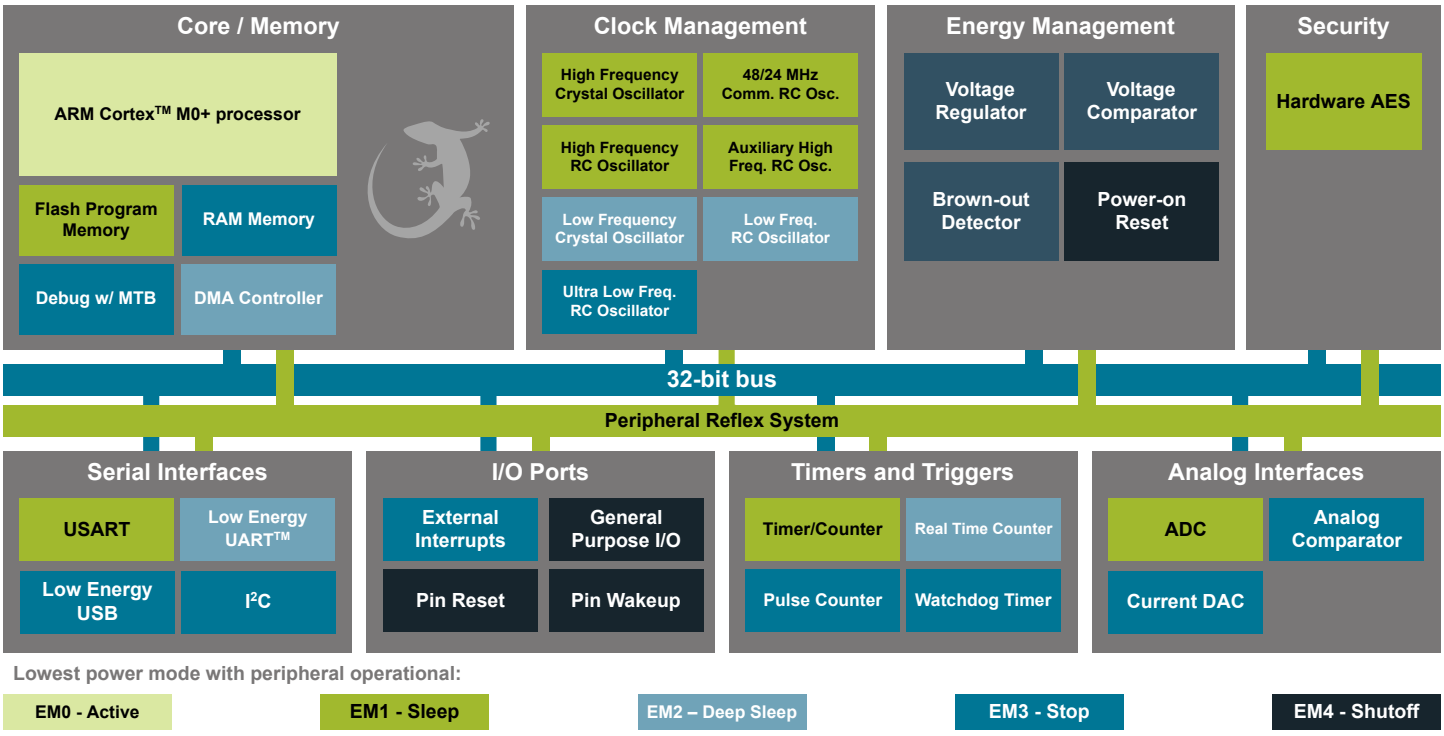


Figure 3.1. Block Diagram

3.1.1 ARM Cortex-M0+ Core

The ARM Cortex-M0+ includes a 32-bit RISC processor which can achieve as much as 0.9 Dhrystone MIPS/MHz. A wake-up Interrupt Controller handling interrupts triggered while the CPU is asleep is included as well. The EFM32 implementation of the Cortex-M0+ is described in detail in *ARM Cortex-M0+ Devices Generic User Guide*.

3.1.2 Debug Interface (DBG)

This device includes hardware debug support through a 2-pin serial-wire debug interface and a Micro Trace Buffer (MTB) for data/instruction tracing.

3.1.3 Memory System Controller (MSC)

The Memory System Controller (MSC) is the program memory unit of the EFM32HG microcontroller. The flash memory is readable and writable from both the Cortex-M0+ and DMA. The flash memory is divided into two blocks; the main block and the information block. Program code is normally written to the main block. Additionally, the information block is available for special user data and flash lock bits. There is also a read-only page in the information block containing system and device calibration data. Read and write operations are supported in the energy modes EM0 and EM1.

3.1.4 Direct Memory Access Controller (DMA)

The Direct Memory Access (DMA) controller performs memory operations independently of the CPU. This has the benefit of reducing the energy consumption and the workload of the CPU, and enables the system to stay in low energy modes when moving for instance data from the USART to RAM or from the External Bus Interface to a PWM-generating timer. The DMA controller uses the PL230 µDMA controller licensed from ARM.

3.1.5 Reset Management Unit (RMU)

The RMU is responsible for handling the reset functionality of the EFM32HG.

3.1.6 Energy Management Unit (EMU)

The Energy Management Unit (EMU) manage all the low energy modes (EM) in EFM32HG microcontrollers. Each energy mode manages if the CPU and the various peripherals are available. The EMU can also be used to turn off the power to unused SRAM blocks.

3.1.7 Clock Management Unit (CMU)

The Clock Management Unit (CMU) is responsible for controlling the oscillators and clocks on-board the EFM32HG. The CMU provides the capability to turn on and off the clock on an individual basis to all peripheral modules in addition to enable/disable and configure the available oscillators. The high degree of flexibility enables software to minimize energy consumption in any specific application by not wasting power on peripherals and oscillators that are inactive.

3.1.8 Watchdog (WDOG)

The purpose of the watchdog timer is to generate a reset in case of a system failure, to increase application reliability. The failure may e.g. be caused by an external event, such as an ESD pulse, or by a software failure.

3.1.9 Peripheral Reflex System (PRS)

The Peripheral Reflex System (PRS) system is a network which lets the different peripheral module communicate directly with each other without involving the CPU. Peripheral modules which send out Reflex signals are called producers. The PRS routes these reflex signals to consumer peripherals which apply actions depending on the data received. The format for the Reflex signals is not given, but edge triggers and other functionality can be applied by the PRS.

3.1.10 Low Energy USB

The unique Low Energy USB peripheral provides a full-speed USB 2.0 compliant device controller and PHY with ultra-low current consumption. The device supports both full-speed (12 MBit/s) and low speed (1.5 MBit/s) operation, and includes a dedicated USB oscillator with clock recovery mechanism for crystal-free operation. No external components are required. The Low Energy Mode ensures the current consumption is optimized and enables USB communication on a strict power budget. The USB device includes an internal dedicated descriptor-based Scatter/Gather DMA and supports up to 3 OUT endpoints and 3 IN endpoints, in addition to endpoint 0. The on-chip PHY includes software controllable pull-up and pull-down resistors.

3.1.11 Inter-Integrated Circuit Interface (I2C)

The I^2C module provides an interface between the MCU and a serial I^2C-bus. It is capable of acting as both a master and a slave, and supports multi-master buses. Both standard-mode, fast-mode and fastmode plus speeds are supported, allowing transmission rates all the way from 10 kbit/s up to 1 Mbit/s. Slave arbitration and timeouts are also provided to allow implementation of an SMBus compliant system. The interface provided to software by the I^2C module, allows both fine-grained control of the transmission process and close to automatic transfers. Automatic recognition of slave addresses is provided in all energy modes.

3.1.12 Universal Synchronous/Asynchronous Receiver/Transmitter (USART)

The Universal Synchronous Asynchronous serial Receiver and Transmitter (USART) is a very flexible serial I/O module. It supports full duplex asynchronous UART communication as well as RS-485, SPI, MicroWire and 3-wire. It can also interface with ISO7816 SmartCards, IrDA and I2S devices.

3.1.13 Pre-Programmed USB/UART Bootloader

The bootloader presented in application note AN0042 is pre-programmed in the device at factory. The bootloader enables users to program the EFM32 through a UART or a USB CDC class virtual UART without the need for a debugger. The autobaud feature, interface and commands are described further in the application note.

3.1.14 Low Energy Universal Asynchronous Receiver/Transmitter (LEUART)

The unique LEUART™, the Low Energy UART, is a UART that allows two-way UART communication on a strict power budget. Only a 32.768 kHz clock is needed to allow UART communication up to 9600 baud/ s. The LEUART includes all necessary hardware support to make asynchronous serial communication possible with minimum of software intervention and energy consumption.

3.1.15 Timer/Counter (TIMER)

The 16-bit general purpose Timer has 3 compare/capture channels for input capture and compare/Pulse- Width Modulation (PWM) output. TIMER0 also includes a Dead-Time Insertion module suitable for motor control applications.

3.1.16 Real Time Counter (RTC)

The Real Time Counter (RTC) contains a 24-bit counter and is clocked either by a 32.768 kHz crystal oscillator, or a 32.768 kHz RC oscillator. In addition to energy modes EM0 and EM1, the RTC is also available in EM2. This makes it ideal for keeping track of time since the RTC is enabled in EM2 where most of the device is powered down.

3.1.17 Pulse Counter (PCNT)

The Pulse Counter (PCNT) can be used for counting pulses on a single input or to decode quadrature encoded inputs. It runs off either the internal LFACLK or the PCNTn_S0IN pin as external clock source. The module may operate in energy mode EM0 - EM3.

3.1.18 Analog Comparator (ACMP)

The Analog Comparator is used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. Inputs can either be one of the selectable internal references or from external pins. Response time and thereby also the current consumption can be configured by altering the current supply to the comparator.

3.1.19 Voltage Comparator (VCMP)

The Voltage Supply Comparator is used to monitor the supply voltage from software. An interrupt can be generated when the supply falls below or rises above a programmable threshold. Response time and thereby also the current consumption can be configured by altering the current supply to the comparator.

3.1.20 Analog to Digital Converter (ADC)

The ADC is a Successive Approximation Register (SAR) architecture, with a resolution of up to 12 bits at up to one million samples per second. The integrated input mux can select inputs from 4 external pins and 6 internal signals.

3.1.21 Current Digital to Analog Converter (IDAC)

The current digital to analog converter can source or sink a configurable constant current, which can be output on, or sinked from pin or ADC. The current is configurable with several ranges of various step sizes.

3.1.22 Advanced Encryption Standard Accelerator (AES)

The AES accelerator performs AES encryption and decryption with 128-bit. Encrypting or decrypting one 128-bit data block takes 52 HFCORECLK cycles with 128-bit keys. The AES module is an AHB slave which enables efficient access to the data and key registers. All write accesses to the AES module must be 32-bit operations, i.e. 8- or 16-bit operations are not supported.

3.1.23 General Purpose Input/Output (GPIO)

In the EFM32HG, there are up to 37 General Purpose Input/Output (GPIO) pins, which are divided into ports with up to 16 pins each. These pins can individually be configured as either an output or input. More advanced configurations like open-drain, filtering and drive strength can also be configured individually for the pins. The GPIO pins can also be overridden by peripheral pin connections, like Timer PWM outputs or USART communication, which can be routed to several locations on the device. The GPIO supports up to 16 asynchronous external pin interrupts, which enables interrupts from any pin on the device. Also, the input value of a pin can be routed through the Peripheral Reflex System to other peripherals.

3.2 Configuration Summary

3.2.1 EFM32HG108

The features of the EFM32HG108 is a subset of the feature set described in the EFM32HG Reference Manual. The following table describes device specific implementation of the features.

Table 3.1. EFM32HG108 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA and I2S	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with IrDA and I2S	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[1:0], ACMP0_O
VCMP	Full configuration	NA
GPIO	17 pins	Available pins are shown in 5.1.3 GPIO Pinout Overview

3.2.2 EFM32HG110

The features of the EFM32HG110 is a subset of the feature set described in the EFM32HG Reference Manual. The following table describes device specific implementation of the features.

Table 3.2. EFM32HG110 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA and I2S	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with IrDA and I2S	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[1:0], ACMP0_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:6], ADC0_CH[1:0]
IDAC0	Full configuration	IDAC0_OUT
AES	Full configuration	NA
GPIO	17 pins	Available pins are shown in 5.2.3 GPIO Pinout Overview

3.2.3 EFM32HG210

The features of the EFM32HG210 is a subset of the feature set described in the EFM32HG Reference Manual. The following table describes device specific implementation of the features.

Table 3.3. EFM32HG210 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA and I2S	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with IrDA and I2S	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[1:0], ACMP0_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:4], ADC0_CH[1:0]
IDAC0	Full configuration	IDAC0_OUT
AES	Full configuration	NA
GPIO	24 pins	Available pins are shown in 5.3.3 GPIO Pinout Overview

3.2.4 EFM32HG222

The features of the EFM32HG222 is a subset of the feature set described in the EFM32HG Reference Manual. The following table describes device specific implementation of the features.

Table 3.4. EFM32HG222 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA and I2S	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with IrDA and I2S	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[4:0], ACMP0_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:4], ADC0_CH[1:0]
IDAC0	Full configuration	IDAC0_OUT
AES	Full configuration	NA
GPIO	37 pins	Available pins are shown in 5.4.3 GPIO Pinout Overview

3.2.5 EFM32HG308

The features of the EFM32HG308 is a subset of the feature set described in the EFM32HG Reference Manual. The following table describes device specific implementation of the features.

Table 3.5. EFM32HG308 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
USB	Full configuration	USB_VREGI, USB_VREGO, USB_DM, USB_DMPU, USB_DP
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA and I2S	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with IrDA and I2S	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[1:0], ACMP0_O
VCMP	Full configuration	NA
GPIO	15 pins	Available pins are shown in 5.5.3 GPIO Pinout Overview

3.2.6 EFM32HG309

The features of the EFM32HG309 is a subset of the feature set described in the EFM32HG Reference Manual. The following table describes device specific implementation of the features.

Table 3.6. EFM32HG309 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
USB	Full configuration	USB_VREGI, USB_VREGO, USB_DM, USB_DMPU, USB_DP
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA and I2S	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with IrDA and I2S	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[1:0], ACMP0_O
VCMP	Full configuration	ADC0_CH[1:0]
ADC0	Full configuration	ADC0_CH[9:8]
IDAC0	Full configuration	IDAC0_OUT
AES	Full configuration	NA
GPIO	15 pins	Available pins are shown in 5.6.3 GPIO Pinout Overview

3.2.7 EFM32HG310

The features of the EFM32HG310 is a subset of the feature set described in the EFM32HG Reference Manual. The following table describes device specific implementation of the features.

Table 3.7. EFM32HG310 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
USB	Full configuration	USB_VREGI, USB_VREGO, USB_DM, USB_DMPU, USB_DP
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA and I2S	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with IrDA and I2S	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[1:0], ACMP0_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:5], ADC0_CH[1:0]
IDAC0	Full configuration	IDAC0_OUT
AES	Full configuration	NA
GPIO	22 pins	Available pins are shown in 5.7.3 GPIO Pinout Overview

3.2.8 EFM32HG321

The features of the EFM32HG321 is a subset of the feature set described in the EFM32HG Reference Manual. The following table describes device specific implementation of the features.

Table 3.8. EFM32HG321 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
USB	Full configuration	USB_VREGI, USB_VREGO, USB_DM, USB_DMPU, USB_DP
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA and I2S	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with IrDA and I2S	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[4:0], ACMP0_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:4], ADC0_CH[1:0]
IDAC0	Full configuration	IDAC0_OUT
GPIO	35 pins	Available pins are shown in 5.8.3 GPIO Pinout Overview

3.2.9 EFM32HG322

The features of the EFM32HG322 is a subset of the feature set described in the EFM32HG Reference Manual. The following table describes device specific implementation of the features.

Table 3.9. EFM32HG322 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
USB	Full configuration	USB_VREGI, USB_VREGO, USB_DM, USB_DMPU, USB_DP
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA and I2S	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with IrDA and I2S	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[4:0], ACMP0_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:4], ADC0_CH[1:0]
IDAC0	Full configuration	IDAC0_OUT
AES	Full configuration	NA
GPIO	35 pins	Available pins are shown in 5.9.3 GPIO Pinout Overview

3.2.10 EFM32HG350

The features of the EFM32HG350 is a subset of the feature set described in the EFM32HG Reference Manual. The following table describes device specific implementation of the features.

Table 3.10. EFM32HG350 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M0+	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
USB	Full configuration	USB_VREGI, USB_VREGO, USB_DM, USB_DMPU, USB_DP
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA and I2S	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration with IrDA and I2S	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
PCNT0	Full configuration, 16-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[1:0], ACMP0_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:5], ADC0_CH[1:0]
IDAC0	Full configuration	IDAC0_OUT
AES	Full configuration	NA
GPIO	22 pins	Available pins are shown in 5.10.3 GPIO Pinout Overview

3.3 Memory Map

The EFM32HG memory map is shown in the following figure, with RAM and Flash sizes for the largest memory configuration.

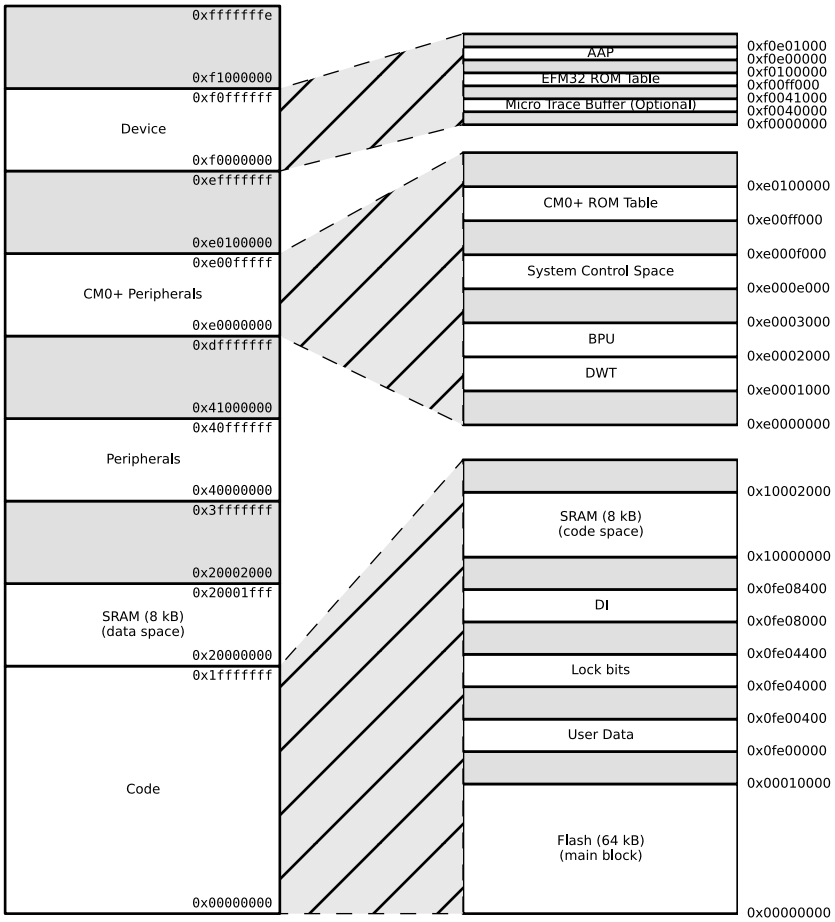


Figure 3.2. System Address Space with Core and Code Space Listing

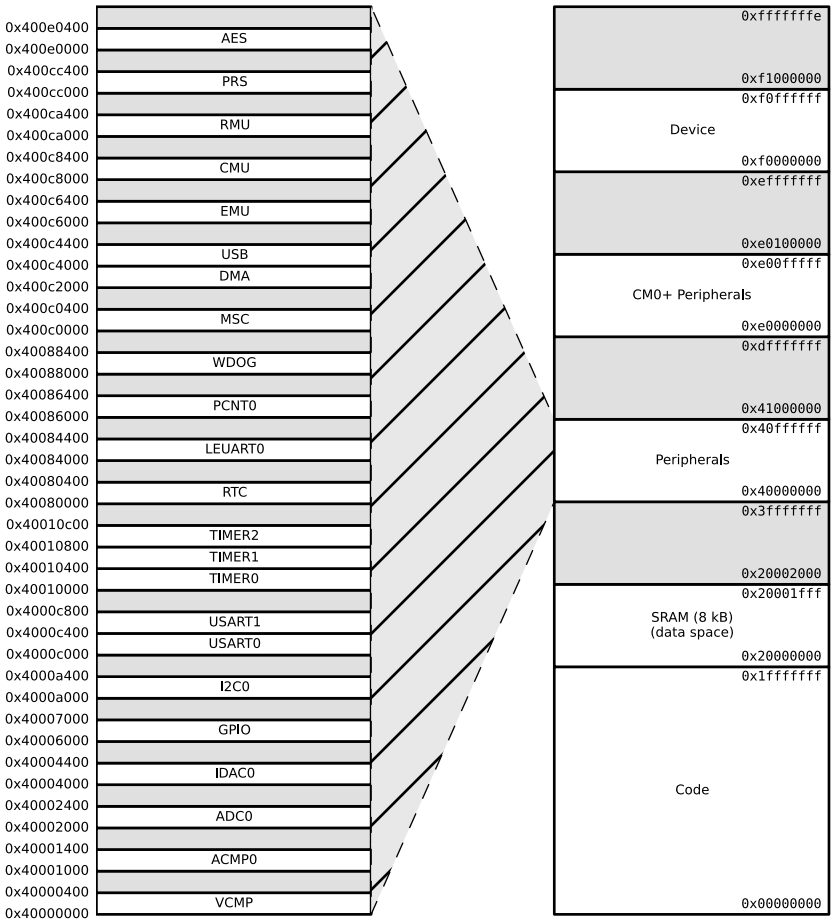


Figure 3.3. System Address Space with Peripheral Listing

4. Electrical Characteristics

4.1 Test Conditions

4.1.1 Typical Values

The typical data are based on T_{AMB}=25°C and V_{DD}=3.0 V, as defined in 4.3 General Operating Conditions, unless otherwise specified.

4.1.2 Minimum and Maximum Values

The minimum and maximum values represent the worst conditions of ambient temperature, supply voltage and frequencies, as defined in 4.3 General Operating Conditions, unless otherwise specified.

4.2 Absolute Maximum Ratings

The absolute maximum ratings are stress ratings, and functional operation under such conditions are not guaranteed. Stress beyond the limits specified in the following table may affect the device reliability or cause permanent damage to the device. Functional operating conditions are given in 4.3 General Operating Conditions.

Table 4.1. Absolute Maximum Ratings

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Storage temperature range	T_{STG}		-40	—	150	°C
Maximum soldering temperature	T_S	Latest IPC/JEDEC J-STD-020 Standard	—	—	260	°C
External main supply voltage	V_{DDMAX}		0	—	3.8	V
Voltage on any I/O pin	V_{IOPIN}		-0.3	—	V_{DD}+0.3	V
Current per I/O pin (sink)	I_{IOMAX_SINK}		—	—	100	mA
Current per I/O pin (source)	I_{IOMAX_SOURCE}		—	—	-100	mA

4.3 General Operating Conditions

Table 4.2. General Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Ambient temperature range (EFM32HGxxxFxx only)	T_{AMB}	-40	—	85	°C
Ambient temperature range (EFM32HGxxxFxxN only)	T_{AMB}	-40	—	105	°C
Operating supply voltage	V_{DDOP}	1.98	—	3.8	V
Internal APB clock frequency	f_{APB}	—	—	25	MHz
Internal AHB clock frequency	f_{AHB}	—	—	25	MHz

4.4 Thermal Characteristics

Table 4.3. Thermal Characteristics

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Thermal resistance, Junction to Ambient	θ_{JA}	QFN24 Package, 4-Layer PCB, Air velocity = 0 m/s	—	25.8	—	°C/W
		QFN32 Package, 4-Layer PCB, Air velocity = 0 m/s	—	24.1	—	°C/W
		TQFP48 Package, 4-Layer PCB, Air velocity = 0 m/s	—	60.0	—	°C/W
Thermal resistance, Junction to Case	θ_{JC}	QFN24 Package, 4-Layer PCB, Air velocity = 0 m/s	—	20.7	—	°C/W
		QFN32 Package, 4-Layer PCB, Air velocity = 0 m/s	—	16.0	—	°C/W
		TQFP48 Package, 4-Layer PCB, Air velocity = 0 m/s	—	15.0	—	°C/W

4.5 Current Consumption

Table 4.4. Current Consumption

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
EM0 current. No prescaling. Running prime number calculation code from Flash.	I_{EM0}	24 MHz HFXO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	148	158	µA/MHz
		24 MHz HFXO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	153	163	µA/MHz
		24 MHz USHFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	161	172	µA/MHz
		24 MHz USHFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	163	174	µA/MHz
		24 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	127	137	µA/MHz
		24 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	129	139	µA/MHz
		21 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	131	140	µA/MHz
		21 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	134	143	µA/MHz
		14 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	134	143	µA/MHz
		14 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	137	145	µA/MHz
		11 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	136	144	µA/MHz
		11 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	139	148	µA/MHz
		6.6 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	142	150	µA/MHz
		6.6 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	146	154	µA/MHz
		1.2 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	184	196	µA/MHz
		1.2 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	194	208	µA/MHz

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
EM1 current	I_{EM1}	24 MHz HFXO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	64	68	µA/MHz
		24 MHz HFXO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	67	71	µA/MHz
		24 MHz USHFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	85	91	µA/MHz
		24 MHz USHFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	86	92	µA/MHz
		24 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	51	55	µA/MHz
		24 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	52	56	µA/MHz
		21 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	53	57	µA/MHz
		21 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	54	58	µA/MHz
		14 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	56	59	µA/MHz
		14 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	57	61	µA/MHz
		11 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	58	61	µA/MHz
		11 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	59	63	µA/MHz
		6.6 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	64	68	µA/MHz
		6.6 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	67	71	µA/MHz
		1.2 MHz HFRCO. all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	106	114	µA/MHz
		1.2 MHz HFRCO. all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=105°C	—	114	126	µA/MHz
EM2 current	I_{EM2}	EM2 current with RTC prescaled to 1 Hz, 32.768 kHz LFRCO, V_{DD}= 3.0 V, T_{AMB}=25°C	—	0.9	1.35	µA
		EM2 current with RTC prescaled to 1 Hz, 32.768 kHz LFRCO, V_{DD}= 3.0 V, T_{AMB}=85°C	—	1.6	3.50	µA
		EM2 current with RTC prescaled to 1 Hz, 32.768 kHz LFRCO, V_{DD}= 3.0 V, T_{AMB}=105°C, EFM32HGxxxFxxN only	—	1.6	8.00	µA

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
EM3 current	I_{EM3}	EM3 current (ULFRCO enabled, LFRCO/LFXO disabled), V_{DD}= 3.0 V, T_{AMB}=25°C	—	0.6	0.90	µA
		EM3 current (ULFRCO enabled, LFRCO/LFXO disabled), V_{DD}= 3.0 V, T_{AMB}=85°C	—	1.2	2.65	µA
		EM3 current (ULFRCO enabled, LFRCO/LFXO disabled), V_{DD}= 3.0 V, T_{AMB}=105°C, EFM32HGxxxFxxN only	—	1.2	7.00	µA
EM4 current	I_{EM4}	V_{DD}= 3.0 V, T_{AMB}=25°C	—	0.02	0.035	µA
		V_{DD}= 3.0 V, T_{AMB}=85°C	—	0.18	0.480	µA
		V_{DD}= 3.0 V, T_{AMB}=105°C, EFM32HGxxxFxxN only	—	0.18	1.500	µA

4.5.1 EM0 Current Consumption

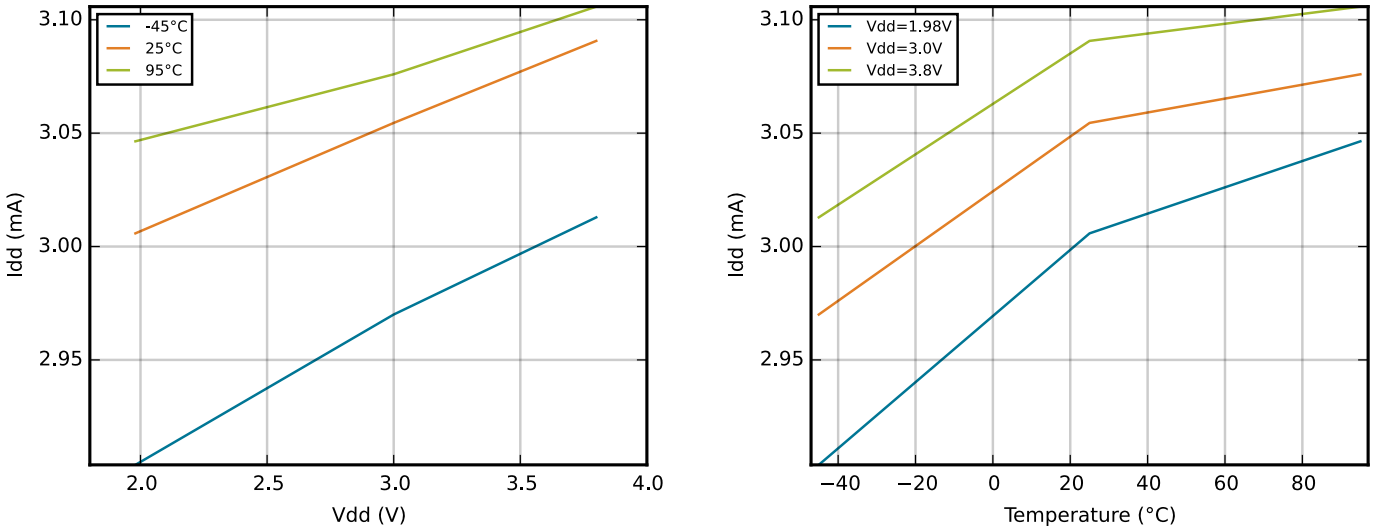


Figure 4.1. EM0 Current Consumption while Executing Prime Number Calculation Code from Flash with all Peripheral Clocks Disabled and HFRCO Running at 24 MHz

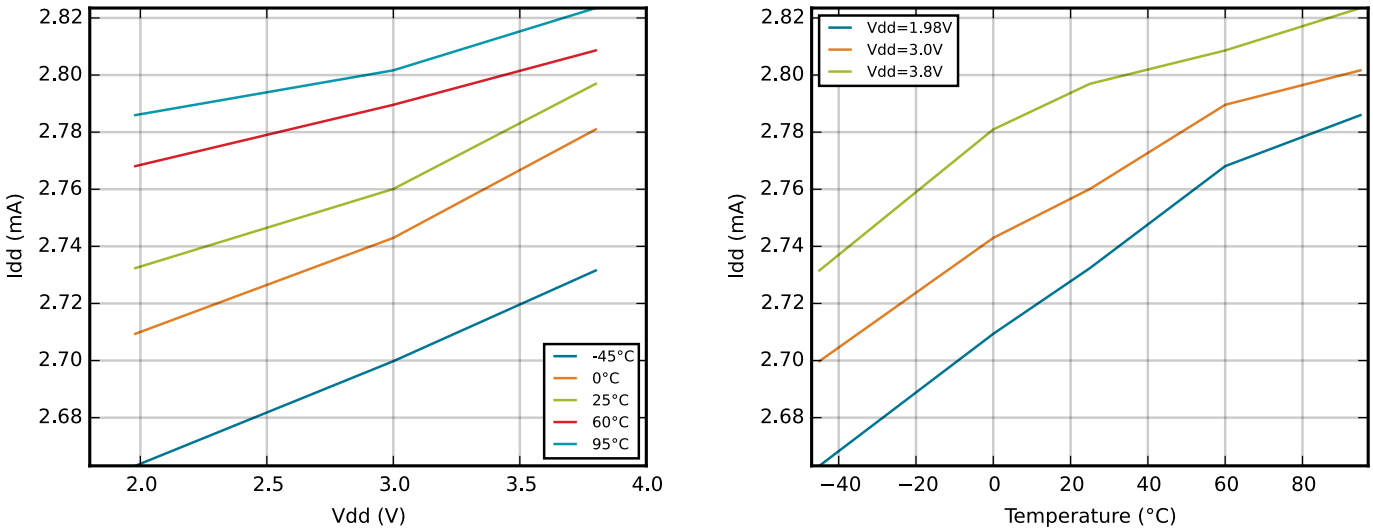


Figure 4.2. EM0 Current Consumption while Executing Prime Number Calculation Code from Flash with all Peripheral Clocks Disabled and HFRCO Running at 21 MHz

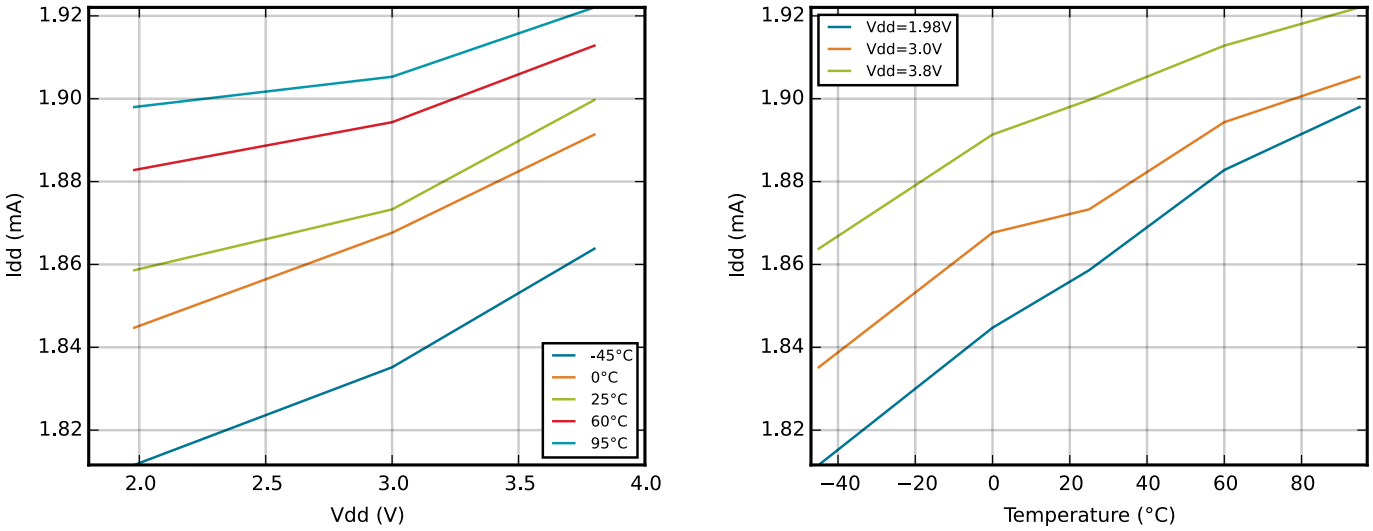


Figure 4.3. EM0 Current Consumption while Executing Prime Number Calculation Code from Flash with all Peripheral Clocks Disabled and HFRCO Running at 14 MHz

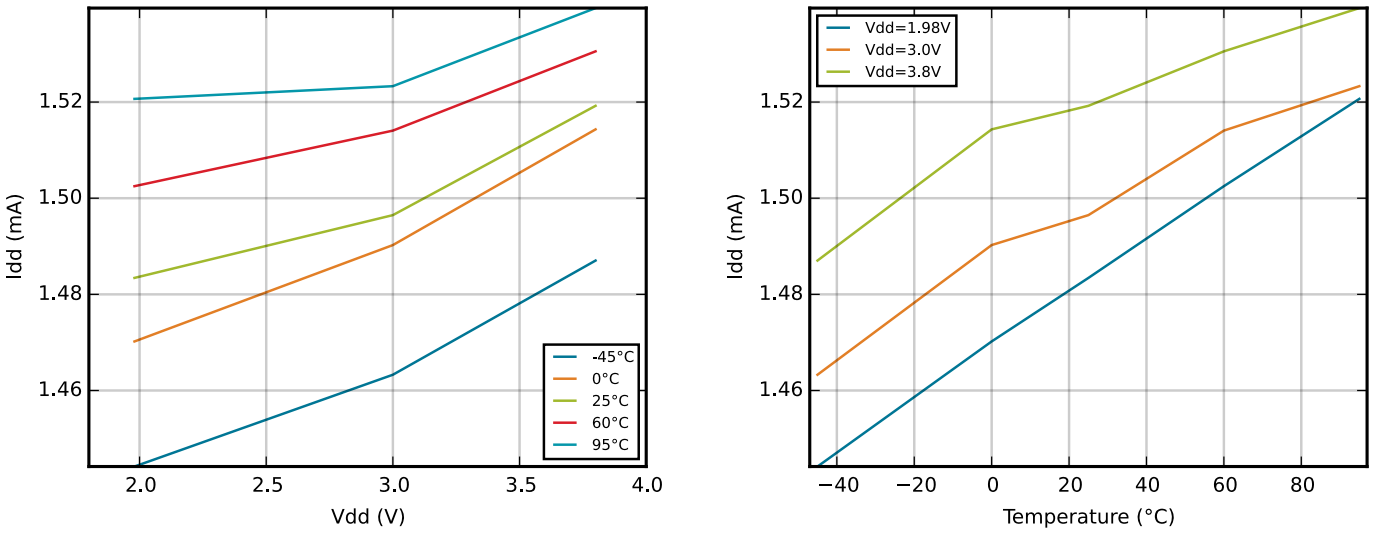


Figure 4.4. EM0 Current Consumption while Executing Prime Number Calculation Code from Flash with all Peripheral Clocks Disabled and HFRCO Running at 11 MHz

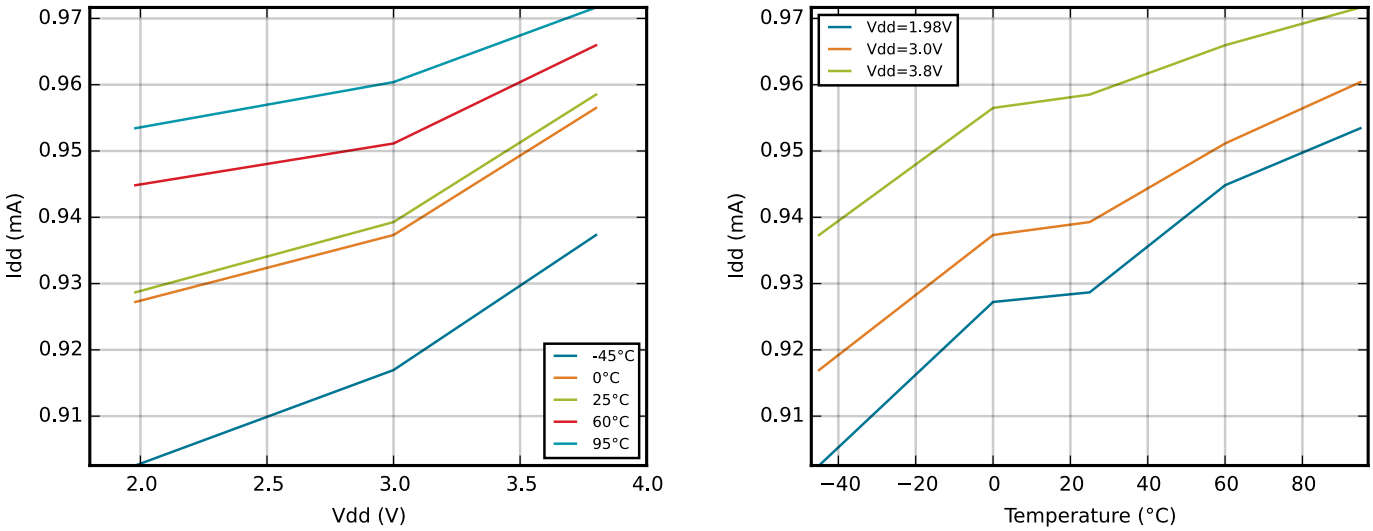


Figure 4.5. EM0 Current Consumption with all Peripheral Clocks Disabled and HFRCO Running at 6.6 MHz

4.5.2 EM1 Current Consumption

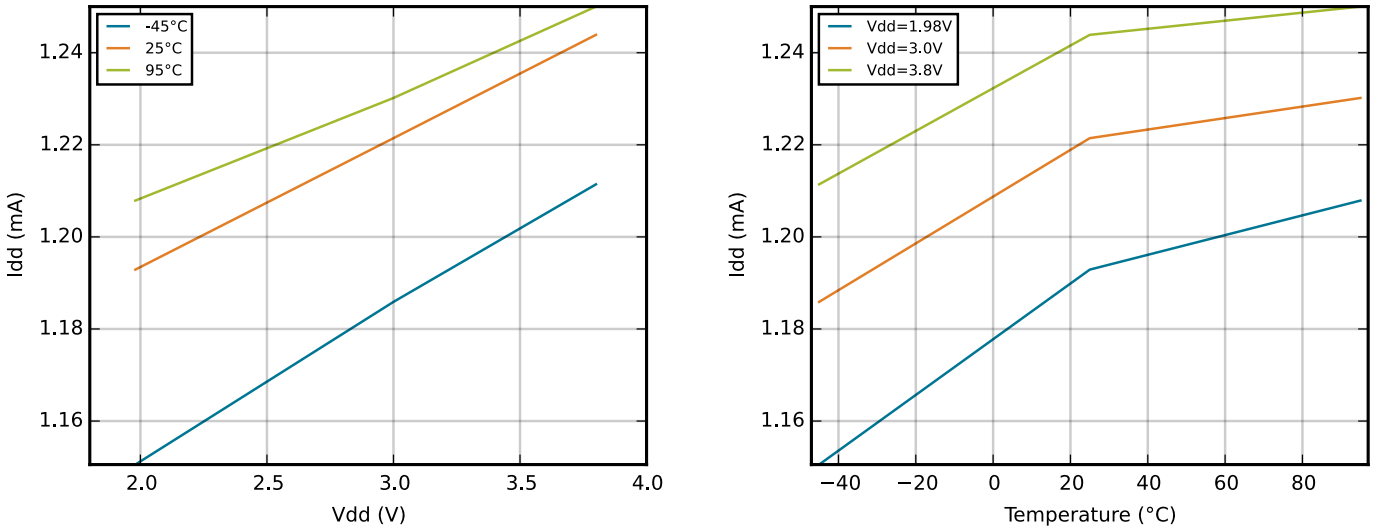


Figure 4.6. EM1 Current Consumption with all Peripheral Clocks Disabled and HFRCO Running at 24 MHz

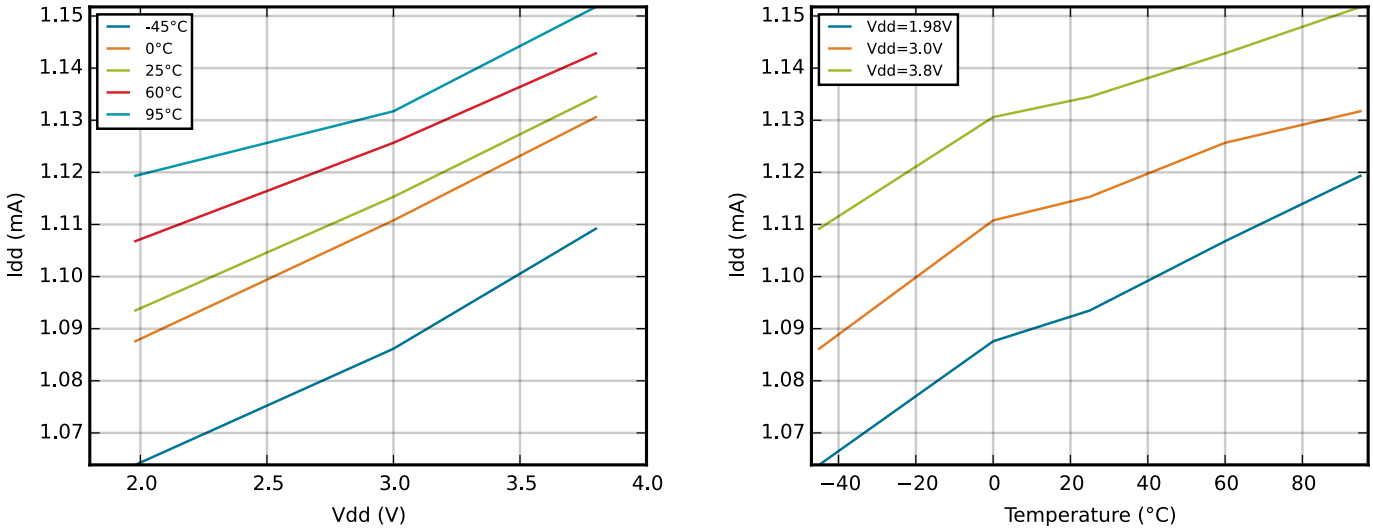


Figure 4.7. EM1 Current Consumption with all Peripheral Clocks Disabled and HFRCO Running at 21 MHz

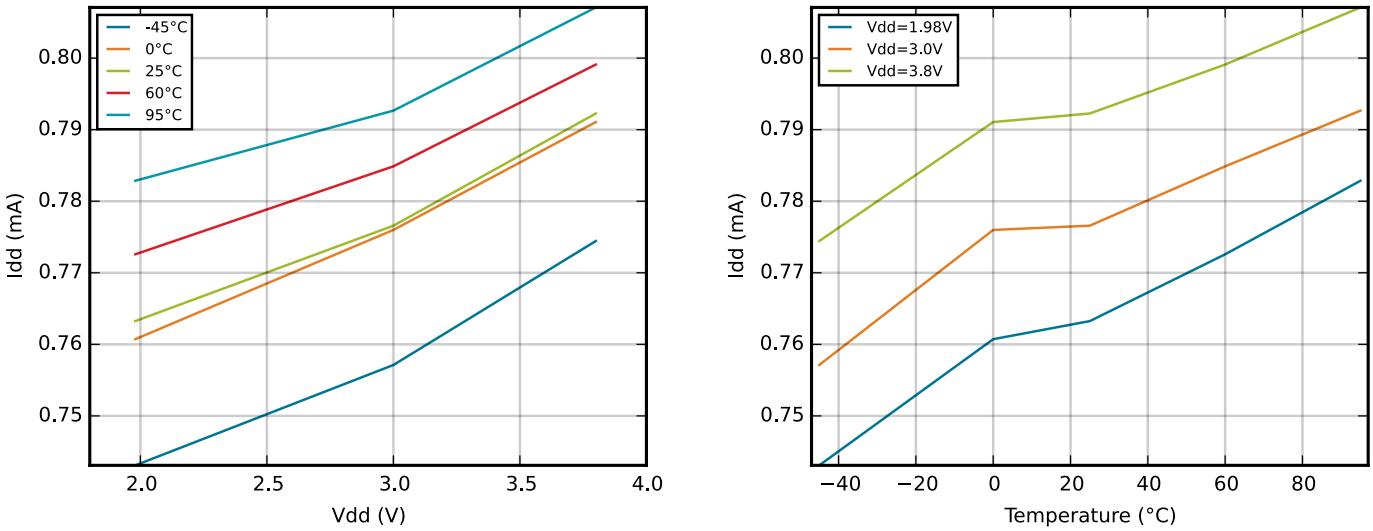


Figure 4.8. EM1 Current Consumption with all Peripheral Clocks Disabled and HFRCO Running at 14 MHz

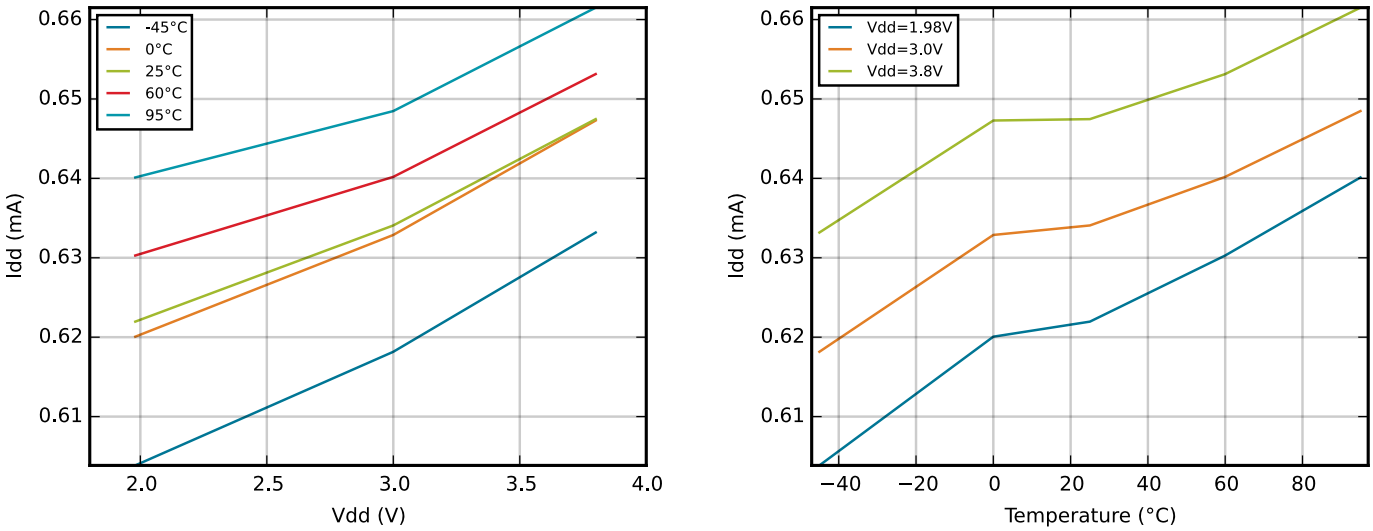


Figure 4.9. EM1 Current Consumption with all Peripheral Clocks Disabled and HFRCO Running at 11 MHz

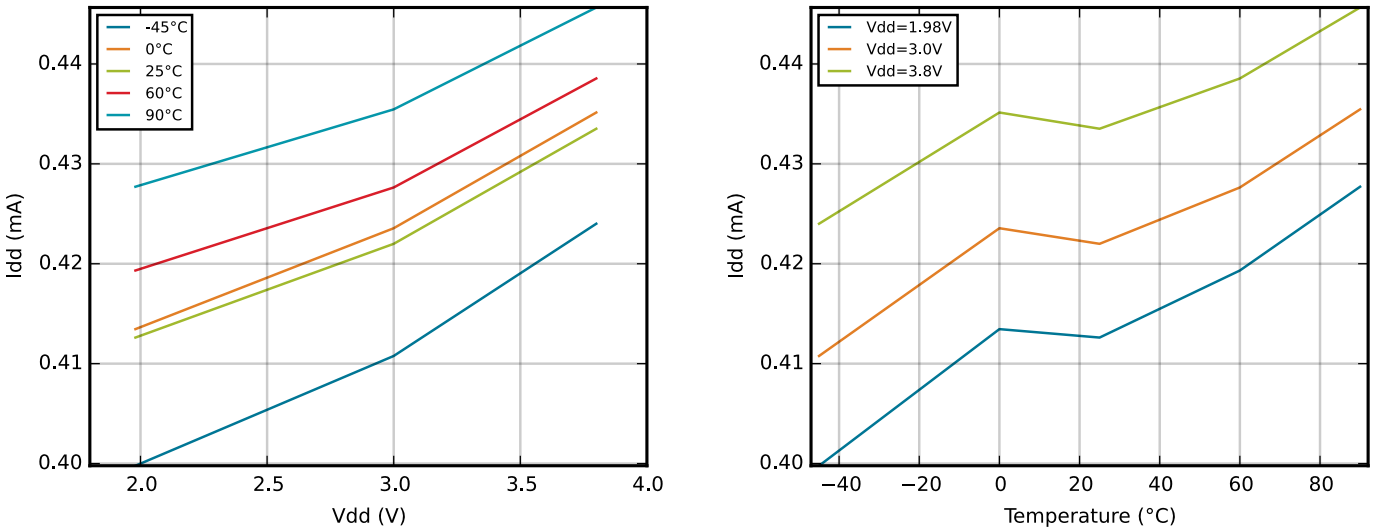


Figure 4.10. EM1 Current Consumption with all Peripheral Clocks Disabled and HFRCO Running at 6.6 MHz

4.5.3 EM2 Current Consumption

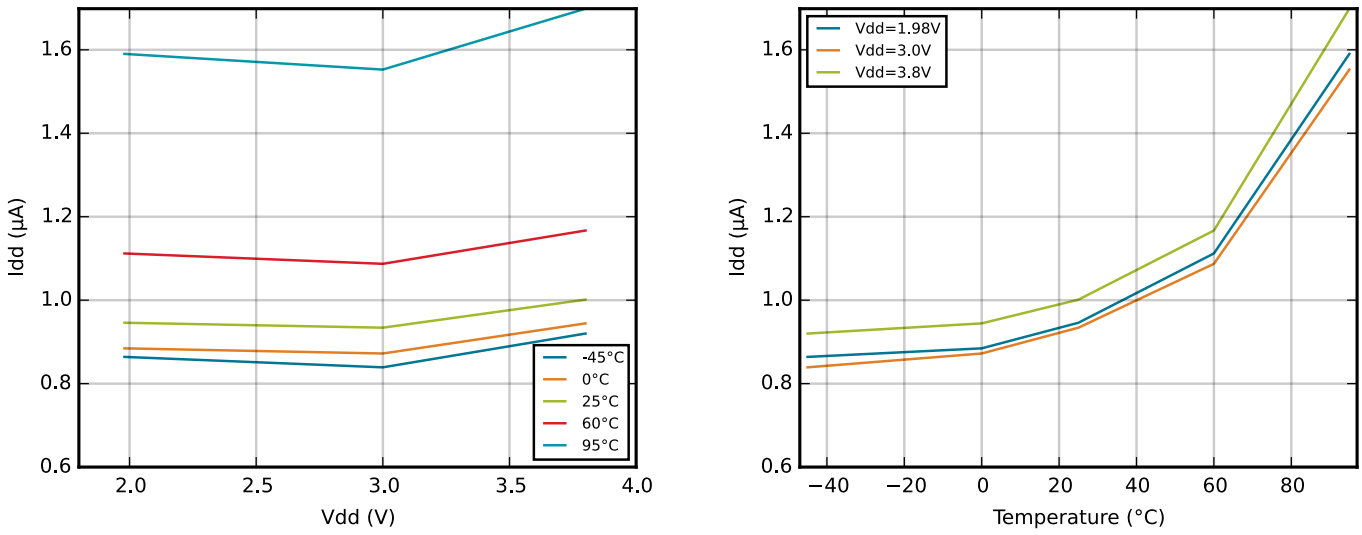


Figure 4.11. EM2 Current Consumption, RTC prescaled to 1 kHz, 32.768 kHz LFRCO

4.5.4 EM3 Current Consumption

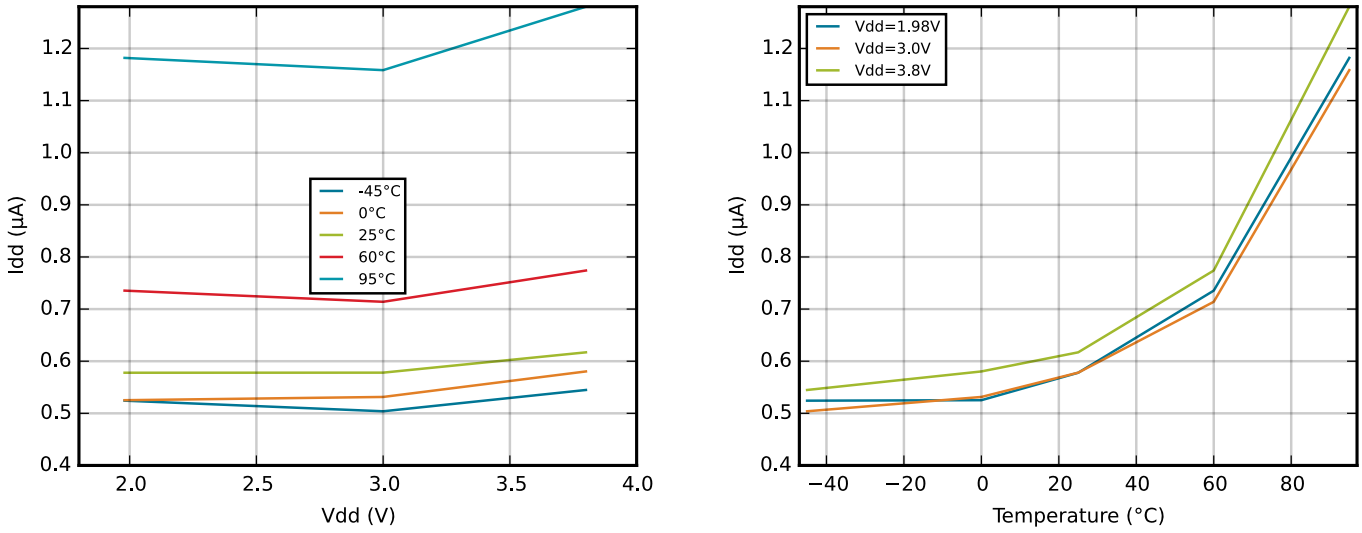


Figure 4.12. EM3 Current Consumption

4.5.5 EM4 Current Consumption

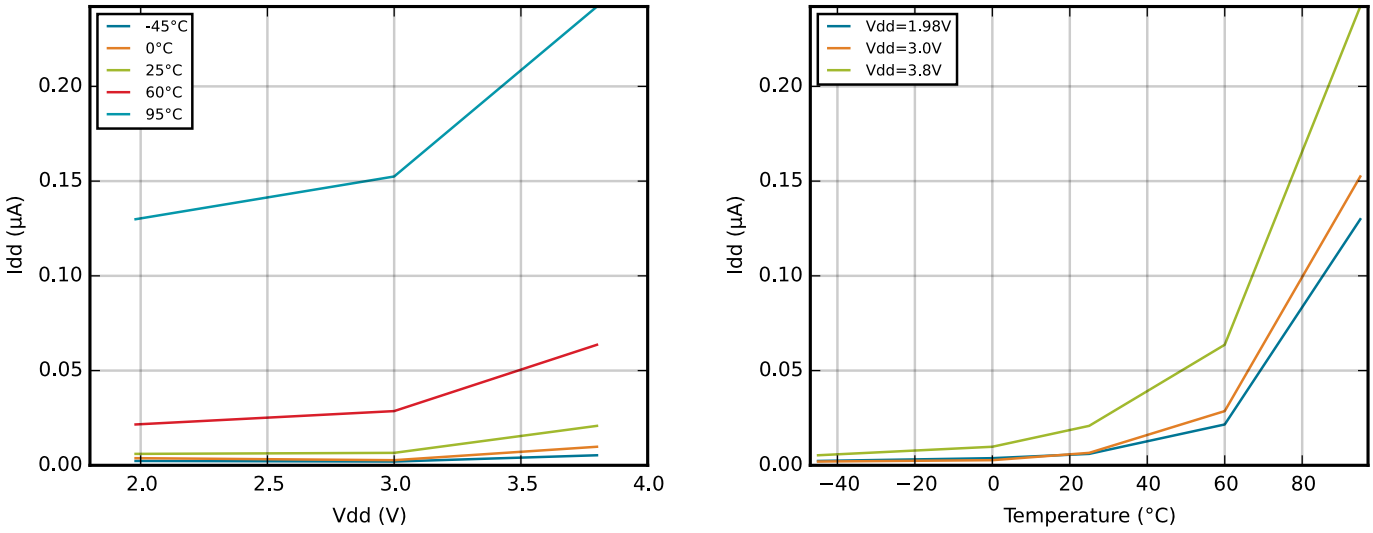


Figure 4.13. EM4 Current Consumption

4.6 Transition between Energy Modes

The transition times are measured from the trigger to the first clock edge in the CPU.

Table 4.5. Energy Modes Transitions

Parameter	Symbol	Min	Typ	Max	Unit
Transition time from EM1 to EM0	t_{EM10}	—	0	—	HFCORECLK cycles
Transition time from EM2 to EM0	t_{EM20}	—	2	—	µs
Transition time from EM3 to EM0	t_{EM30}	—	2	—	µs
Transition time from EM4 to EM0	t_{EM40}	—	163	—	µs

4.7 Power Management

The EFM32HG requires the AVDD_x, VDD_DREG and IOVDD_x pins to be connected together (with optional filter) at the PCB level. For practical schematic recommendations, please see the application note, *AN0002 EFM32 Hardware Design Considerations*.

Table 4.6. Power Management

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
BOD threshold on falling external supply voltage	$V_{BODextthr-}$	EM0	1.74	—	1.96	V
		EM2	1.71	1.86	1.98	V
BOD threshold on rising external supply voltage	$V_{BODextthr+}$		—	1.85	—	V
Delay from reset is released until program execution starts	t_{RESET}	Applies to Power-on Reset, Brown-out Reset and pin reset.	—	163	—	µs
Voltage regulator decoupling capacitor.	$C_{DECOUPLE}$	X5R capacitor recommended. Apply between DECOUPLE pin and GROUND	—	1	—	µF
USB voltage regulator out decoupling capacitor.	C_{USB_VREGO}	X5R capacitor recommended. Apply between USB_VREGO pin and GROUND	—	1	—	µF
USB voltage regulator in decoupling capacitor.	C_{USB_VREGI}	X5R capacitor recommended. Apply between USB_VREGI pin and GROUND	—	4.7	—	µF

4.8 Flash

Table 4.7. Flash

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Flash erase cycles before failure	EC_{FLASH}		20000	—	—	cycles
Flash word write cycles between erase	WWC_{FLASH}		—	—	2[1]	cycles
Flash data retention	RET_{FLASH}	T_{AMB}<150 °C	10000	—	—	h
		T_{AMB}<85 °C	10	—	—	years
		T_{AMB}<70 °C	20	—	—	years
Word (32-bit) programming time	t_{W_PROG}		20	—	—	µs
Page erase time[2]	t_{PERASE}		20.7	22.0	24.8	ms
Device erase time[3]	t_{DERASE}		41.8	45.0	49.2	ms
Erase current	I_{ERASE}		—	—	7[4]	mA
Write current	I_{WRITE}		—	—	7[4]	mA
Supply voltage during flash erase and write	V_{FLASH}		1.98	—	3.8	V

Note:

1. There is a maximum of two writes to the same word between each erase due to a physical limitation of the flash. No bit should be written to ‘0’ more than once between erases. To write a word twice between erases, any bit written to ‘0’ by the first write should be written to ‘1’ by the second write. This preserves the specified flash write/erase endurance and does not change the ‘0’ written by the first write.
2. From setting ERASEPAGE bit in MSC_WRITECMD to 1 to reading 1 in ERASE bit in MSC_IF. Internal setup and hold times for flash control signals are included.
3. From setting DEVICEERASE bit in AAP_CMD to 1 to reading 0 in ERASEBUSY bit in AAP_STATUS. Internal setup and hold times for flash control signals are included.
4. Measured at 25 °C.

4.9 General Purpose Input Output

Table 4.8. GPIO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input low voltage	V_{IOIL}		—	—	0.30×V_{DD}	V
Input high voltage	V_{IOIH}		0.70×V_{DD}	—	—	V
Output high voltage (Production test condition = 3.0V, DRIVEMODE = STANDARD)	V_{IOOH}	Sourcing 0.1 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = LOWEST	—	0.80×V_{DD}	—	V
		Sourcing 0.1 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = LOWEST	—	0.90×V_{DD}	—	V
		Sourcing 1 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = LOW	—	0.85×V_{DD}	—	V
		Sourcing 1 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = LOW	—	0.90×V_{DD}	—	V
		Sourcing 6 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = STANDARD	0.75×V_{DD}	—	—	V
		Sourcing 6 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = STANDARD	0.85×V_{DD}	—	—	V
		Sourcing 20 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = HIGH	0.60×V_{DD}	—	—	V
		Sourcing 20 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = HIGH	0.80×V_{DD}	—	—	V
Output low voltage (Production test condition = 3.0V, DRIVEMODE = STANDARD)	V_{IOOL}	Sinking 0.1 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = LOWEST	—	0.20×V_{DD}	—	V
		Sinking 0.1 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = LOWEST	—	0.10×V_{DD}	—	V
		Sinking 1 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = LOW	—	0.10×V_{DD}	—	V
		Sinking 1 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = LOW	—	0.05×V_{DD}	—	V
		Sinking 6 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = STANDARD	—	—	0.30×V_{DD}	V
		Sinking 6 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = STANDARD	—	—	0.20×V_{DD}	V
		Sinking 20 mA, V_{DD}=1.98 V, GPIO_Px_CTRL DRIVEMODE = HIGH	—	—	0.35×V_{DD}	V
		Sinking 20 mA, V_{DD}=3.0 V, GPIO_Px_CTRL DRIVEMODE = HIGH	—	—	0.25×V_{DD}	V

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input leakage current	I_{IOLEAK}	High Impedance IO connected to GROUND or VDD, EFM32HGxxxFxx only	—	±0.1	±40	nA
		High Impedance IO connected to GROUND or VDD, EFM32HGxxxFxxN only	—	±0.1	±70	nA
I/O pin pull-up resistor	R_{PU}		—	40	—	kΩ
I/O pin pull-down resistor	R_{PD}		—	40	—	kΩ
Internal ESD series resistor	R_{IOESD}		—	200	—	Ω
Pulse width of pulses to be removed by the glitch suppression filter	$t_{IO-GLITCH}$		10	—	50	ns
Output fall time	t_{IOOF}	GPIO_Px_CTRL DRIVEMODE = LOWEST and load capacitance C_L=12.5-25pF.	20+0.1×C_L	—	250	ns
		GPIO_Px_CTRL DRIVEMODE = LOW and load capacitance C_L=350-600pF	20+0.1×C_L	—	250	ns
I/O pin hysteresis (V_{IOTHR+} - V_{IOTHR-})	V_{IOHYST}	V_{DD} = 1.98 - 3.8 V	0.10×V_{DD}	—	—	V

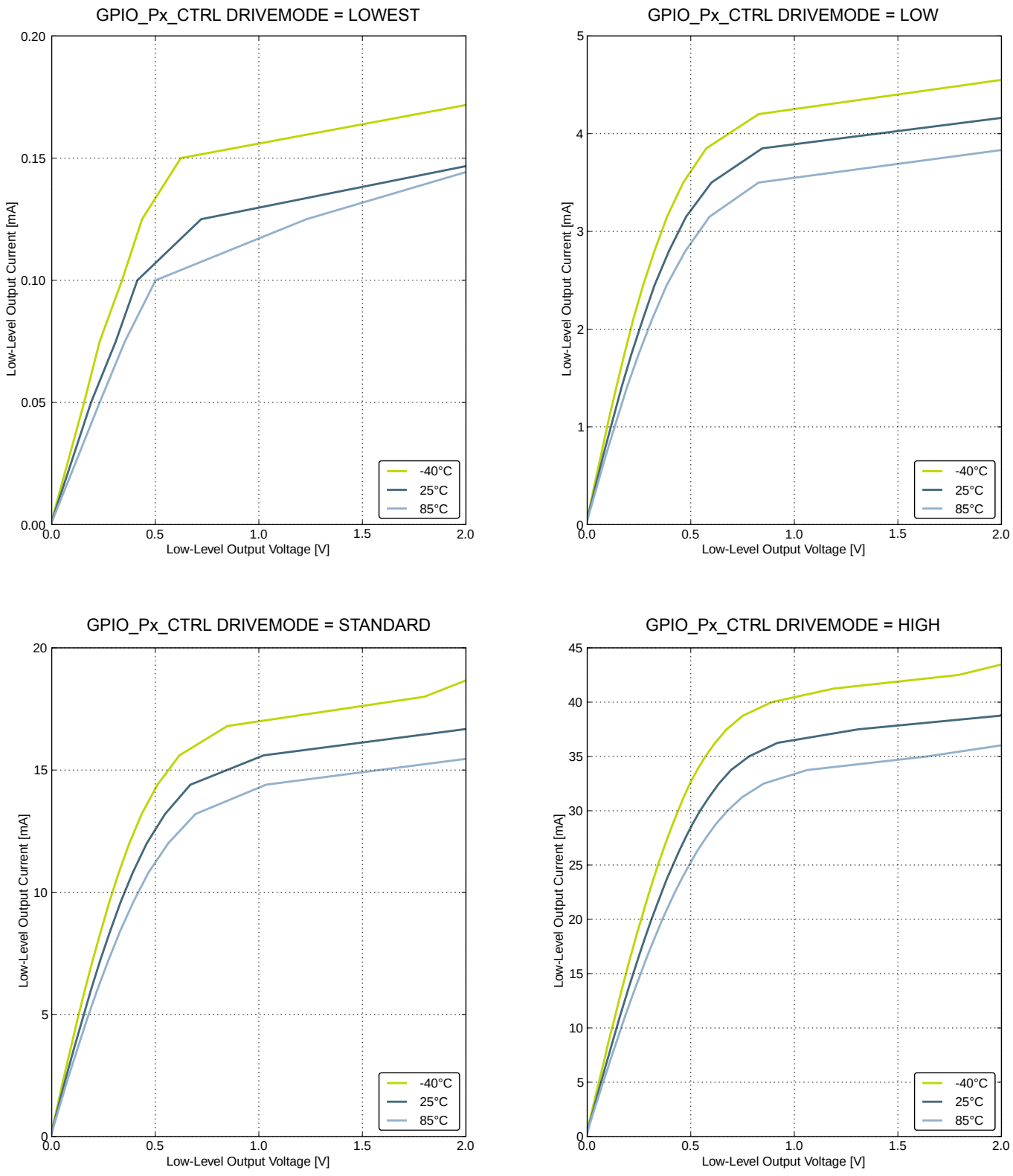


Figure 4.14. Typical Low-Level Output Current, 2V Supply Voltage

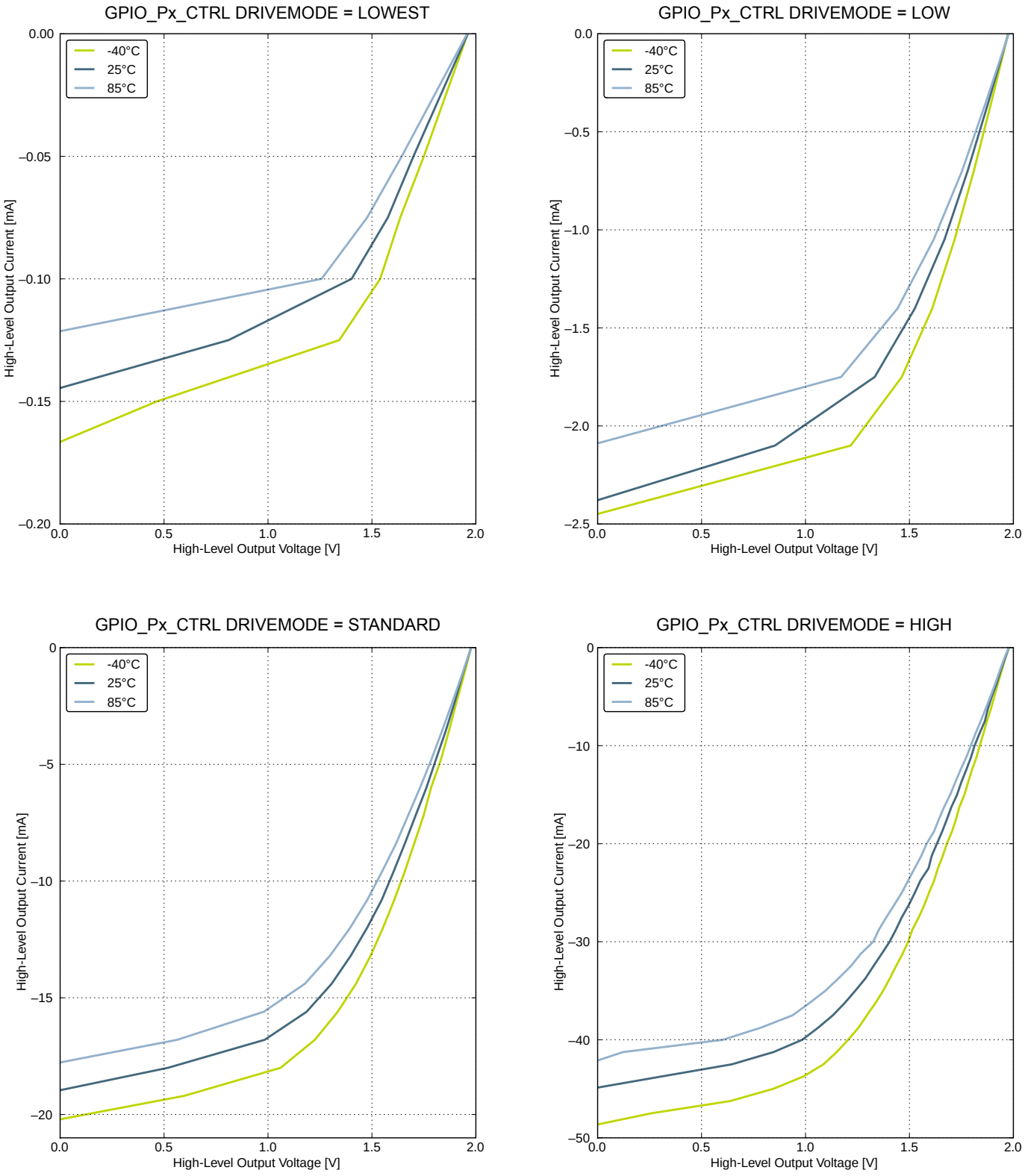


Figure 4.15. Typical High-Level Output Current, 2 V Supply Voltage

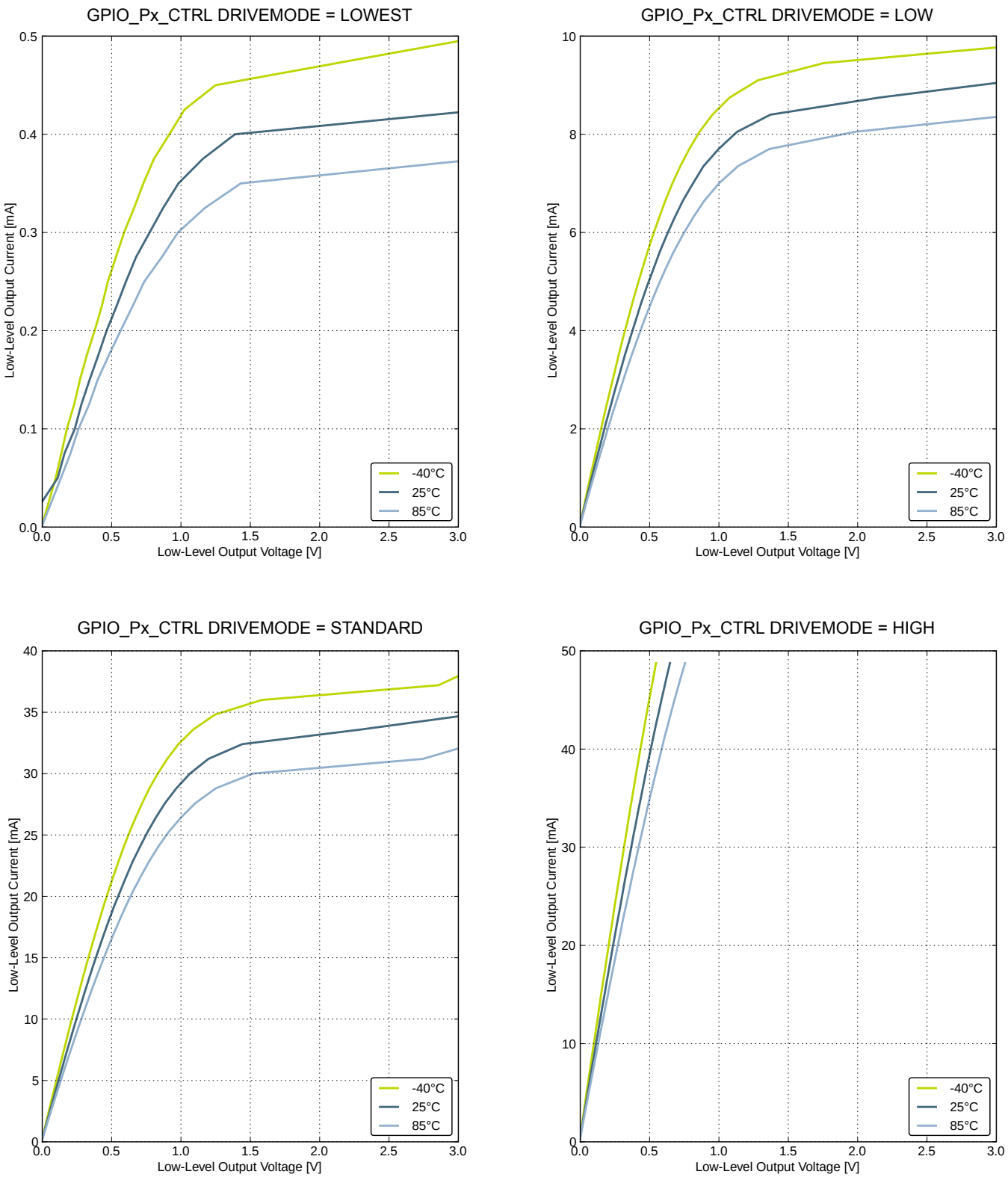


Figure 4.16. Typical Low-Level Output Current, 3 V Supply Voltage

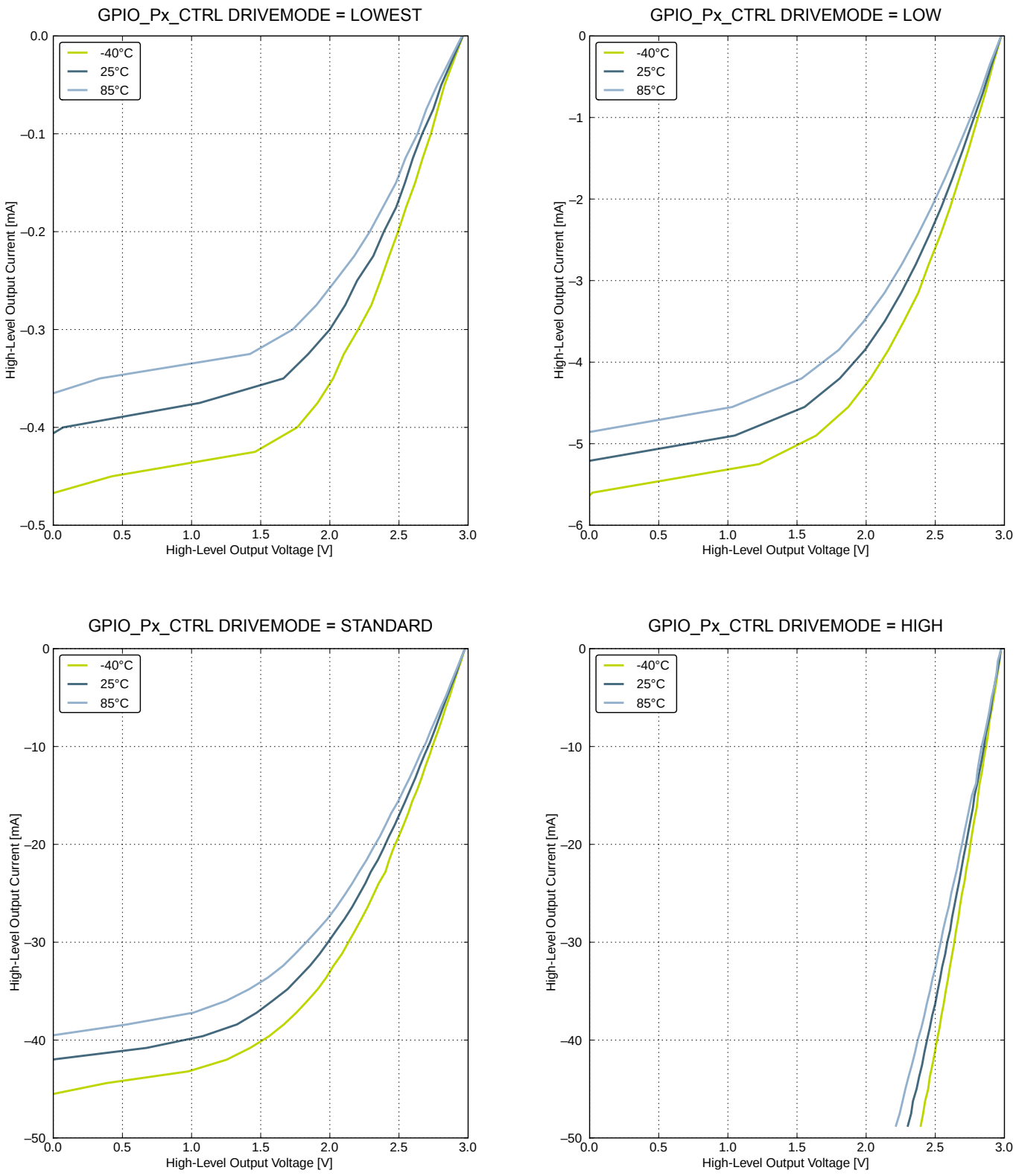


Figure 4.17. Typical High-Level Output Current, 3 V Supply Voltage

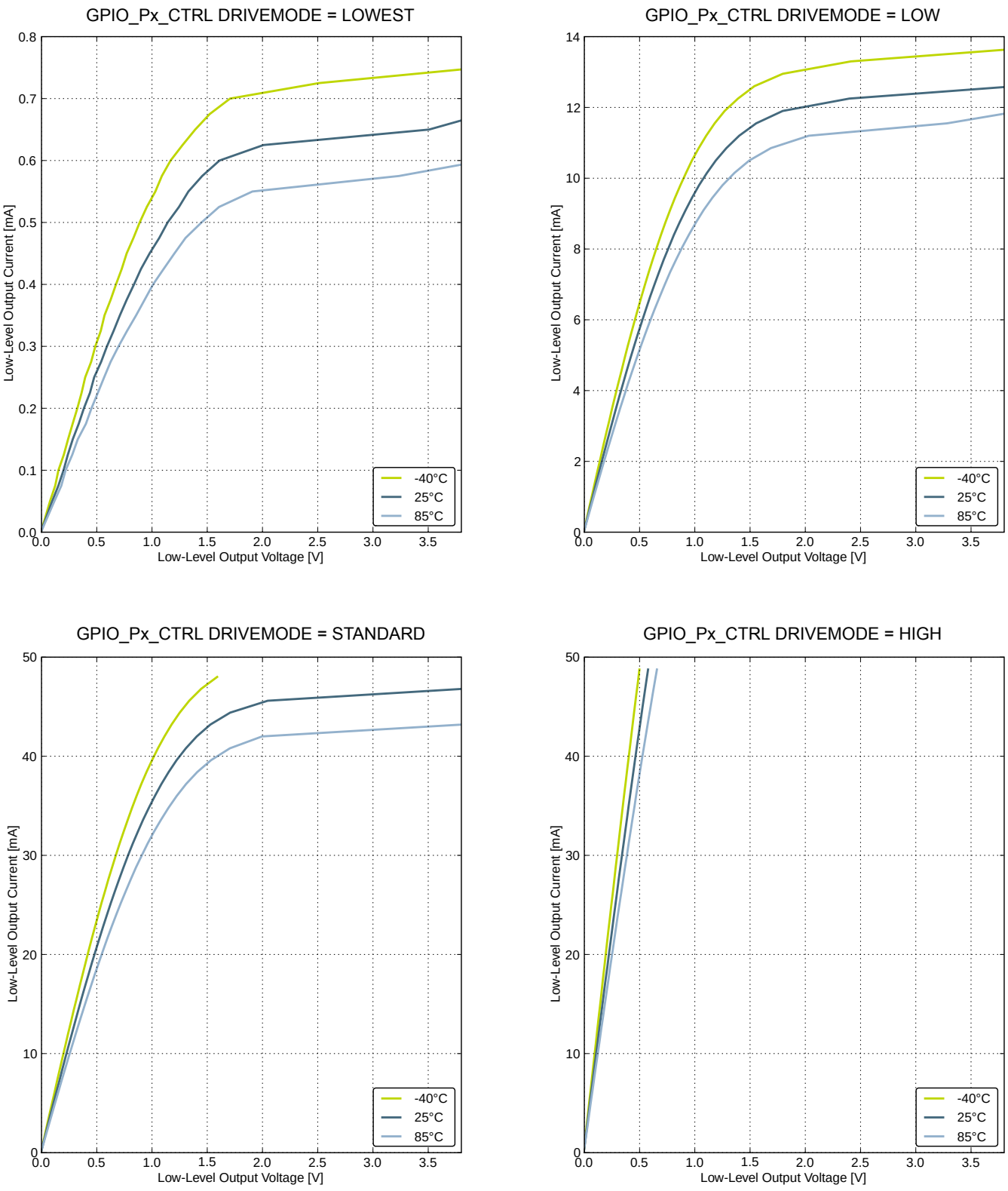


Figure 4.18. Typical Low-Level Output Current, 3.8 V Supply Voltage

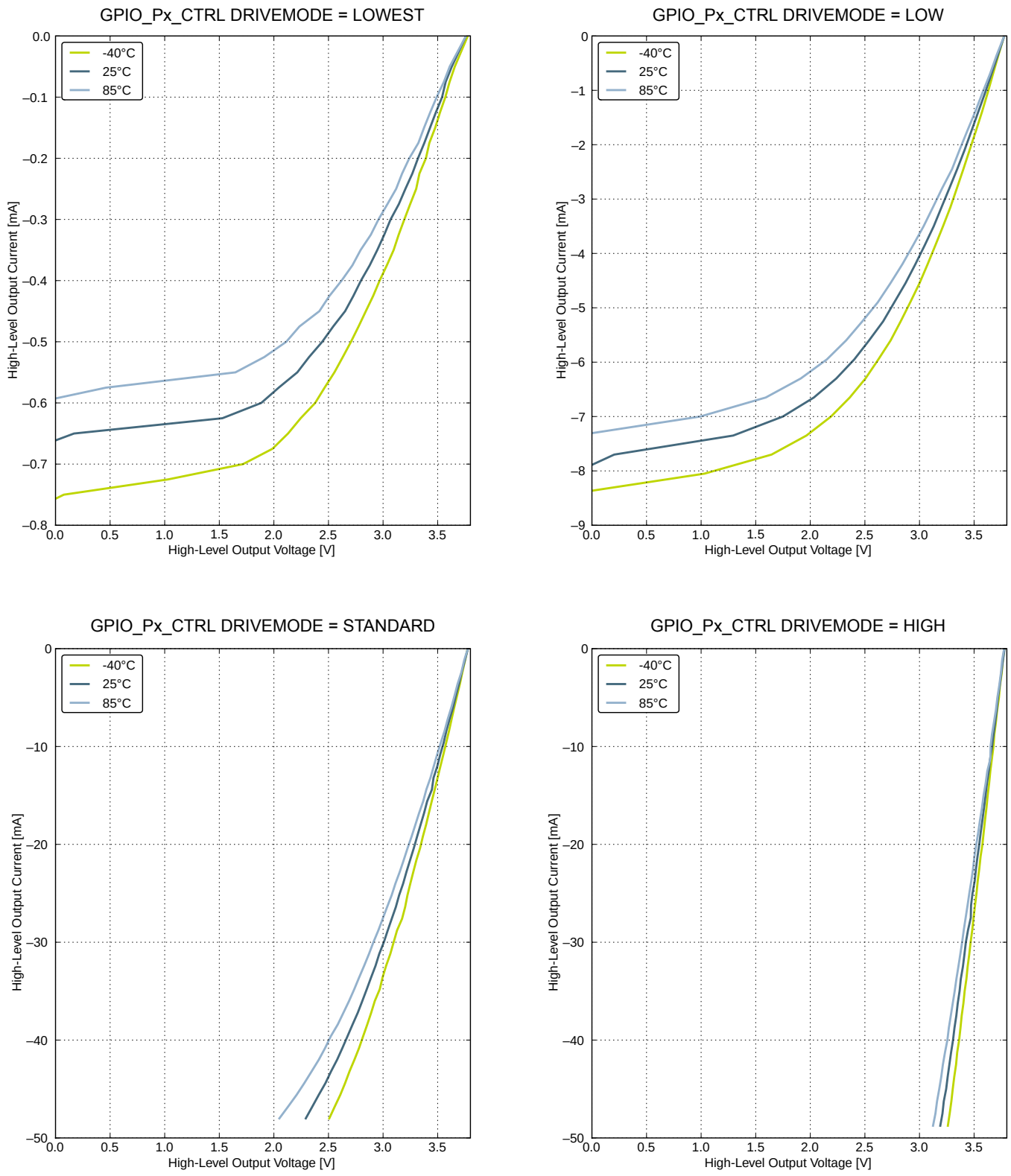


Figure 4.19. Typical High-Level Output Current, 3.8 V Supply Voltage

4.10 Oscillators

4.10.1 LFXO

Table 4.9. LFXO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supported nominal crystal frequency	f_{LFXO}		—	32.768	—	kHz
Supported crystal equivalent series resistance (ESR)	ESR_{LFXO}		—	30	120	kΩ
Supported crystal external load range	C_{LFXOL}		5	—	25	pF
Current consumption for core and buffer after startup.	I_{LFXO}	ESR=30 kΩ, C_L=10 pF, LFXOBOOST in CMU_CTRL is 1	—	190	—	nA
Start- up time.	t_{LFXO}	ESR=30 kΩ, CL=10 pF, 40% - 60% duty cycle has been reached, LFXOBOOST in CMU_CTRL is 1	—	1100	—	ms

For safe startup of a given crystal, the Configurator tool in Simplicity Studio contains a tool to help users configure both load capacitance and software settings for using the LFXO. For details regarding the crystal configuration, the reader is referred to application note *AN0016 EFM32 Oscillator Design Consideration*.

4.10.2 HFXO

Table 4.10. HFXO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supported nominal crystal Frequency	f_{HFXO}		4	—	25	MHz
Supported crystal equivalent series resistance (ESR)	ESR_{HFXO}	Crystal frequency 25 MHz	—	30	100	Ω
		Crystal frequency 4 MHz	—	400	1500	Ω
The transconductance of the HFXO input transistor at crystal startup	g_{mHFXO}	HFXOBOOST in CMU_CTRL equals 0b11	20	—	—	mS
Supported crystal external load range	C_{HFXOL}		5	—	25	pF
Current consumption for HFXO after startup	I_{HFXO}	4 MHz: ESR=400 Ω, C_L=20 pF, HFXOBOOST in CMU_CTRL equals 0b11	—	85	—	µA
		25 MHz: ESR=30 Ω, C_L=10 pF, HFXOBOOST in CMU_CTRL equals 0b11	—	165	—	µA
Startup time	t_{HFXO}	25 MHz: ESR=30 Ω, C_L=10 pF, HFXOBOOST in CMU_CTRL equals 0b11	—	785	—	µs

4.10.3 LFRCO

Table 4.11. LFRCO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency, V_{DD}= 3.0 V, T_{AMB}=25°C	f_{LFRCO}		31.3	32.768	34.3	kHz
Startup time not including software calibration	t_{LFRCO}		—	150	—	µs
Current consumption	I_{LFRCO}		—	361	492	nA
Frequency step for LSB change in TUNING value	$TUNESTEP_{LFRCO}$		—	202	—	Hz

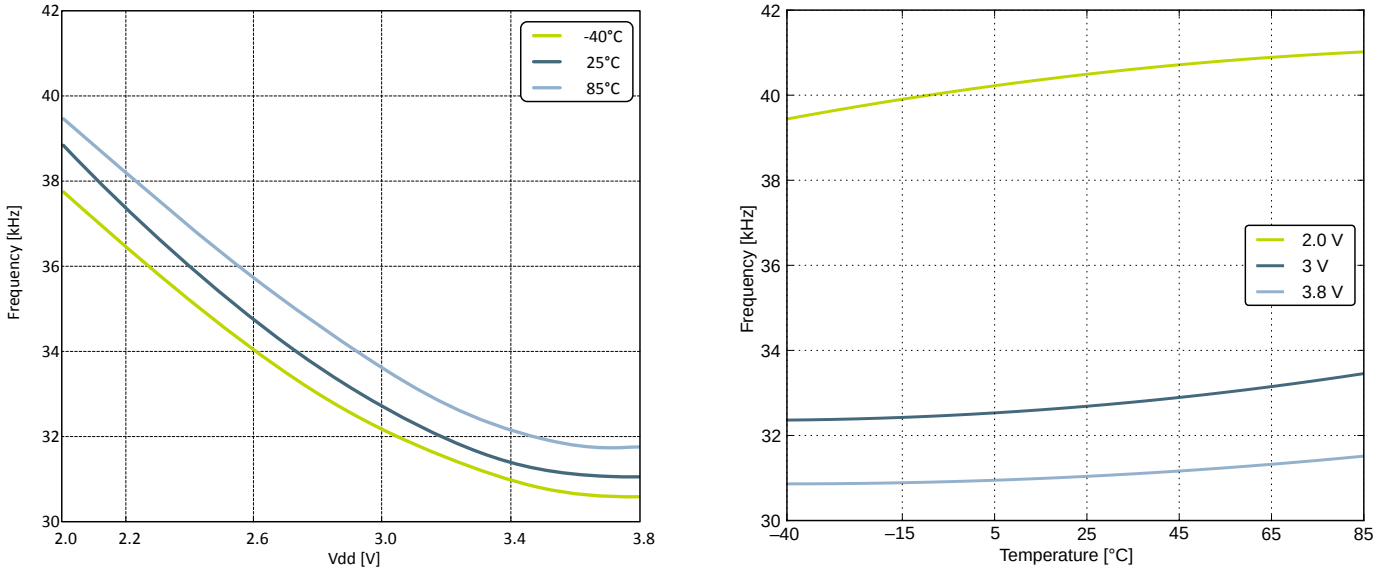


Figure 4.20. Calibrated LFRCO Frequency vs Temperature and Supply Voltage

4.10.4 HFRCO

Table 4.12. HFRCO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency, V_{DD}= 3.0 V, T_{AMB}=25°C	f_{HFRCO}	21 MHz frequency band	20.37	21.0	21.63	MHz
		14 MHz frequency band	13.58	14.0	14.42	MHz
		11 MHz frequency band	10.67	11.0	11.33	MHz
		7 MHz frequency band	6.40	6.60	6.80	MHz
		1 MHz frequency band	1.15	1.20	1.25	MHz
Settling time after start-up	$t_{HFRCO_settling}$	f_{HFRCO} = 14 MHz	—	0.6	—	Cycles
Current consumption	I_{HFRCO}	f_{HFRCO} = 21 MHz	—	143	175	µA
		f_{HFRCO} = 14 MHz	—	113	140	µA
		f_{HFRCO} = 11 MHz	—	101	125	µA
		f_{HFRCO} = 6.6 MHz	—	84	105	µA
		f_{HFRCO} = 1.2 MHz	—	27	40	µA
Frequency step for LSB change in TUNING value	$TUNESTEP_{HFRCO}$	21 MHz frequency band	—	52.8[1]	—	kHz
		14 MHz frequency band	—	36.9[1]	—	kHz
		11 MHz frequency band	—	30.1[1]	—	kHz
		7 MHz frequency band	—	18.0[1]	—	kHz
		1 MHz frequency band	—	3.4	—	kHz

Note:

1. The TUNING field in the CMU_HFRCOCTRL register may be used to adjust the HFRCO frequency. There is enough adjustment range to ensure that the frequency bands above 7 MHz will always have some overlap across supply voltage and temperature. By using a stable frequency reference such as the LFXO or HFXO, a firmware calibration routine can vary the TUNING bits and the frequency band to maintain the HFRCO frequency at any arbitrary value between 7 MHz and 21 MHz across operating conditions.

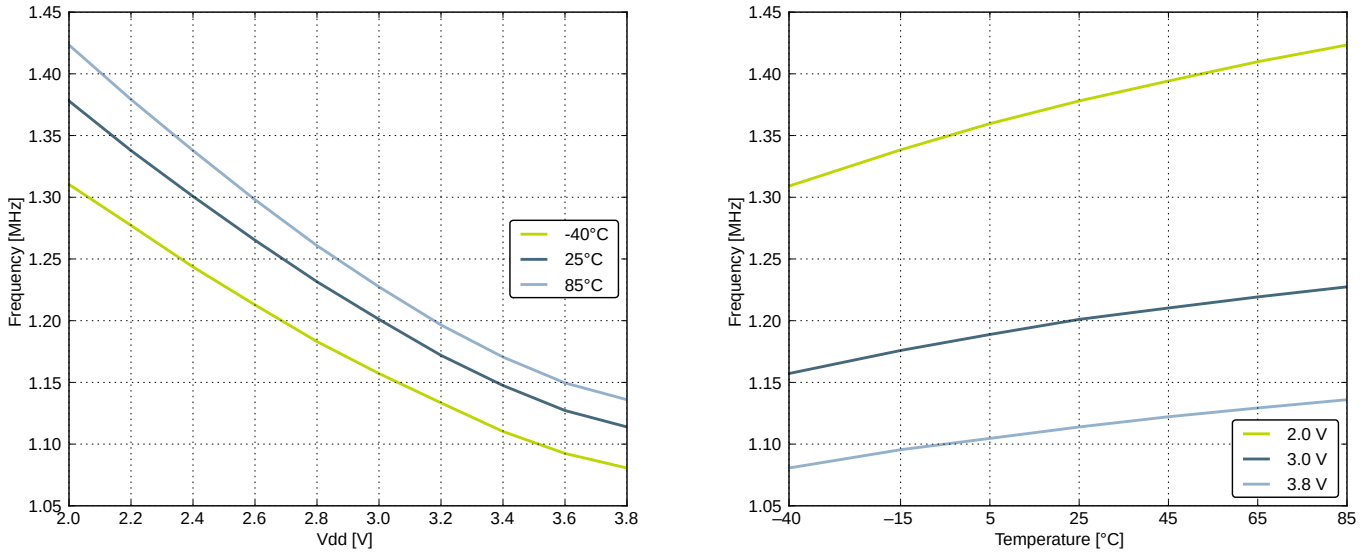


Figure 4.21. Calibrated HFRCO 1 MHz Band Frequency vs Supply Voltage and Temperature

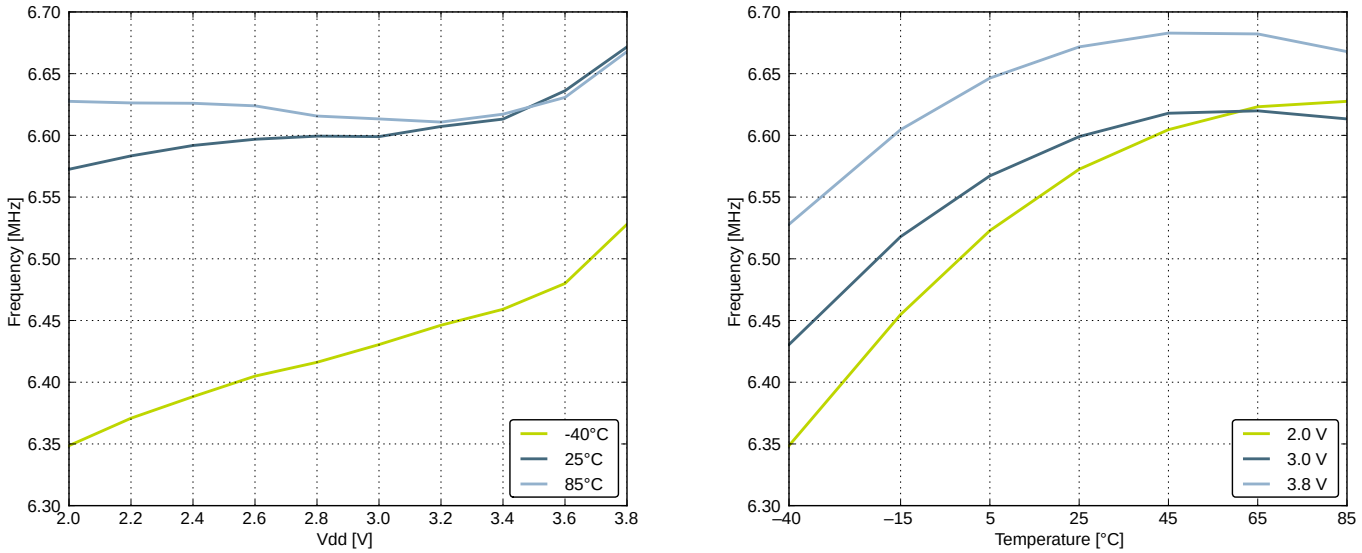


Figure 4.22. Calibrated HFRCO 7 MHz Band Frequency vs Supply Voltage and Temperature

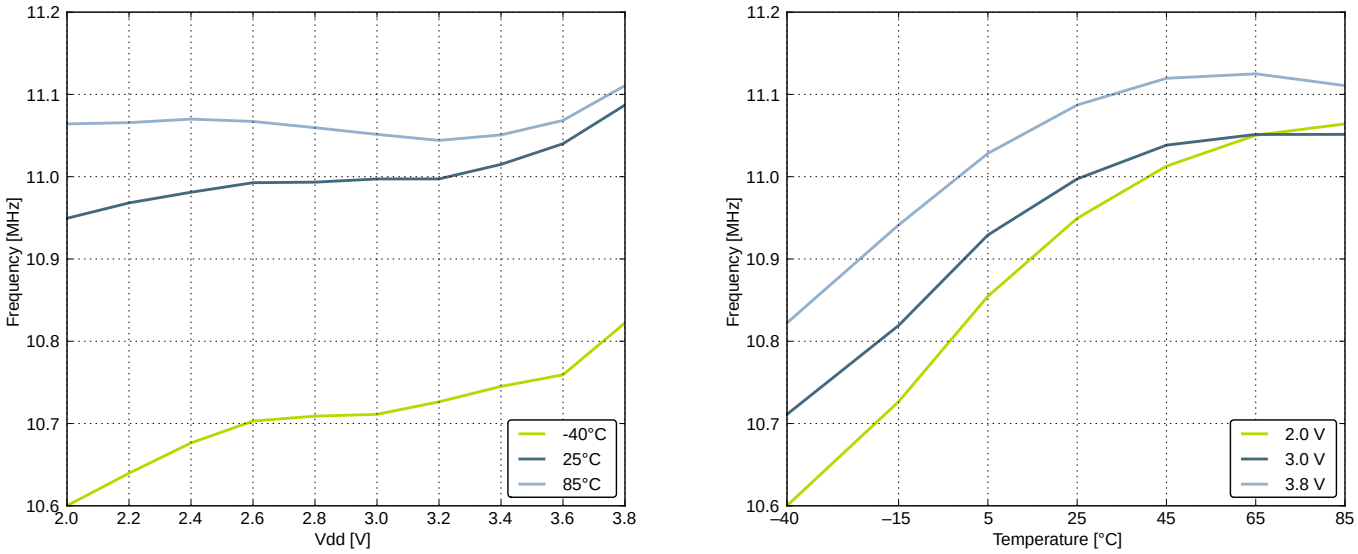


Figure 4.23. Calibrated HFRCO 11 MHz Band Frequency vs Supply Voltage and Temperature

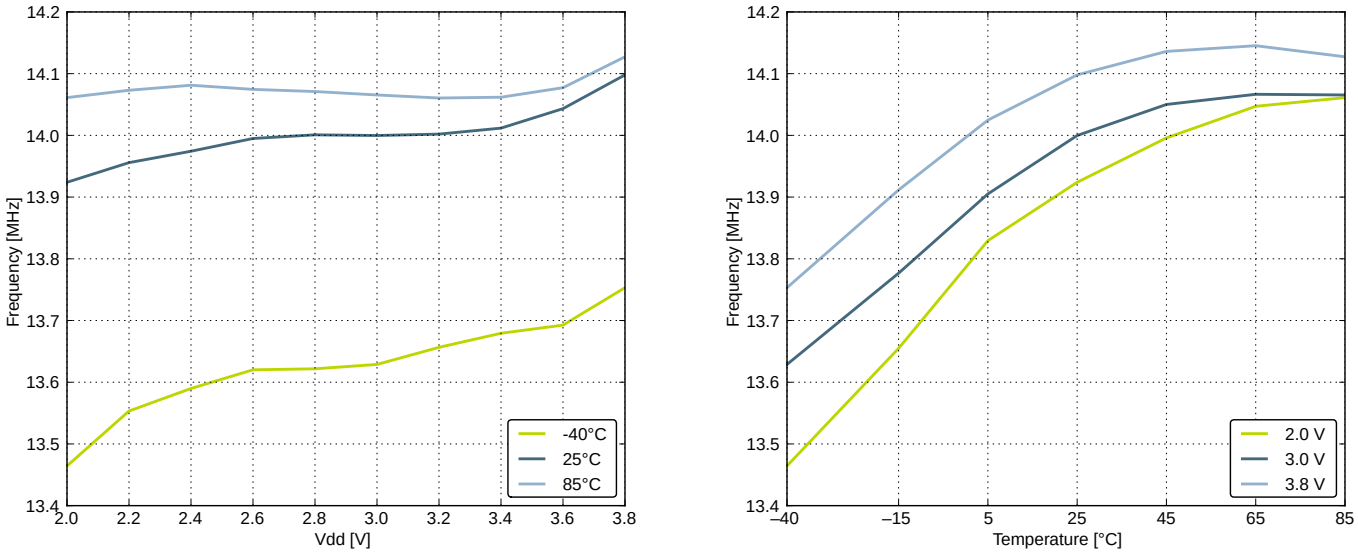


Figure 4.24. Calibrated HFRCO 14 MHz Band Frequency vs Supply Voltage and Temperature

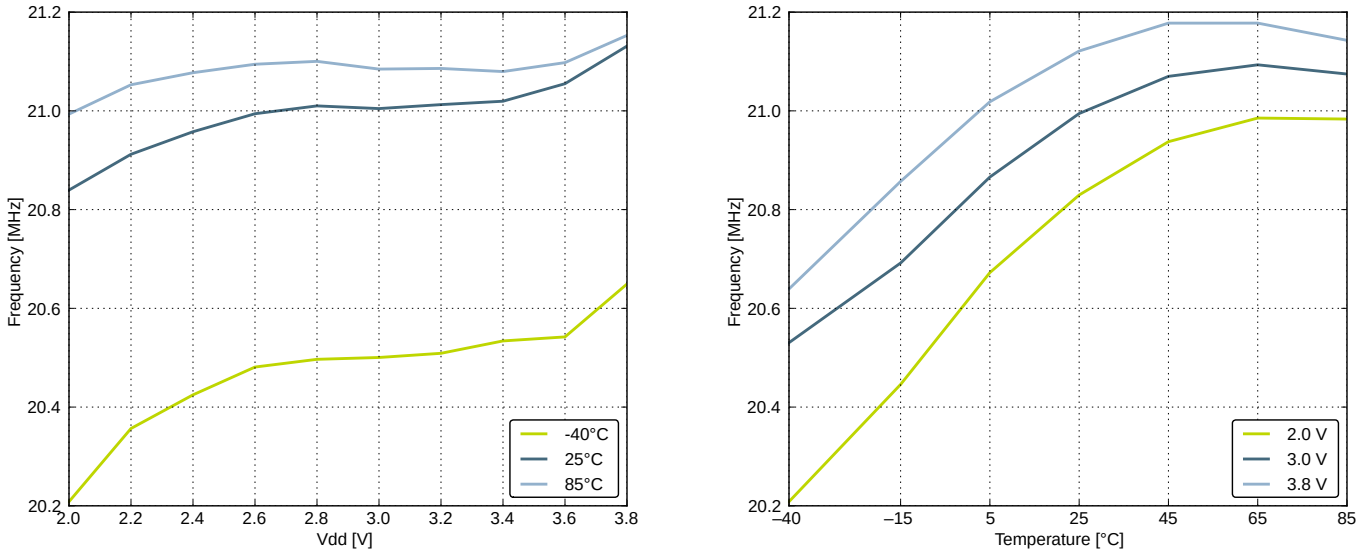


Figure 4.25. Calibrated HFRCO 21 MHz Band Frequency vs Supply Voltage and Temperature

4.10.5 AUXHFRCO

Table 4.13. AUXHFRCO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency, V_{DD}= 3.0 V, T_{AMB}=25°C	$f_{AUXHFRCO}$	21 MHz frequency band	20.37	21.0	21.63	MHz
		14 MHz frequency band	13.58	14.0	14.42	MHz
		11 MHz frequency band	10.67	11.0	11.33	MHz
		7 MHz frequency band	6.40	6.60	6.80	MHz
		1 MHz frequency band	1.15	1.20	1.25	MHz
Settling time after start-up	$t_{AUXHFRCO_settling}$	$f_{AUXHFRCO}$ = 14 MHz	—	0.6	—	Cycles
Frequency step for LSB change in TUNING value	$TUNESTEP_{AUXHFRCO}$	21 MHz frequency band	—	52.8	—	kHz
		14 MHz frequency band	—	36.9	—	kHz
		11 MHz frequency band	—	30.1	—	kHz
		7 MHz frequency band	—	18.0	—	kHz
		1 MHz frequency band	—	3.4	—	kHz

4.10.6 USHFRCO

Table 4.14. USHFRCO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency	$f_{USHFRCO}$	No Clock Recovery, Full Temperature and Supply Range, 48 MHz band	47.10	48.00	48.90	MHz
		No Clock Recovery, Full Temperature and Supply Range, 24 MHz band	23.73	24.00	24.32	MHz
		No Clock Recovery, 25°C, 3.3V, 48 MHz band	47.50	48.00	48.50	MHz
		No Clock Recovery, 25°C, 3.3V, 24 MHz band	23.86	24.00	24.16	MHz
		USB Active with Clock Recovery, Full Temperature and Supply Range	47.88	48.00	48.12	MHz
Temperature coefficient	$T_{CUSHFRCO}$	3.3 V	—	0.0175	—	%/°C
Supply voltage coefficient	$VC_{USHFRCO}$	25°C	—	0.0045	—	%/V
Current consumption	$I_{USHFRCO}$	$f_{USHFRCO}$ = 48 MHz	1.21	1.36	1.48	mA
		$f_{USHFRCO}$ = 24 MHz	0.81	0.92	1.02	mA

4.10.7 ULFRCO

Table 4.15. ULFRCO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency	f_{ULFRCO}	25°C, 3V	0.70	—	1.75	kHz
Temperature coefficient	TC_{ULFRCO}		—	0.05	—	%/°C
Supply voltage coefficient	VC_{ULFRCO}		—	-18.2	—	%/V

4.11 Analog Digital Converter (ADC)

Table 4.16. ADC

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V_{ADCIN}	Single-ended	0	—	V_{REF}	V
		Differential	$-V_{REF}/2$	—	$V_{REF}/2$	V
Input range of external reference voltage, single-ended and differential	$V_{ADCREFIN}$		1.25	—	V_{DD}	V
Input range of external negative reference voltage on channel 7	$V_{ADCREFIN_CH7}$	See $V_{ADCREFIN}$	0	—	V_{DD} - 1.1	V
Input range of external positive reference voltage on channel 6	$V_{ADCREFIN_CH6}$	See $V_{ADCREFIN}$	0.625	—	V_{DD}	V
Common mode input range	$V_{ADCCMIN}$		0	—	V_{DD}	V
Input current	I_{ADCIN}	2 pF sampling capacitors	—	<100	—	nA
Analog input common mode rejection ratio	$CMRR_{ADC}$		—	65	—	dB
Average active current	I_{ADC}	1 Msamples/s, 12 bit, external reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	735[1]	—	µA
		1 Msamples/s, 12 bit, internal 1.25V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	760[1]	—	µA
		500 Ksamples/s, 12 bit, external reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	346[1]	—	µA
		500 Ksamples/s, 12 bit, internal 1.25V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	354[1]	—	µA
		10 kSamples/s, 12 bit, internal 1.25 V reference, WARMUP = 00b, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	52[1]	—	µA
		10 kSamples/s, 12 bit, internal 1.25 V reference, WARMUP = 01b, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	50[1]	—	µA
		10 kSamples/s, 12 bit, internal 1.25 V reference, WARMUP = 10b, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	54[1]	—	µA
Current Consumption of internal voltage referene	I_{ADCREF}	Internal voltage reference	—	65	—	µA
Input capacitance	C_{ADCIN}		—	2	—	pF
Input ON resistance	R_{ADCIN}		1	—	—	MΩ
Input RC filter resistance	$R_{ADCFILT}$		—	10	—	kΩ

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input RC filter/decoupling capacitance	$C_{ADCFILT}$		—	250	—	fF
Input bias current	$I_{ADCBIASIN}$	VSS < VIN < VDD	-40	—	40	nA
Input offset current	$I_{ADCOFFSETIN}$	VSS < VIN < VDD	-40	—	40	nA
ADC Clock Frequency	f_{ADCCLK}	BIASPROG=0x747	—	—	7	MHz
		BIASPROG=0xF4B	—	—	13	MHz
Conversion time	$t_{ADCCONV}$	6-bit	7	—	—	ADCCLK Cycles
		8-bit	11	—	—	ADCCLK Cycles
		12-bit	13	—	—	ADCCLK Cycles
Acquisition time	t_{ADCACQ}	Programmable	1	—	256	ADCCLK Cycles
Required acquisition time for VDD/3 reference	$t_{ADCACQVDD3}$		2	—	—	µs
Startup time of reference generator and ADC core	$t_{ADCSTART}$	NORMAL mode	—	5	—	µs
		KEEPADCWARM mode	—	1	—	µs

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Signal-to-Noise Ratio (SNR)	SNR_{ADC}	1 MSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	59	—	dB
		1 MSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	63	—	dB
		1 MSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	67	—	dB
		1 MSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	63	—	dB
		1 MSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, 5 V reference, ADC_CLK =13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, V_{DD} reference, ADC_CLK= 13 MHz, BIASPROG =0xF4B	63	69	—	dB
		1 MSamples/s, 12 bit, differential, $2xV_{DD}$ reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	70	—	dB
		200 kSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	62	—	dB
		200 kSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	63	—	dB
		200 kSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	67	—	dB
		200 kSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	63	—	dB
		200 kSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	66	—	dB
		200 kSamples/s, 12 bit, differential, 5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	66	—	dB

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Signal-to-Noise Ratio (SNR)	SNR_{ADC}	200 kSamples/s, 12 bit, differential, V_{DD} reference,ADC_CLK = 7 MHz, BIASPROG = 0x747	63	69	—	dB
		200 kSamples/s, 12 bit, differential, 2xV_{DD} reference,ADC_CLK = 7 MHz, BIASPROG = 0x747	—	70	—	dB

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Signal-to-Noise And Distortion Ratio (SINAD)	$SINAD_{ADC}$	1 MSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	58	—	dB
		1 MSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	62	—	dB
		1 MSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	63	—	dB
		1 MSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, 5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, V_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	62	68	—	dB
		1 MSamples/s, 12 bit, differential, $2xV_{DD}$ reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	68	—	dB
		200 kSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	61	—	dB
		200 kSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	62	—	dB
		200 kSamples/s, 12 bit, single-ended, VDD reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	66	—	dB
		200 kSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	63	—	dB
		200 kSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	66	—	dB
		200 kSamples/s, 12 bit, differential, 5V reference, ADC_CLK= 7 MHz, BIASPROG = 0x747	—	66	—	dB

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Signal-to-Noise And Distortion Ratio (SINAD)	$SINAD_{ADC}$	200 kSamples/s, 12 bit, differential, V_{DD} reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	62	68	—	dB
		200 kSamples/s, 12 bit, differential, $2xV_{DD}$ reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	69	—	dB

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Spurious-Free Dynamic Range (SFDR)	$SFDR_{ADC}$	1 MSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	75	—	dBc
		1 MSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	76	—	dBc
		1 MSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	76	—	dBc
		1 MSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	78	—	dBc
		1 MSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	77	—	dBc
		1 MSamples/s, 12 bit, differential, V_{DD} reference, ADC_CLK= 13 MHz, BIASPROG = 0xF4B	—	76	—	dBc
		1 MSamples/s, 12 bit, differential, $2xV_{DD}$ reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	68	79	—	dBc
		1 MSamples/s, 12 bit, differential, 5 V reference, ADC_CLK =13 MHz, BIASPROG = 0xF4B	—	79	—	dBc
		200 kSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	75	—	dBc
		200 kSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	75	—	dBc
		200 kSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	76	—	dBc
		200 kSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	79	—	dBc
		200 kSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	79	—	dBc
		200 kSamples/s, 12 bit, differential, 5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	78	—	dBc

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Spurious-Free Dynamic Range (SFDR)	$SFDR_{ADC}$	200 kSamples/s, 12 bit, differential, V_{DD} reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	68	79	—	dBc
		200 kSamples/s, 12 bit, differential, 2xV_{DD} reference,ADC_CLK = 7 MHz, BIASPROG = 0x747	—	79	—	dBc
Offset voltage	$V_{ADCOFFSET}$	After calibration, single-ended	—	0.3	—	mV
		After calibration, differential	-4	0.3	4	mV
Thermometer output gradient	$TGRAD_{ADCTH}$		—	-1.92	—	mV/°C
			—	-6.3	—	ADC Codes/°C
Differential non-linearity (DNL)	DNL_{ADC}	V_{DD}= 3.0 V, external 2.5V reference	-1	±0.7	4	LSB
Integral non-linearity (INL), End point method	INL_{ADC}	V_{DD}= 3.0 V, external 2.5V reference	—	±1.6	±3	LSB
Missing codes	MC_{ADC}		—	—	3	LSB
Gain error drift	$GAIN_{ED}$	1.25 V reference	—	0.01[2]	0.033[3]	%/°C
		2.5 V reference	—	0.01[2]	0.03[3]	%/°C
Offset error drift	$OFFSET_{ED}$	1.25 V reference	—	0.00[2]	0.06[3]	LSB/°C
		2.5 V reference	—	0.00[2]	0.04[3]	LSB/°C
VREF voltage	V_{REF}	1.25 V reference	1.2	1.25	1.3	V
		2.5 V reference	2.4	2.5	2.6	V
VREF voltage drift	V_{REF_VDRIFT}	1.25 V reference	-12.4	2.9	18.2	mV/V
		2.5 V reference, VDD > 2.5 V	-24.6	5.7	35.2	mV/V
VREF temperature drift	V_{REF_TDRIFT}	1.25 V reference	-132	272	677	µV/°C
		2.5 V reference	-231	545	1271	µV/°C
VREF current consumption	I_{VREF}	1.25 V reference	—	67	114	µA
		2.5 V reference	—	55	82	µA
ADC and DAC VREF matching	V_{REF_MATCH}	1.25 V reference	—	99.85	—	%
		2.5 V reference	—	100.01	—	%

Note:

1. Includes required contribution from the voltage reference.
2. Typical numbers given by abs(Mean) / (85 - 25).
3. Max number given by (abs(Mean) + 3x stddev) / (85 - 25).

The integral non-linearity (INL) and differential non-linearity parameters are explained in the following two figures.

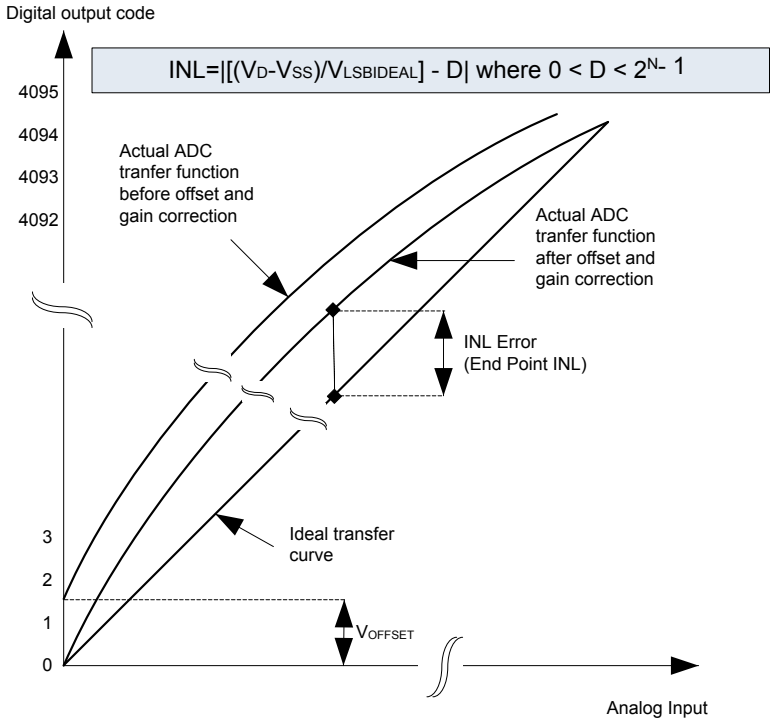


Figure 4.26. Integral Non-Linearity (INL)

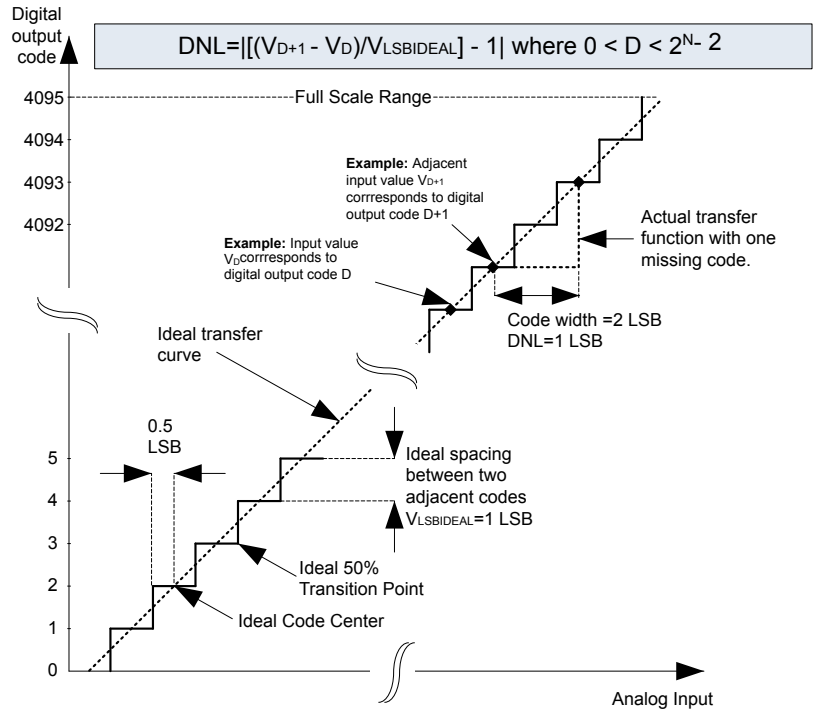


Figure 4.27. Differential Non-Linearity (DNL)

4.11.1 Typical Performance

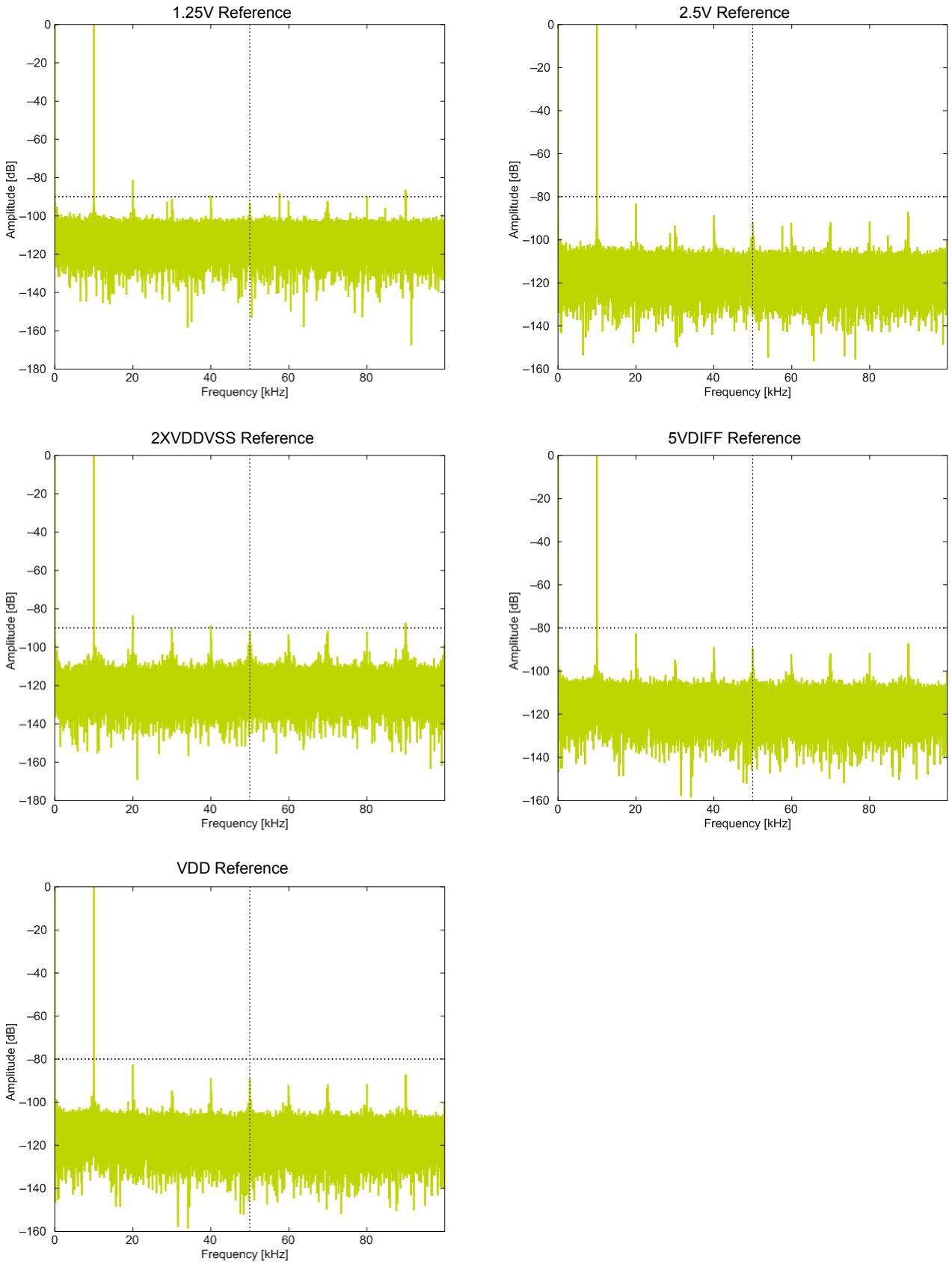


Figure 4.28. ADC Frequency Spectrum, VDD = 3 V, Temp = 25 °C

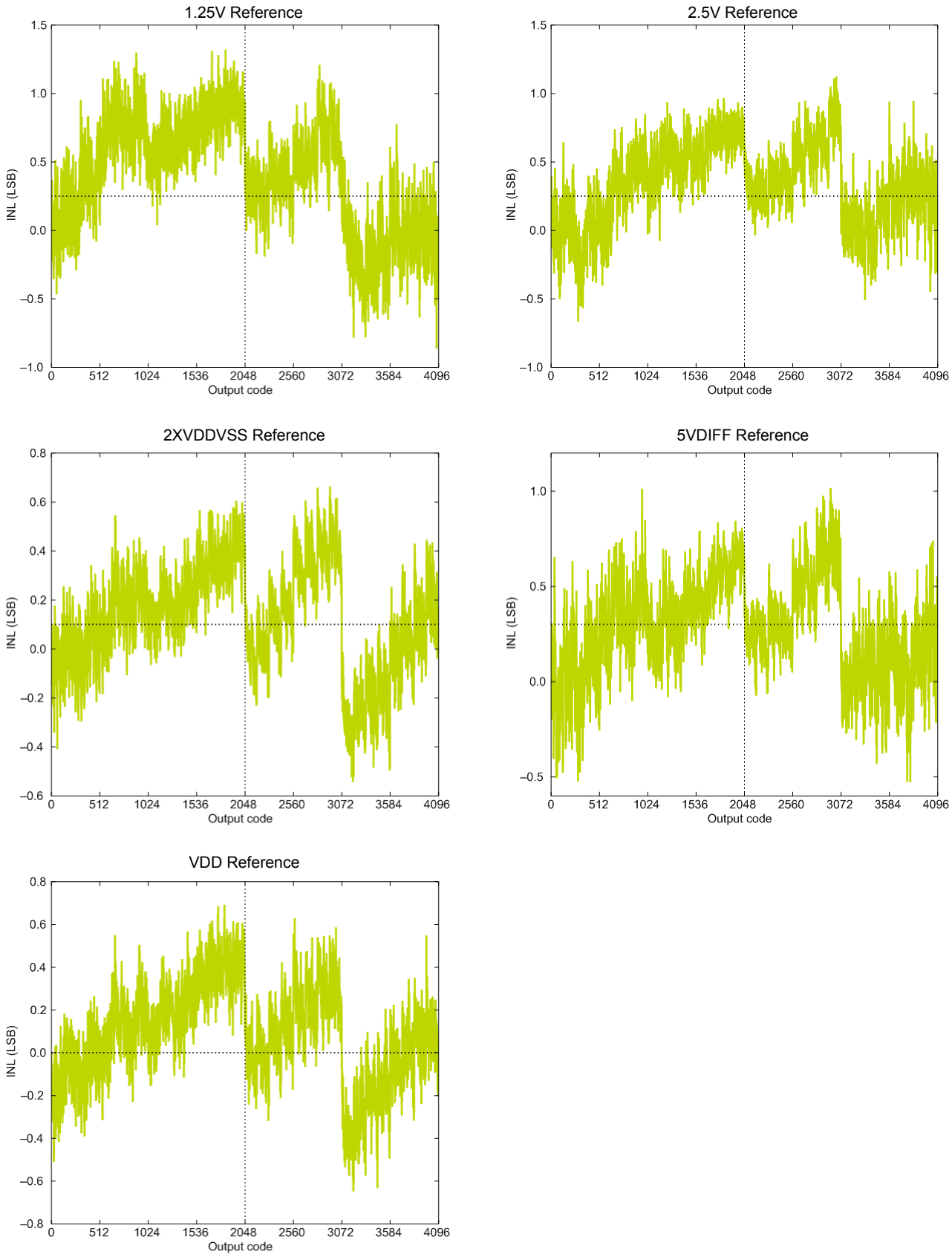


Figure 4.29. ADC Integral Linearity Error vs Code, VDD = 3 V, Temp = 25 °C

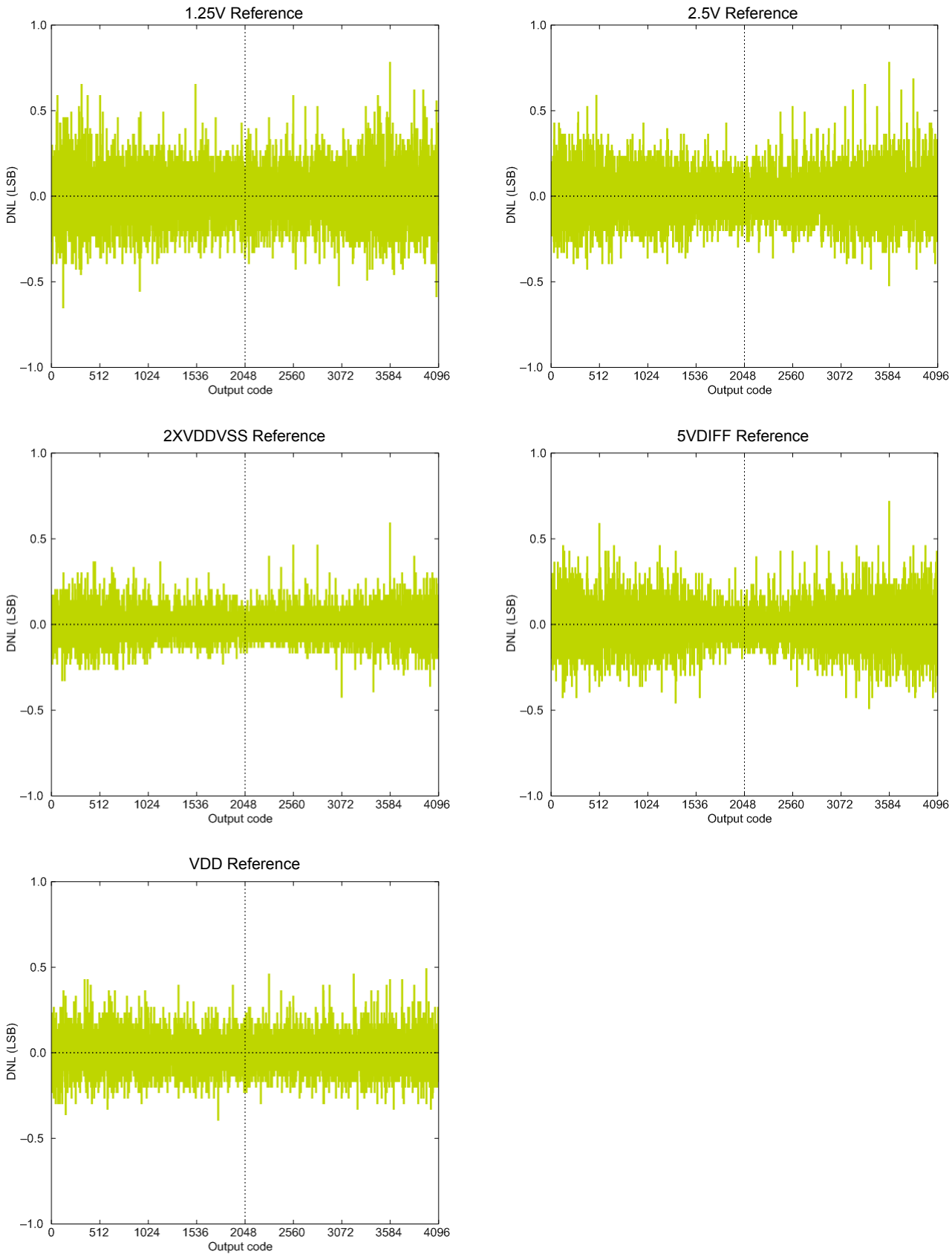


Figure 4.30. ADC Differential Linearity Error vs Code, VDD = 3 V, Temp = 25 °C

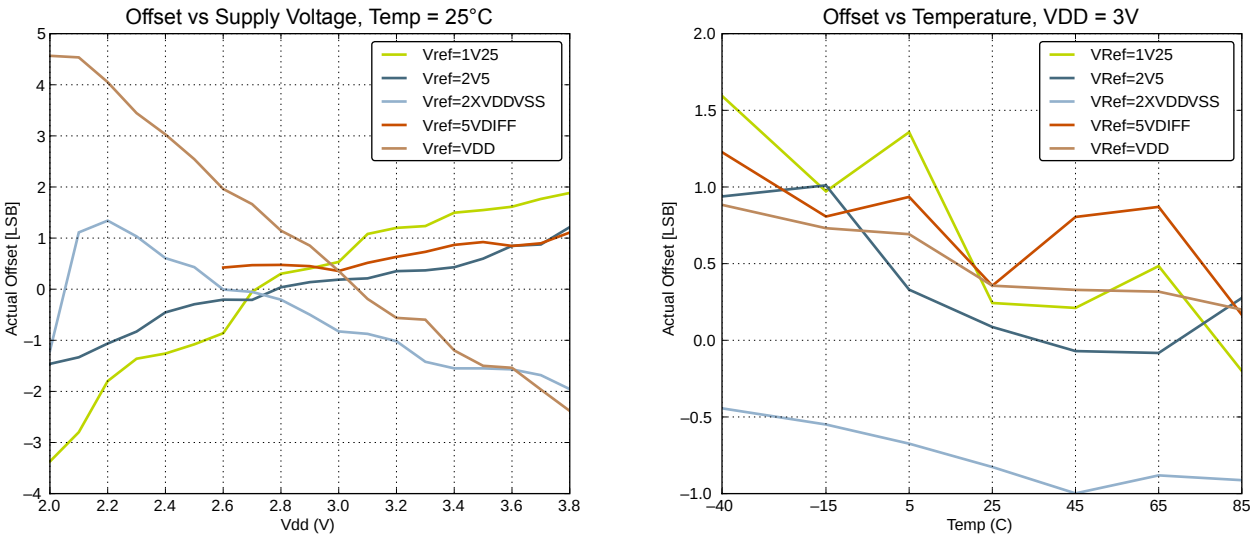


Figure 4.31. ADC Absolute Offset, Common Mode = VDD/2

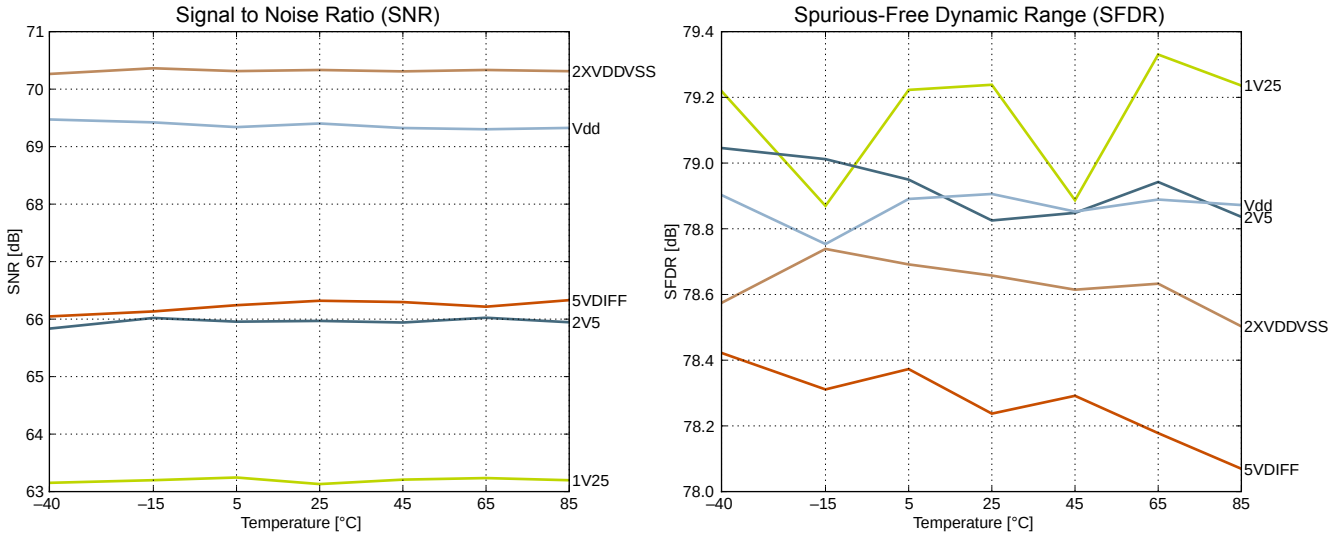


Figure 4.32. ADC Dynamic Performance vs Temperature for all ADC References, VDD = 3 V

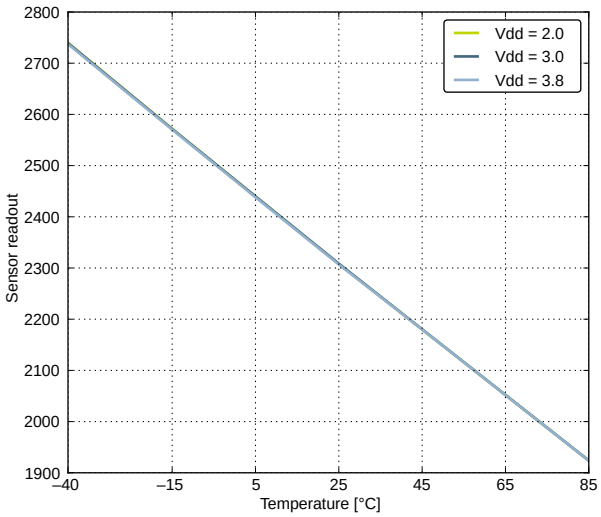


Figure 4.33. ADC Temperature Sensor Readout

4.12 Current Digital Analog Converter (IDAC)

Table 4.17. IDAC Range 0 Source

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Active current with STEP-SEL=0x10	I_{IDAC}	EM0, default settings	—	13.0	—	µA
		Duty-cycled	—	10	—	nA
Nominal IDAC output current with STEPSEL=0x10	I_{0x10}		—	0.85	—	µA
Step size	I_{STEP}		—	0.05	—	µA
Current drop at high impedance load	I_D	V_{IDAC_OUT} = VDD - 100mV	—	0.79	—	%
Temperature coefficient	TC_{IDAC}	VDD = 3.0V, STEPSEL=0x10	—	0.3	—	nA/°C
Voltage coefficient	VC_{IDAC}	T = 25°C, STEPSEL=0x10	—	11.7	—	nA/V

Table 4.18. IDAC Range 0 Sink

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Active current with STEP-SEL=0x10	I_{IDAC}	EM0, default settings	—	15.1	—	µA
Nominal IDAC output current with STEPSEL=0x10	I_{0x10}		—	0.85	—	µA
Step size	I_{STEP}		—	0.05	—	µA
Current drop at high impedance load	I_D	V_{IDAC_OUT} = 200mV	—	0.30	—	%
Temperature coefficient	TC_{IDAC}	VDD = 3.0V, STEPSEL=0x10	—	0.2	—	nA/°C
Voltage coefficient	VC_{IDAC}	T = 25°C, STEPSEL=0x10	—	12.5	—	nA/V

Table 4.19. IDAC Range 1 Source

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Active current with STEP-SEL=0x10	I_{IDAC}	EM0, default settings	—	14.4	—	µA
		Duty-cycled	—	10	—	nA
Nominal IDAC output current with STEPSEL=0x10	I_{0x10}		—	3.2	—	µA
Step size	I_{STEP}		—	0.1	—	µA
Current drop at high impedance load	I_D	V_{IDAC_OUT} = VDD - 100mV	—	0.75	—	%
Temperature coefficient	TC_{IDAC}	VDD = 3.0V, STEPSEL=0x10	—	0.7	—	nA/°C
Voltage coefficient	VC_{IDAC}	T = 25°C, STEPSEL=0x10	—	38.4	—	nA/V

Table 4.20. IDAC Range 1 Sink

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Active current with STEP-SEL=0x10	I_{IDAC}	EM0, default settings	—	19.4	—	µA
Nominal IDAC output current with STEPSEL=0x10	I_{0x10}		—	3.2	—	µA
Step size	I_{STEP}		—	0.1	—	µA
Current drop at high impedance load	I_D	V_{IDAC_OUT} = 200mV	—	0.32	—	%
Temperature coefficient	TC_{IDAC}	VDD = 3.0V, STEPSEL=0x10	—	0.7	—	nA/°C
Voltage coefficient	VC_{IDAC}	T = 25°C, STEPSEL=0x10	—	40.9	—	nA/V

Table 4.21. IDAC Range 2 Source

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Active current with STEP-SEL=0x10	I_{IDAC}	EM0, default settings	—	17.3	—	µA
		Duty-cycled	—	10	—	nA
Nominal IDAC output current with STEPSEL=0x10	I_{0x10}		—	8.5	—	µA
Step size	I_{STEP}		—	0.5	—	µA
Current drop at high impedance load	I_D	V_{IDAC_OUT} = VDD - 100mV	—	1.22	—	%
Temperature coefficient	TC_{IDAC}	VDD = 3.0V, STEPSEL=0x10	—	2.8	—	nA/°C
Voltage coefficient	VC_{IDAC}	T = 25°C, STEPSEL=0x10	—	96.6	—	nA/V

Table 4.22. IDAC Range 2 Sink

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Active current with STEP-SEL=0x10	I_{IDAC}	EM0, default settings	—	29.3	—	µA
Nominal IDAC output current with STEPSEL=0x10	I_{0x10}		—	8.5	—	µA
Step size	I_{STEP}		—	0.5	—	µA
Current drop at high impedance load	I_D	V_{IDAC_OUT} = 200mV	—	0.62	—	%
Temperature coefficient	TC_{IDAC}	VDD = 3.0V, STEPSEL=0x10	—	2.8	—	nA/°C
Voltage coefficient	VC_{IDAC}	T = 25°C, STEPSEL=0x10	—	94.4	—	nA/V

Table 4.23. IDAC Range 3 Source

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Active current with STEP-SEL=0x10	I_{IDAC}	EM0, default settings	—	18.7	—	µA
		Duty-cycled	—	10	—	nA
Nominal IDAC output current with STEPSEL=0x10	I_{0x10}		—	33.9	—	µA
Step size	I_{STEP}		—	2.0	—	µA
Current drop at high impedance load	I_D	V_{IDAC_OUT} = VDD - 100mV	—	3.54	—	%
Temperature coefficient	TC_{IDAC}	VDD = 3.0V, STEPSEL=0x10	—	10.9	—	nA/°C
Voltage coefficient	VC_{IDAC}	T = 25°C, STEPSEL=0x10	—	159.5	—	nA/V

Table 4.24. IDAC Range 3 Sink

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Active current with STEP-SEL=0x10	I_{IDAC}	EM0, default settings	—	62.5	—	µA
Nominal IDAC output current with STEPSEL=0x10	I_{0x10}		—	34.1	—	µA
Step size	I_{STEP}		—	2.0	—	µA
Current drop at high impedance load	I_D	V_{IDAC_OUT} = 200mV	—	1.75	—	%
Temperature coefficient	TC_{IDAC}	VDD = 3.0V, STEPSEL=0x10	—	10.9	—	nA/°C
Voltage coefficient	VC_{IDAC}	T = 25°C, STEPSEL=0x10	—	148.6	—	nA/V

Table 4.25. IDAC

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Start-up time, from enabled to output settled	$t_{IDAC-START}$		—	40	—	µs

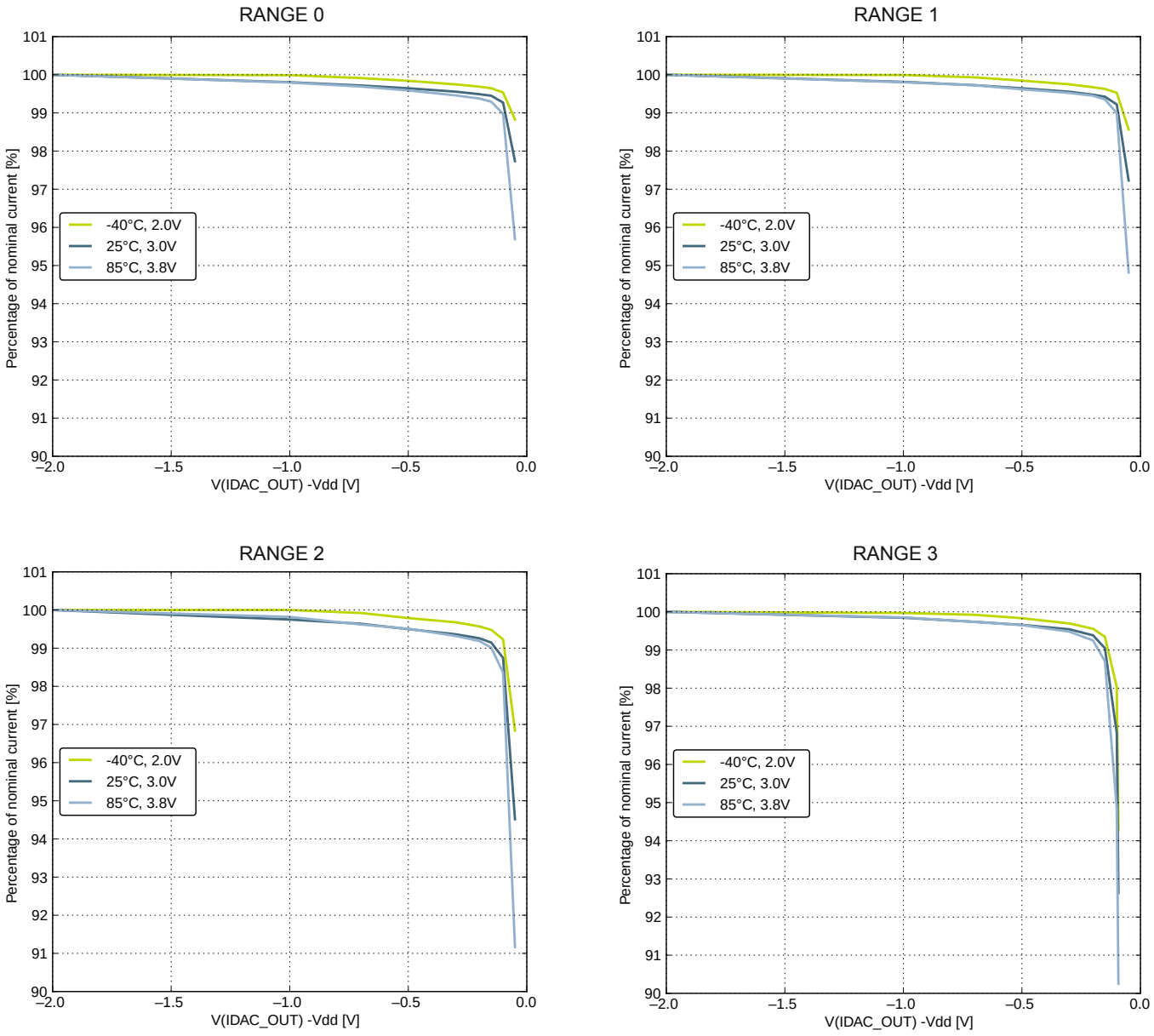


Figure 4.34. IDAC Source Current as a function of voltage on IDAC_OUT

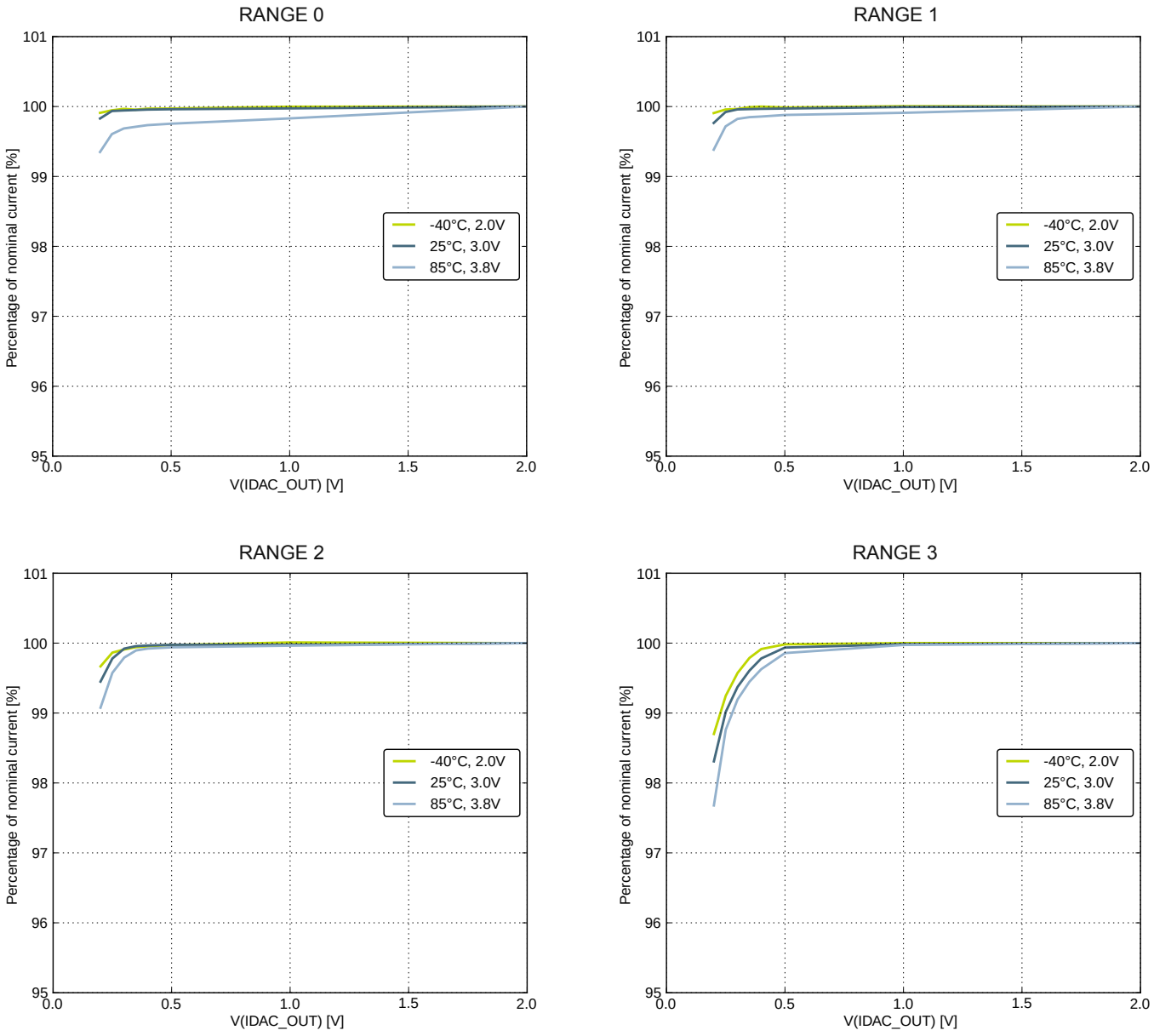


Figure 4.35. IDAC Sink Current as a function of voltage on IDAC_OUT

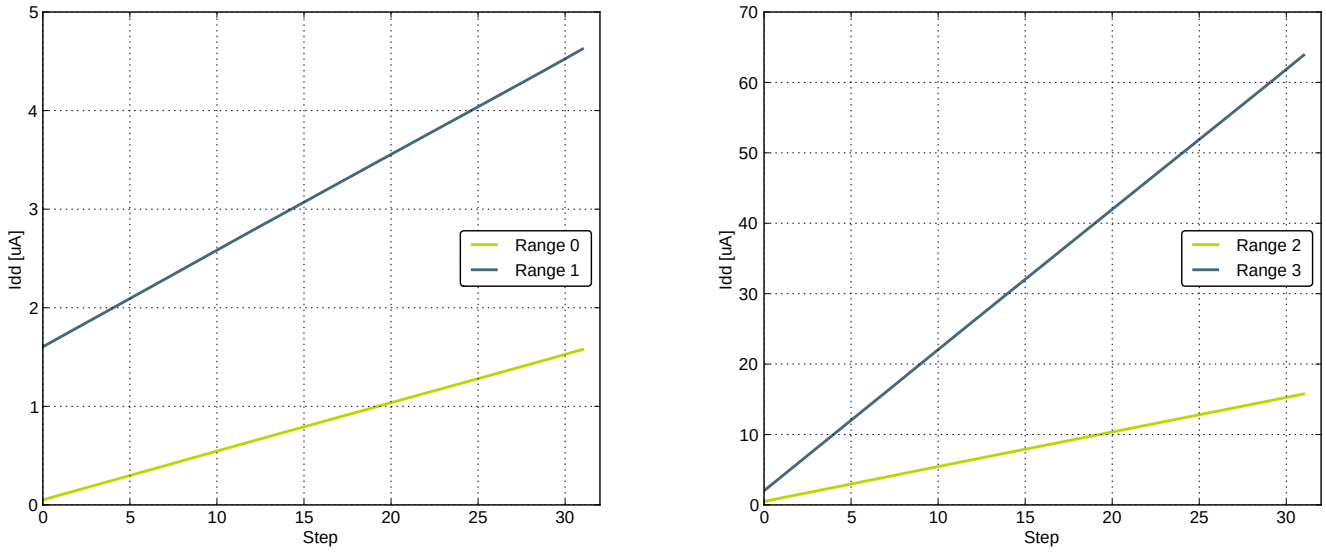


Figure 4.36. IDAC Linearity

4.13 Analog Comparator (ACMP)

Table 4.26. ACMP

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V_{ACMPIN}		0	—	V_{DD}	V
ACMP Common Mode voltage range	V_{ACMPCM}		0	—	V_{DD}	V
Active current	I_{ACMP}	BIASPROG=0b0000, FULLBIAS=0 and HALFBIAS=1 in ACMPn_CTRL register	—	0.1	0.4	µA
		BIASPROG=0b1111, FULLBIAS= 0 and HALFBIAS=0 in ACMPn_CTRL register	—	2.87	15	µA
		BIASPROG=0b1111, FULLBIAS= 1 and HALFBIAS=0 in ACMPn_CTRL register	—	195	520	µA
Current consumption of internal voltage reference	$I_{ACMPREF}$	Internal voltage reference off. Using external voltage reference	—	0	—	µA
		Internal voltage reference	—	5	—	µA
Offset voltage	$V_{ACMPOFFSET}$	BIASPROG= 0b1010, FULLBIAS=0 and HALFBIAS=0 in ACMPn_CTRL register	-12	0	12	mV
ACMP hysteresis	$V_{ACMPHYST}$	Programmable	—	17	—	mV
Capacitive Sense Internal Resistance	R_{CSRES}	CSRESSEL=0b00 in ACMPn_INPUTSEL	—	40	—	kΩ
		CSRESSEL=0b01 in ACMPn_INPUTSEL	—	70	—	kΩ
		CSRESSEL=0b10 in ACMPn_INPUTSEL	—	101	—	kΩ
		CSRESSEL=0b11 in ACMPn_INPUTSEL	—	132	—	kΩ
Startup time	$t_{ACMPSTART}$		—	—	10	µs

The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference as given in in the following equation. $I_{ACMPREF}$ is zero if an external voltage reference is used.

$$I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF}$$

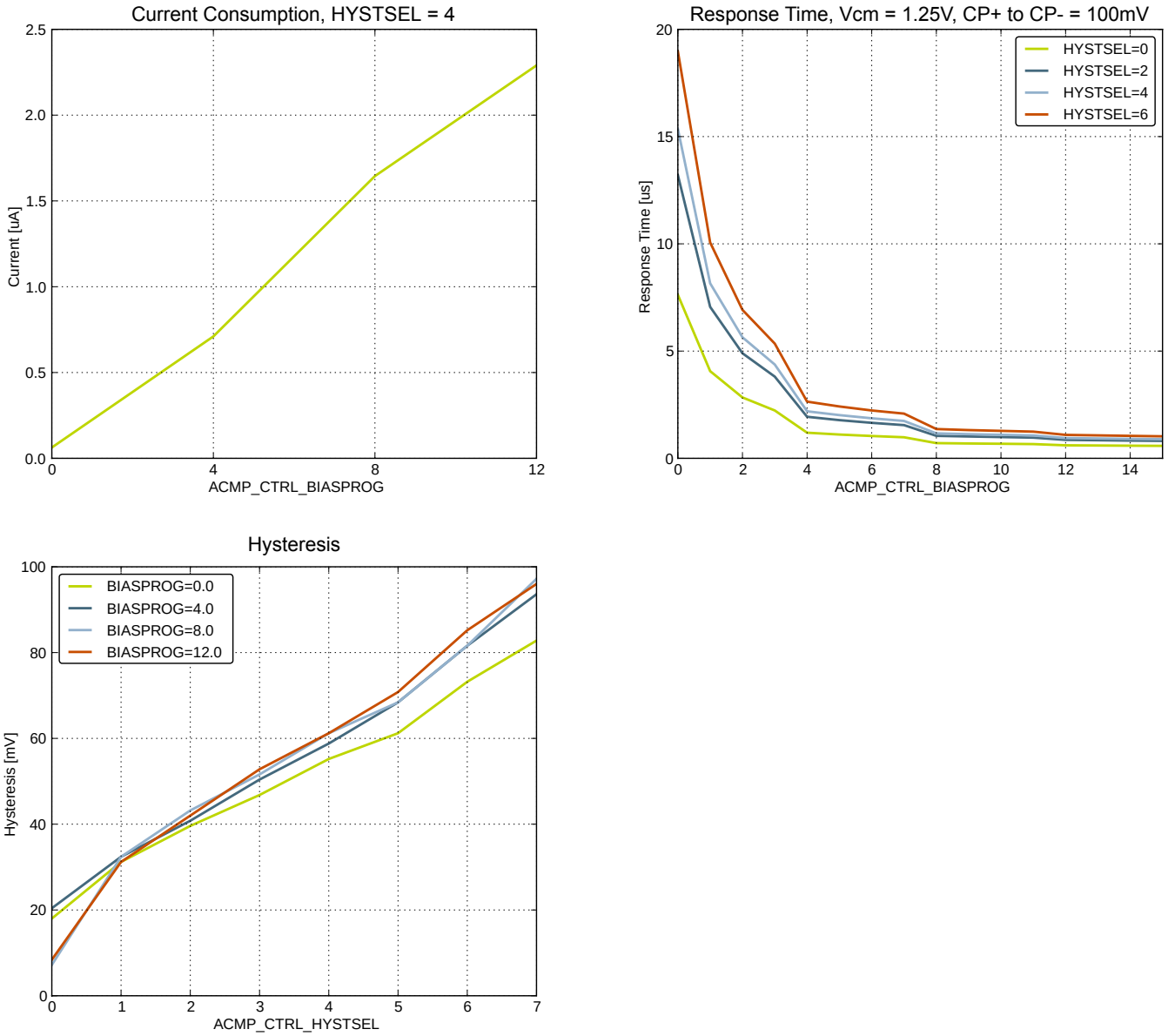


Figure 4.37. ACMP Characteristics, Vdd = 3 V, Temp = 25 °C, FULLBIAS = 0, HALFBIAS = 1

4.14 Voltage Comparator (VCMP)

Table 4.27. VCMP

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V_{VCMPIN}		—	V_{DD}	—	V
VCMP Common Mode voltage range	V_{VCMPCM}		—	V_{DD}	—	V
Active current	I_{VCMP}	BIASPROG=0b0000 and HALFBIAS=1 in VCMPn_CTRL register	—	0.2	0.8	µA
		BIASPROG=0b1111 and HALFBIAS=0 in VCMPn_CTRL register. LPREF=0.	—	22	35	µA
Startup time reference generator	$t_{VCMPREF}$	NORMAL	—	10	—	µs
Offset voltage	$V_{VCMPOFFSET}$	Single-ended	—	10	—	mV
		Differential	—	10	—	mV
VCMP hysteresis	$V_{VCMPHYST}$		—	17	—	mV
Startup time	$t_{VCMPSTART}$		—	—	10	µs

The V_{DD} trigger level can be configured by setting the TRIGLEVEL field of the VCMP_CTRL register in accordance with the following equation:

$$V_{\text{DD Trigger Level}} = 1.667V + 0.034 \times \text{TRIGLEVEL}$$

4.15 I2C

Table 4.28. I2C Standard-mode (Sm)

Parameter	Symbol	Min	Typ	Max	Unit
SCL clock frequency	f_{SCL}	0	—	100[1]	kHz
SCL clock low time	t_{LOW}	4.7	—	—	µs
SCL clock high time	t_{HIGH}	4.0	—	—	µs
SDA set-up time	$t_{SU,DAT}$	250	—	—	ns
SDA hold time	$t_{HD,DAT}$	8	—	3450[2,3]	ns
Repeated START condition set-up time	$t_{SU,STA}$	4.7	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$	4.0	—	—	µs
STOP condition set-up time	$t_{SU,STO}$	4.0	—	—	µs
Bus free time between a STOP and a START condition	t_{BUF}	4.7	—	—	µs

Note:
1. For the minimum HFPERCLK frequency required in Standard-mode, see the I2C chapter in the EFM32HG Reference Manual.
2. The maximum SDA hold time ($t_{HD,DAT}$) needs to be met only when the device does not stretch the low time of SCL (t_{LOW}).
3. When transmitting data, this number is guaranteed only when I2Cn_CLKDIV < ((3450*10^{-9} [s] * $f_{HFPERCLK}$ [Hz]) - 5).

Table 4.29. I2C Fast-mode (Fm)

Parameter	Symbol	Min	Typ	Max	Unit
SCL clock frequency	f_{SCL}	0	—	400[1]	kHz
SCL clock low time	t_{LOW}	1.3	—	—	µs
SCL clock high time	t_{HIGH}	0.6	—	—	µs
SDA set-up time	$t_{SU,DAT}$	100	—	—	ns
SDA hold time	$t_{HD,DAT}$	8	—	900[2,3]	ns
Repeated START condition set-up time	$t_{SU,STA}$	0.6	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$	0.6	—	—	µs
STOP condition set-up time	$t_{SU,STO}$	0.6	—	—	µs
Bus free time between a STOP and a START condition	t_{BUF}	1.3	—	—	µs

Note:
1. For the minimum HFPERCLK frequency required in Fast-mode, see the I2C chapter in the EFM32HG Reference Manual.
2. The maximum SDA hold time ($t_{HD,DAT}$) needs to be met only when the device does not stretch the low time of SCL (t_{LOW}).
3. When transmitting data, this number is guaranteed only when I2Cn_CLKDIV < ((900*10^{-9} [s] * $f_{HFPERCLK}$ [Hz]) - 5).

Table 4.30. I2C Fast-mode Plus (Fm+)

Parameter	Symbol	Min	Typ	Max	Unit
SCL clock frequency	f_{SCL}	0	—	1000[1]	kHz
SCL clock low time	t_{LOW}	0.5	—	—	µs
SCL clock high time	t_{HIGH}	0.26	—	—	µs
SDA set-up time	$t_{SU,DAT}$	50	—	—	ns
SDA hold time	$t_{HD,DAT}$	8	—	—	ns
Repeated START condition set-up time	$t_{SU,STA}$	0.26	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$	0.26	—	—	µs
STOP condition set-up time	$t_{SU,STO}$	0.26	—	—	µs
Bus free time between a STOP and a START condition	t_{BUF}	0.5	—	—	µs

Note:
1. For the minimum HFPERCLK frequency required in Fast-mode Plus, see the I2C chapter in the EFM32HG Reference Manual.

4.16 USB

The USB hardware in the EFM32HG passes all tests for USB 2.0 Full Speed certification. The test report will be distributed with application note *AN0046 - USB Hardware Design Guide* when ready.

Table 4.31. USB

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
USB regulator output voltage	V_{USBOUT}		3.1	3.4	3.7	V
USB regulator output current	I_{USBOUT}	BIASPROG=0, T_{AMB}=25°C	55.7	79.4	104.1	mA
		BIASPROG=1, T_{AMB}=25°C	66.0	95.9	126.4	mA
		BIASPROG=2, T_{AMB}=25°C	94.6	146.5	188.1	mA
		BIASPROG=3, T_{AMB}=25°C	80.4	128.3	176.0	mA

4.17 Digital Peripherals

Table 4.32. Digital Peripherals

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
USART current	I_{USART}	USART idle current, clock enabled	—	7.5	—	µA/MHz
LEUART current	I_{LEUART}	LEUART idle current, clock enabled	—	150	—	nA
I2C current	I_{I2C}	I2C idle current, clock enabled	—	6.25	—	µA/MHz
TIMER current	I_{TIMER}	TIMER_0 idle current, clock enabled	—	8.75	—	µA/MHz
PCNT current	I_{PCNT}	PCNT idle current, clock enabled	—	100	—	nA
RTC current	I_{RTC}	RTC idle current, clock enabled	—	100	—	nA
AES current	I_{AES}	AES idle current, clock enabled	—	2.5	—	µA/MHz
GPIO current	I_{GPIO}	GPIO idle current, clock enabled	—	5.31	—	µA/MHz
PRS current	I_{PRS}	PRS idle current	—	2.81	—	µA/MHz
DMA current	I_{DMA}	Clock enable	—	8.12	—	µA/MHz

5. Pin Definitions

Note: Please refer to the application note *AN0002 EFM32 Hardware Design Considerations* for guidelines on designing Printed Circuit Boards (PCBs) for the EFM32HG.

5.1 EFM32HG108 (QFN24)

5.1.1 Pinout

The EFM32HG108 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

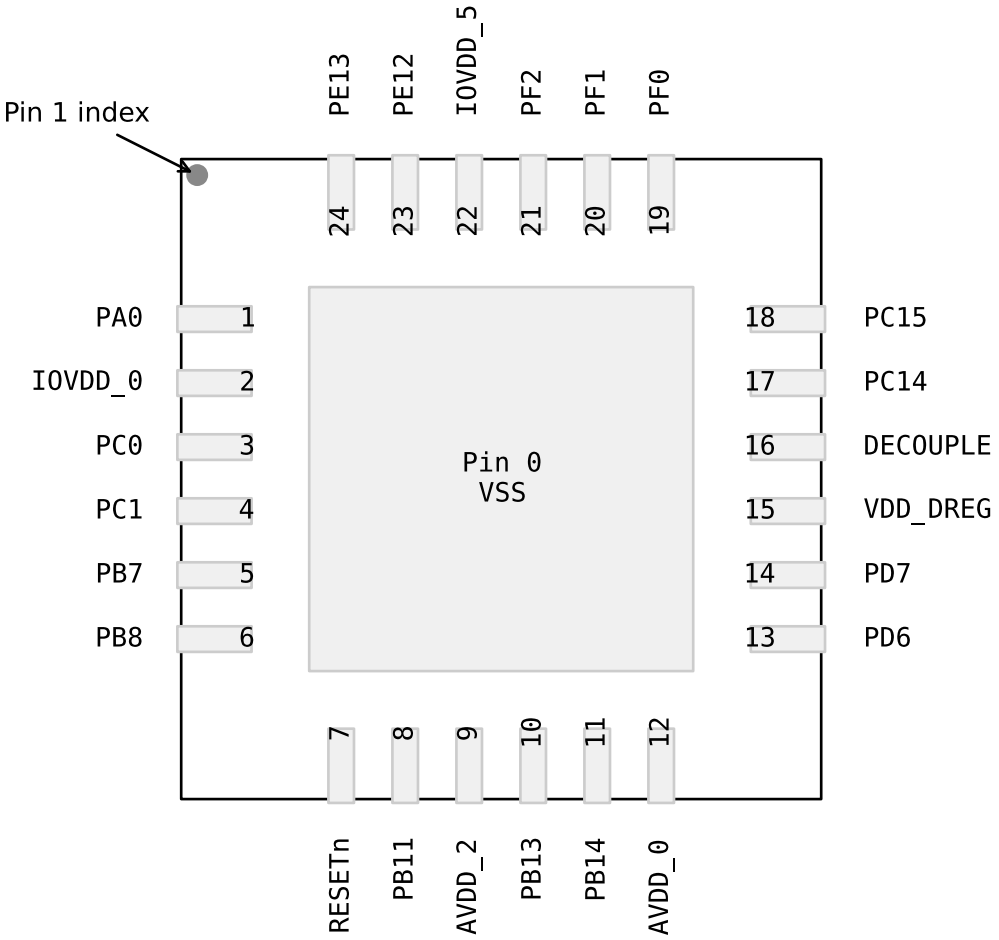


Figure 5.1. EFM32HG108 Pinout (top view, not to scale)

Table 5.1. Device Pinout

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
0	VSS	Ground.			
1	PA0		TIM0_CC1 #6 TIM0_CC0 #0/1/4 PCNT0_S0IN #4	US1_RX #4 LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 PRS_CH3 #3 GPIO_EM4WU0
2	IOVDD_0	Digital IO power supply 0.			

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
3	PC0	ACMP0_CH0	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5/6 US1_TX #0 US1_CS #5 I2C0_SDA #4	PRS_CH2 #0
4	PC1	ACMP0_CH1	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5/6 US1_TX #5 US1_RX #0 I2C0_SCL #4	PRS_CH3 #0
5	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
6	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
7	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
8	PB11		TIM1_CC2 #3 PCNT0_S1IN #4	US1_CLK #4	CMU_CLK1 #3 ACMP0_O #3
9	AVDD_2	Analog power supply 2.			
10	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
11	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
12	AVDD_0	Analog power supply 0.			
13	PD6		TIM1_CC0 #4 PCNT0_S0IN #3	US1_RX #2/3 I2C0_SDA #1	ACMP_O #2
14	PD7		TIM1_CC1 #4 PCNT0_S1IN #3	US1_TX #2/3 I2C0_SCL #1	CMU_CLK0 #2
15	VDD_DREG	Power supply for on-chip voltage regulator.			
16	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
17	PC14		TIM0_CDTI1 #1/6 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 US1_CS #3/4 LEU0_TX #5	PRS_CH0 #2
18	PC15		TIM0_CDTI2 #1/6 TIM1_CC2 #0	US0_CLK #3 US1_CLK #3 LEU0_RX #5	PRS_CH1 #2

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
19	PF0		TIM0_CC0 #5	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0 BOOT_TX
20	PF1		TIM0_CC1 #5	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0 GPIO_EM4WU3 BOOT_RX
21	PF2		TIM0_CC2 #5/6 TIM2_CC0 #3	US1_TX #4 LEU0_TX #4	CMU_CLK0 #3 PRS_CH0 #3 GPIO_EM4WU4
22	IOVDD_5	Digital IO power supply 5.			
23	PE12		TIM1_CC2 #1 TIM2_CC1 #3	US0_RX #3 US0_CLK #0/6 I2C0_SDA #6	CMU_CLK1 #2 PRS_CH1 #3
24	PE13		TIM2_CC2 #3	US0_TX #3 US0_CS #0/6 I2C0_SCL #6	ACMP0_O #0 PRS_CH2 #3 GPIO_EM4WU5

5.1.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.2. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_O	PE13		PD6	PB11				Analog comparator ACMP0, digital output.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0			PD7	PF2				Clock Management Unit, clock output number 0.
CMU_CLK1			PE12	PB11				Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL		PD7			PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6			PC0	PF0	PE12	I2C0 Serial Data input / output.
LEU0_RX		PB14		PF1	PA0	PC15		LEUART0 Receive input.
LEU0_TX		PB13		PF0	PF2	PC14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN			PC0	PD6	PA0			Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1	PD7	PB11			Pulse Counter PCNT0 input number 1.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
PRS_CH0	PA0		PC14	PF2				Peripheral Reflex System PRS, channel 0.
PRS_CH1			PC15	PE12				Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0			PE13				Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1			PA0				Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1					PC0	PF1	PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2					PC1	PF2	PF2	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI1		PC14					PC14	Timer 0 Complimentary Dead Time Insertion channel 1.
TIM0_CDTI2		PC15					PC15	Timer 0 Complimentary Dead Time Insertion channel 2.
TIM1_CC0				PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14			PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11				Timer 1 Capture Compare input / output channel 2.
TIM2_CC0				PF2				Timer 2 Capture Compare input / output channel 0.
TIM2_CC1				PE12				Timer 2 Capture Compare input / output channel 1.
TIM2_CC2				PE13				Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12			PC15	PB13	PB13	PE12	USART0 clock input / output.
US0_CS	PE13			PC14	PB14	PB14	PE13	USART0 chip select input / output.
US0_RX				PE12	PB8	PC1	PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX				PE13	PB7	PC0	PC0	USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7		PF0	PC15	PB11			USART1 clock input / output.
US1_CS	PB8		PF1	PC14	PC14	PC0		USART1 chip select input / output.
US1_RX	PC1		PD6	PD6	PA0			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0		PD7	PD7	PF2	PC1		USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).

5.1.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32HG108 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.3. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	PA0
Port B	-	PB14	PB13	-	PB11	-	-	PB8	PB7	-	-	-	-	-	-	-
Port C	PC15	PC14	-	-	-	-	-	-	-	-	-	-	-	-	PC1	PC0
Port D	-	-	-	-	-	-	-	-	PD7	PD6	-	-	-	-	-	-
Port E	-	-	PE13	PE12	-	-	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	-	-	-	PF2	PF1	PF0

5.2 EFM32HG110 (QFN24)

5.2.1 Pinout

The EFM32HG110 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

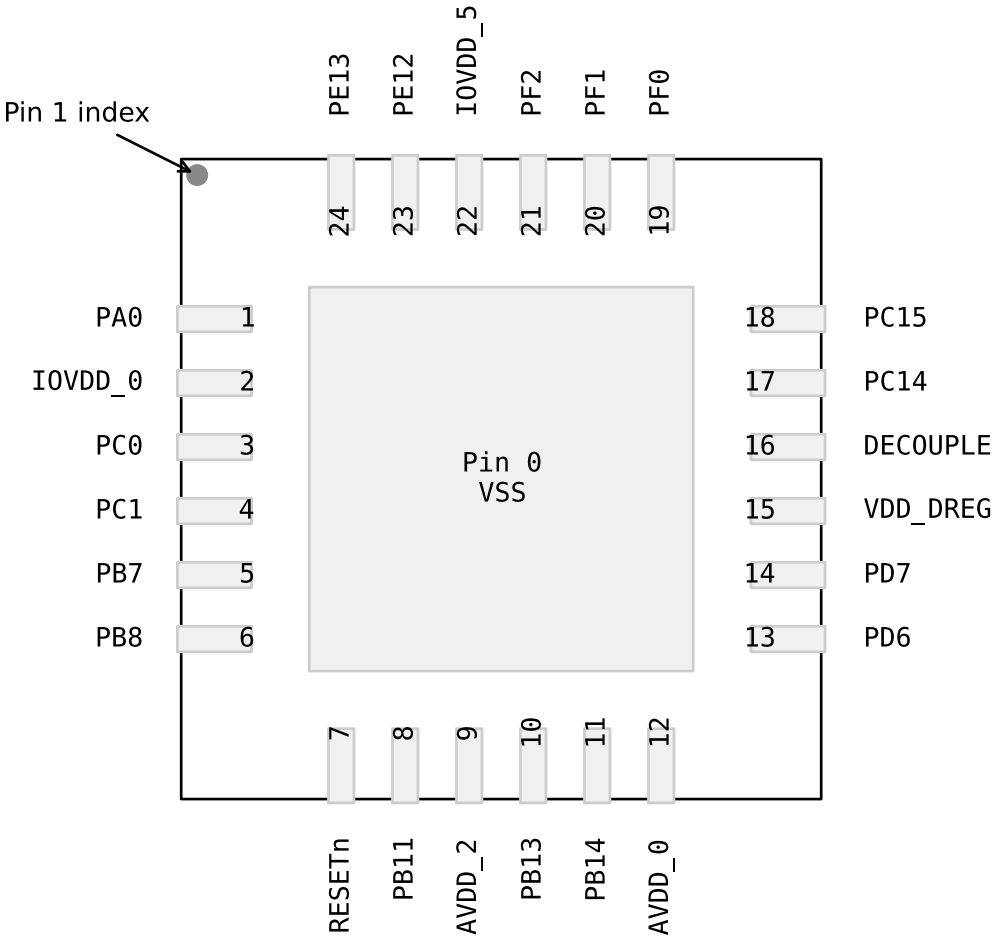


Figure 5.2. EFM32HG110 Pinout (top view, not to scale)

Table 5.4. Device Pinout

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
0	VSS	Ground.			
1	PA0		TIM0_CC1 #6 TIM0_CC0 #0/1/4 PCNT0_S0IN #4	US1_RX #4 LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 PRS_CH3 #3 GPIO_EM4WU0
2	IOVDD_0	Digital IO power supply 0.			

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
3	PC0	ACMP0_CH0	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5/6 US1_TX #0 US1_CS #5 I2C0_SDA #4	PRS_CH2 #0
4	PC1	ACMP0_CH1	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5/6 US1_TX #5 US1_RX #0 I2C0_SCL #4	PRS_CH3 #0
5	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
6	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
7	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
8	PB11	IDAC0_OUT	TIM1_CC2 #3 PCNT0_S1IN #4	US1_CLK #4	CMU_CLK1 #3 ACMP0_O #3
9	AVDD_2	Analog power supply 2.			
10	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
11	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
12	AVDD_0	Analog power supply 0.			
13	PD6	ADC_CH6	TIM1_CC0 #4 PCNT0_S0IN #3	US1_RX #2/3 I2C0_SDA #1	ACMP_O #2
14	PD7	ADC_CH7	TIM1_CC1 #4 PCNT0_S1IN #3	US1_TX #2/3 I2C0_SCL #1	CMU_CLK0 #2
15	VDD_DREG	Power supply for on-chip voltage regulator.			
16	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
17	PC14		TIM0_CDTI1 #1/6 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 US1_CS #3/4 LEU0_TX #5	PRS_CH0 #2
18	PC15		TIM0_CDTI2 #1/6 TIM1_CC2 #0	US0_CLK #3 US1_CLK #3 LEU0_RX #5	PRS_CH1 #2

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
19	PF0		TIM0_CC0 #5	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0 BOOT_TX
20	PF1		TIM0_CC1 #5	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0 GPIO_EM4WU3 BOOT_RX
21	PF2		TIM0_CC2 #5/6 TIM2_CC0 #3	US1_TX #4 LEU0_TX #4	CMU_CLK0 #3 PRS_CH0 #3 GPIO_EM4WU4
22	IOVDD_5	Digital IO power supply 5.			
23	PE12	ADC0_CH0	TIM1_CC2 #1 TIM2_CC1 #3	US0_RX #3 US0_CLK #0/6 I2C0_SDA #6	CMU_CLK1 #2 PRS_CH1 #3
24	PE13	ADC0_CH1	TIM2_CC2 #3	US0_TX #3 US0_CS #0/6 I2C0_SCL #6	ACMP0_O #0 PRS_CH2 #3 GPIO_EM4WU5

5.2.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.5. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_O	PE13		PD6	PB11				Analog comparator ACMP0, digital output.
ADC0_CH0	PE12							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PE13							Analog to digital converter ADC0, input channel number 1.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	P7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0			PD7	PF2				Clock Management Unit, clock output number 0.
CMU_CLK1			PE12	PB11				Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL		PD7			PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6			PC0	PF0	PE12	I2C0 Serial Data input / output.
IDAC0_OUT	PB11							IDAC0 output.
LEU0_RX		PB14		PF1	PA0	PC15		LEUART0 Receive input.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LEU0_TX		PB13		PF0	PF2	PC14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN			PC0	PD6	PA0			Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1	PD7	PB11			Pulse Counter PCNT0 input number 1.
PRS_CH0	PA0		PC14	PF2				Peripheral Reflex System PRS, channel 0.
PRS_CH1			PC15	PE12				Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0			PE13				Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1			PA0				Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1					PC0	PF1	PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2					PC1	PF2	PF2	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI1		PC14					PC14	Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2		PC15					PC15	Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0				PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14			PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11				Timer 1 Capture Compare input / output channel 2.
TIM2_CC0				PF2				Timer 2 Capture Compare input / output channel 0.
TIM2_CC1				PE12				Timer 2 Capture Compare input / output channel 1.
TIM2_CC2				PE13				Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12			PC15	PB13	PB13	PE12	USART0 clock input / output.
US0_CS	PE13			PC14	PB14	PB14	PE13	USART0 chip select input / output.
US0_RX				PE12	PB8	PC1	PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX				PE13	PB7	PC0	PC0	USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7		PF0	PC15	PB11			USART1 clock input / output.
US1_CS	PB8		PF1	PC14	PC14	PC0		USART1 chip select input / output.
US1_RX	PC1		PD6	PD6	PA0			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
US1_TX	PC0		PD7	PD7	PF2	PC1		USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).

5.2.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32HG110 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.6. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	PA0
Port B	-	PB14	PB13	-	PB11	-	-	PB8	PB7	-	-	-	-	-	-	-
Port C	PC15	PC14	-	-	-	-	-	-	-	-	-	-	-	-	PC1	PC0
Port D	-	-	-	-	-	-	-	-	PD7	PD6	-	-	-	-	-	-
Port E	-	-	PE13	PE12	-	-	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	-	-	-	PF2	PF1	PF0

5.3 EFM32HG210 (QFN32)

5.3.1 Pinout

The EFM32HG210 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

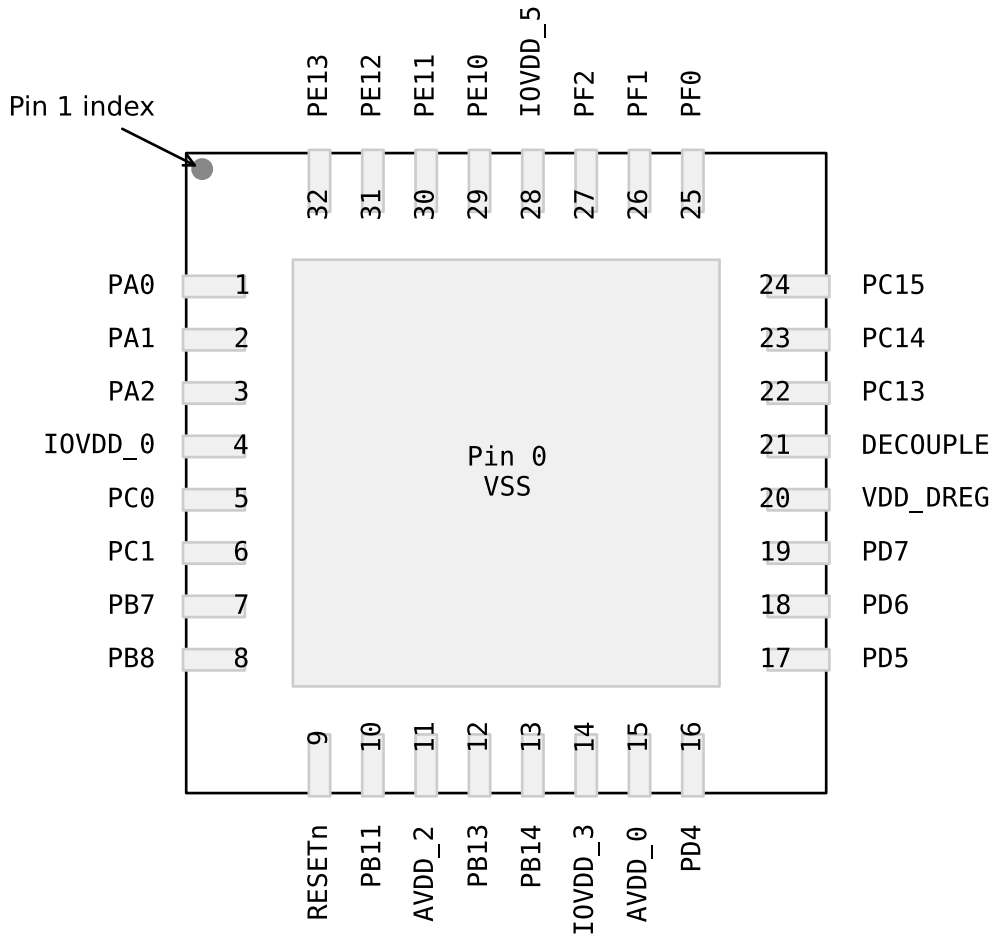


Figure 5.3. EFM32HG210 Pinout (top view, not to scale)

Table 5.7. Device Pinout

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
0	VSS	Ground.			
1	PA0		TIM0_CC1 #6 TIM0_CC0 #0/1/4 PCNT0_S0IN #4	US1_RX #4 LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 PRS_CH3 #3 GPIO_EM4WU0

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
2	PA1		TIM0_CC0 #6 TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
3	PA2		TIM0_CC2 #0/1		CMU_CLK0 #0
4	IOVDD_0	Digital IO power supply 0.			
5	PC0	ACMP0_CH0	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5/6 US1_TX #0 US1_CS #5 I2C0_SDA #4	PRS_CH2 #0
6	PC1	ACMP0_CH1	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5/6 US1_TX #5 US1_RX #0 I2C0_SCL #4	PRS_CH3 #0
7	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
8	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
9	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
10	PB11	IDAC0_OUT	TIM1_CC2 #3 PCNT0_S1IN #4	US1_CLK #4	CMU_CLK1 #3 ACMP0_O #3
11	AVDD_2	Analog power supply 2.			
12	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
13	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
14	IOVDD_3	Digital IO power supply 3.			
15	AVDD_0	Analog power supply 0.			
16	PD4	ADC0_CH4		LEU0_TX #0	
17	PD5	ADC0_CH5		LEU0_RX #0	
18	PD6	ADC0_CH6	TIM1_CC0 #4 PCNT0_S0IN #3	US1_RX #2/3 I2C0_SDA #1	ACMP0_O #2
19	PD7	ADC0_CH7	TIM1_CC1 #4 PCNT0_S1IN #3	US1_TX #2/3 I2C0_SCL #1	CMU_CLK0 #2
20	VDD_DREG	Power supply for on-chip voltage regulator.			
21	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
22	PC13		TIM0_CDTI0 #1/6 TIM1_CC0 #0 TIM1_CC2 #4 PCNT0_S0IN #0		
23	PC14		TIM0_CDTI1 #1/6 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 US1_CS #3/4 LEU0_TX #5	PRS_CH0 #2
24	PC15		TIM0_CDTI2 #1/6 TIM1_CC2 #0	US0_CLK #3 US1_CLK #3 LEU0_RX #5	PRS_CH1 #2
25	PF0		TIM0_CC0 #5	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0 BOOT_TX
26	PF1		TIM0_CC1 #5	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0 GPIO_EM4WU3 BOOT_RX
27	PF2		TIM0_CC2 #5/6 TIM2_CC0 #3	US1_TX #4 LEU0_TX #4	CMU_CLK0 #3 PRS_CH0 #3 GPIO_EM4WU4
28	IOVDD_5	Digital IO power supply 5.			
29	PE10		TIM1_CC0 #1	US0_TX #0	PRS_CH2 #2
30	PE11		TIM1_CC1 #1	US0_RX #0	PRS_CH3 #2
31	PE12	ADC0_CH0	TIM1_CC2 #1 TIM2_CC1 #3	US0_RX #3 US0_CLK #0/6 I2C0_SDA #6	CMU_CLK1 #2 PRS_CH1 #3
32	PE13	ADC0_CH1	TIM2_CC2 #3	US0_TX #3 US0_CS #0/6 I2C0_SCL #6	ACMP0_O #0 PRS_CH2 #3 GPIO_EM4WU5

5.3.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.8. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_O	PE13		PD6	PB11				Analog comparator ACMP0, digital output.
ADC0_CH0	PE12							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PE13							Analog to digital converter ADC0, input channel number 1.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0	PA2		PD7	PF2				Clock Management Unit, clock output number 0.
CMU_CLK1	PA1		PE12	PB11				Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7			PC1	PF1	PE13	I2C0 Serial Clock Line input / output.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
I2C0_SDA	PA0	PD6			PC0	PF0	PE12	I2C0 Serial Data input / output.
IDAC0_OUT	PB11							IDAC0 output.
LEU0_RX	PD5	PB14		PF1	PA0	PC15		LEUART0 Receive input.
LEU0_TX	PD4	PB13		PF0	PF2	PC14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13		PC0	PD6	PA0			Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1	PD7	PB11			Pulse Counter PCNT0 input number 1.
PRS_CH0	PA0		PC14	PF2				Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1		PC15	PE12				Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0		PE10	PE13				Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1		PE11	PA0				Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0	PA1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1			PC0	PF1	PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2			PC1	PF2	PF2	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0		PC13					PC13	Timer 0 Complimentary Dead Time Insertion channel 0.
TIM0_CDTI1		PC14					PC14	Timer 0 Complimentary Dead Time Insertion channel 1.
TIM0_CDTI2		PC15					PC15	Timer 0 Complimentary Dead Time Insertion channel 2.
TIM1_CC0	PC13	PE10		PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11		PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11	PC13			Timer 1 Capture Compare input / output channel 2.
TIM2_CC0				PF2				Timer 2 Capture Compare input / output channel 0.
TIM2_CC1				PE12				Timer 2 Capture Compare input / output channel 1.
TIM2_CC2				PE13				Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12			PC15	PB13	PB13	PE12	USART0 clock input / output.
US0_CS	PE13			PC14	PB14	PB14	PE13	USART0 chip select input / output.
US0_RX	PE11			PE12	PB8	PC1	PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10			PE13	PB7	PC0	PC0	USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
US1_CLK	PB7		PF0	PC15	PB11			USART1 clock input / output.
US1_CS	PB8		PF1	PC14	PC14	PC0		USART1 chip select input / output.
US1_RX	PC1		PD6	PD6	PA0			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0		PD7	PD7	PF2	PC1		USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).

5.3.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32HG210 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.9. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	-	-	-	PA2	PA1	PA0
Port B	-	PB14	PB13	-	PB11	-	-	PB8	PB7	-	-	-	-	-	-	-
Port C	PC15	PC14	PC13	-	-	-	-	-	-	-	-	-	-	-	PC1	PC0
Port D	-	-	-	-	-	-	-	-	PD7	PD6	PD5	PD4	-	-	-	-
Port E	-	-	PE13	PE12	PE11	PE10	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	-	-	-	PF2	PF1	PF0

5.4 EFM32HG222 (TQFP48)

5.4.1 Pinout

The EFM32HG222 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

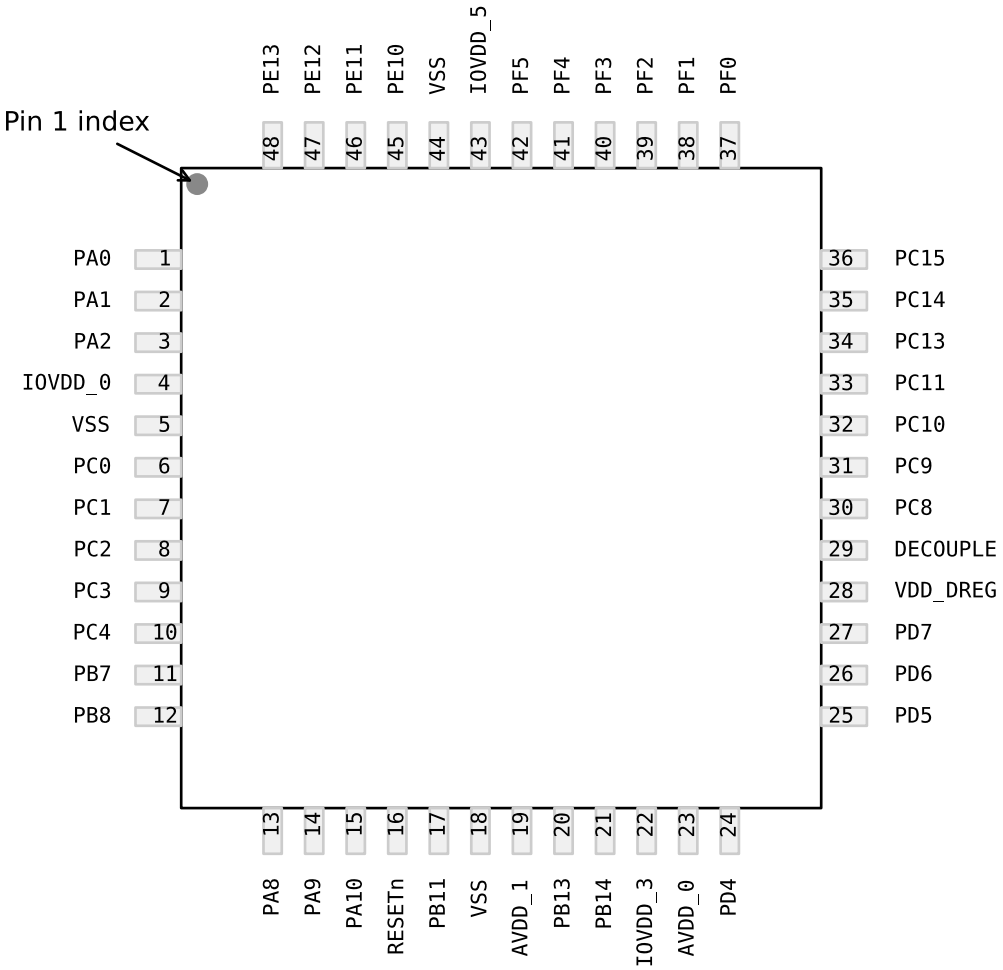


Figure 5.4. EFM32HG222 Pinout (top view, not to scale)

Table 5.10. Device Pinout

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
1	PA0		TIM0_CC1 #6 TIM0_CC0 #0/1/4 PCNT0_S0IN #4	US1_RX #4 LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 PRS_CH3 #3 GPIO_EM4WU0
2	PA1		TIM0_CC0 #6 TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
3	PA2		TIM0_CC2 #0/1		CMU_CLK0 #0
4	IOVDD_0	Digital IO power supply 0.			
5	VSS	Ground.			
6	PC0	ACMP0_CH0	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5/6 US1_TX #0 US1_CS #5 I2C0_SDA #4	PRS_CH2 #0
7	PC1	ACMP0_CH1	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5/6 US1_TX #5 US1_RX #0 I2C0_SCL #4	PRS_CH3 #0
8	PC2	ACMP0_CH2	TIM0_CDTI0 #4	US1_RX #5	
9	PC3	ACMP0_CH3	TIM0_CDTI1 #4	US1_CLK #5	
10	PC4	ACMP0_CH4	TIM0_CDTI2 #4		GPIO_EM4WU6
11	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
12	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
13	PA8		TIM2_CC0 #0		
14	PA9		TIM2_CC1 #0		
15	PA10		TIM2_CC2 #0		
16	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
17	PB11	IDAC0_OUT	TIM1_CC2 #3 PCNT0_S1IN #4	US1_CLK #4	CMU_CLK1 #3 ACMP0_O #3
18	VSS	Ground.			
19	AVDD_1	Analog power supply 1.			
20	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
21	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
22	IOVDD_3	Digital IO power supply 3.			
23	AVDD_0	Analog power supply 0.			
24	PD4	ADC0_CH4		LEU0_TX #0	
25	PD5	ADC0_CH5		LEU0_RX #0	

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
26	PD6	ADC0_CH6	TIM1_CC0 #4 PCNT0_S0IN #3	US1_RX #2/3 I2C0_SDA #1	ACMP0_O #2
27	PD7	ADC0_CH7	TIM1_CC1 #4 PCNT0_S1IN #3	US1_TX #2/3 I2C0_SCL #1	CMU_CLK0 #2
28	VDD_DREG	Power supply for on-chip voltage regulator.			
29	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
30	PC8		TIM2_CC0 #2	US0_CS #2	
31	PC9		TIM2_CC1 #2	US0_CLK #2	GPIO_EM4WU2
32	PC10		TIM2_CC2 #2	US0_RX #2	
33	PC11			US0_TX #2	
34	PC13		TIM0_CDTI0 #1/6 TIM1_CC0 #0 TIM1_CC2 #4 PCNT0_S0IN #0		
35	PC14		TIM0_CDTI1 #1/6 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 US1_CS #3/4 LEU0_TX #5	PRS_CH0 #2
36	PC15		TIM0_CDTI2 #1/6 TIM1_CC2 #0	US0_CLK #3 US1_CLK #3 LEU0_RX #5	PRS_CH1 #2
37	PF0		TIM0_CC0 #5	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0 BOOT_TX
38	PF1		TIM0_CC1 #5	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0 GPIO_EM4WU3 BOOT_RX
39	PF2		TIM0_CC2 #5/6 TIM2_CC0 #3	US1_TX #4 LEU0_TX #4	CMU_CLK0 #3 PRS_CH0 #3 GPIO_EM4WU4
40	PF3		TIM0_CDTI0 #5		PRS_CH0 #1
41	PF4		TIM0_CDTI1 #5		PRS_CH1 #1
42	PF5		TIM0_CDTI2 #5		PRS_CH2 #1
43	IOVDD_5	Digital IO power supply 5.			
44	VSS	Ground.			
45	PE10		TIM1_CC0 #1	US0_TX #0	PRS_CH2 #2

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
46	PE11		TIM1_CC1 #1	US0_RX #0	PRS_CH3 #2
47	PE12	ADC0_CH0	TIM1_CC2 #1 TIM2_CC1 #3	US0_RX #3 US0_CLK #0/6 I2C0_SDA #6	CMU_CLK1 #2 PRS_CH1 #3
48	PE13	ADC0_CH1	TIM2_CC2 #3	US0_TX #3 US0_CS #0/6 I2C0_SCL #6	ACMP0_O #0 PRS_CH2 #3 GPIO_EM4WU5

5.4.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.11. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2							Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3							Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4							Analog comparator ACMP0, channel 4.
ACMP0_O	PE13		PD6	PB11				Analog comparator ACMP0, digital output.
ADC0_CH0	PE12							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PE13							Analog to digital converter ADC0, input channel number 1.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0	PA2		PD7	PF2				Clock Management Unit, clock output number 0.
CMU_CLK1	PA1		PE12	PB11				Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
GPIO_EM4WU6	PC4							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7			PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6			PC0	PF0	PE12	I2C0 Serial Data input / output.
IDAC0_OUT	PB11							IDAC0 output.
LEU0_RX	PD5	PB14		PF1	PA0	PC15		LEUART0 Receive input.
LEU0_TX	PD4	PB13		PF0	PF2	PC14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13		PC0	PD6	PA0			Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1	PD7	PB11			Pulse Counter PCNT0 input number 1.
PRS_CH0	PA0	PF3	PC14	PF2				Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1	PF4	PC15	PE12				Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0	PF5	PE10	PE13				Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1		PE11	PA0				Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0	PA1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1			PC0	PF1	PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2			PC1	PF2	PF2	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0		PC13			PC2	PF3	PC13	Timer 0 Complimentary Dead Time Insertion channel 0.
TIM0_CDTI1		PC14			PC3	PF4	PC14	Timer 0 Complimentary Dead Time Insertion channel 1.
TIM0_CDTI2		PC15			PC4	PF5	PC15	Timer 0 Complimentary Dead Time Insertion channel 2.
TIM1_CC0	PC13	PE10		PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11		PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11	PC13			Timer 1 Capture Compare input / output channel 2.
TIM2_CC0	PA8		PC8	PF2				Timer 2 Capture Compare input / output channel 0.
TIM2_CC1	PA9		PC9	PE12				Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10		PC10	PE13				Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12		PC9	PC15	PB13	PB13	PE12	USART0 clock input / output.
US0_CS	PE13		PC8	PC14	PB14	PB14	PE13	USART0 chip select input / output.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
US0_RX	PE11		PC10	PE12	PB8	PC1	PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10		PC11	PE13	PB7	PC0	PC0	USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7		PF0	PC15	PB11	PC3		USART1 clock input / output.
US1_CS	PB8		PF1	PC14	PC14	PC0		USART1 chip select input / output.
US1_RX	PC1		PD6	PD6	PA0	PC2		USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0		PD7	PD7	PF2	PC1		USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).

5.4.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32HG222 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.12. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	PA10	PA9	PA8	-	-	-	-	-	PA2	PA1	PA0
Port B	-	PB14	PB13	-	PB11	-	-	PB8	PB7	-	-	-	-	-	-	-
Port C	PC15	PC14	PC13	-	PC11	PC10	PC9	PC8	-	-	-	PC4	PC3	PC2	PC1	PC0
Port D	-	-	-	-	-	-	-	-	PD7	PD6	PD5	PD4	-	-	-	-
Port E	-	-	PE13	PE12	PE11	PE10	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	PF5	PF4	PF3	PF2	PF1	PF0

5.5 EFM32HG308 (QFN24)

5.5.1 Pinout

The EFM32HG308 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

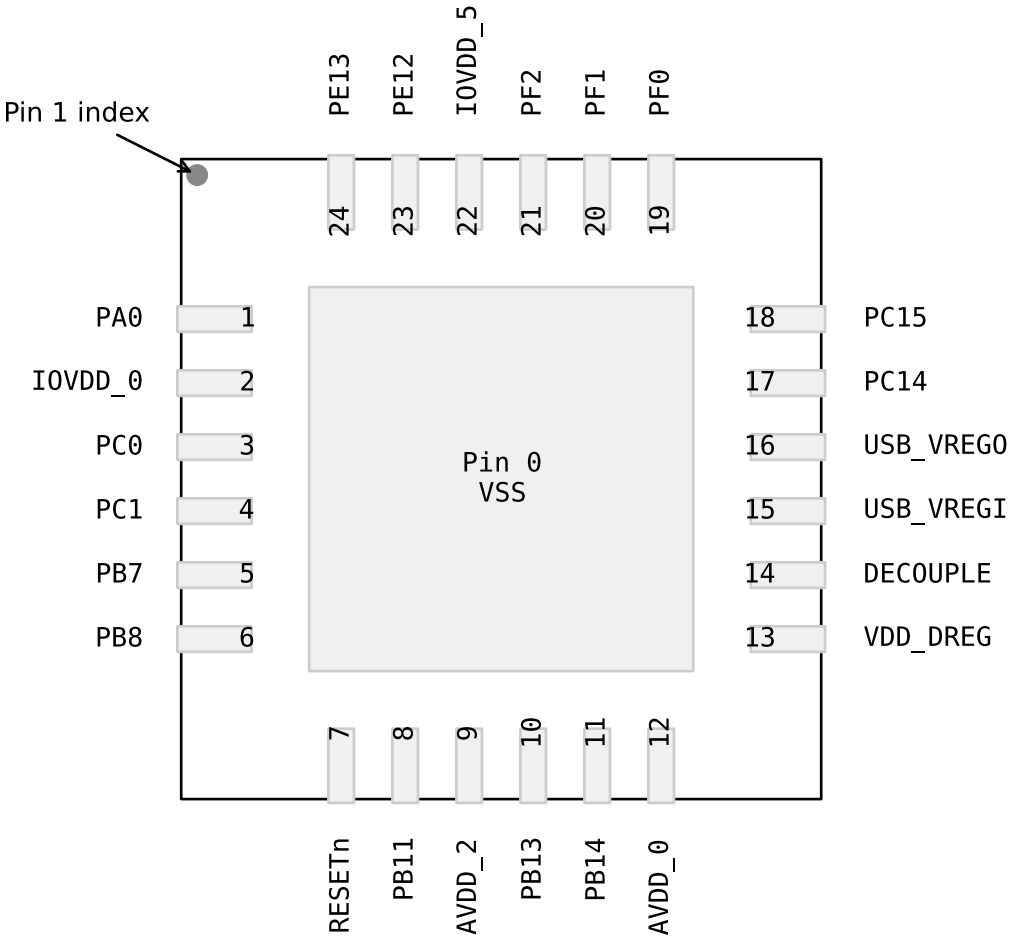


Figure 5.5. EFM32HG308 Pinout (top view, not to scale)

Table 5.13. Device Pinout

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
0	VSS	Ground.			
1	PA0		TIM0_CC1 #6 TIM0_CC0 #0/1/4 PCNT0_S0IN #4	USB_DMPU #0 US1_RX #4 LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 PRS_CH3 #3 GPIO_EM4WU0

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
2	IOVDD_0	Digital IO power supply 0.			
3	PC0	ACMP0_CH0	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5/6 US1_TX #0 US1_CS #5 I2C0_SDA #4	PRS_CH2 #0
4	PC1	ACMP0_CH1	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5/6 US1_TX #5 US1_RX #0 I2C0_SCL #4	PRS_CH3 #0
5	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
6	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
7	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
8	PB11		TIM1_CC2 #3 PCNT0_S1IN #4	US1_CLK #4	CMU_CLK1 #3 ACMP0_O #3
9	AVDD_2	Analog power supply 2.			
10	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
11	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
12	AVDD_0	Analog power supply 0.			
13	VDD_DREG	Power supply for on-chip voltage regulator.			
14	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
15	USB_VREGI				
16	USB_VREGO				
17	PC14		TIM0_CDTI1 #1/6 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 US1_CS #3/4 LEU0_TX #5 USB_DM	PRS_CH0 #2
18	PC15		TIM0_CDTI2 #1/6 TIM1_CC2 #0	US0_CLK #3 US1_CLK #3 LEU0_RX #5 USB_DP	PRS_CH1 #2

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
19	PF0		TIM0_CC0 #5	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0 BOOT_TX
20	PF1		TIM0_CC1 #5	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0 GPIO_EM4WU3 BOOT_RX
21	PF2		TIM0_CC2 #5/6 TIM2_CC0 #3	US1_TX #4 LEU0_TX #4	CMU_CLK0 #3 PRS_CH0 #3 GPIO_EM4WU4
22	IOVDD_5	Digital IO power supply 5.			
23	PE12		TIM1_CC2 #1 TIM2_CC1 #3	US0_RX #3 US0_CLK #0/6 I2C0_SDA #6	CMU_CLK1 #2 PRS_CH1 #3
24	PE13		TIM2_CC2 #3	US0_TX #3 US0_CS #0/6 I2C0_SCL #6	ACMP0_O #0 PRS_CH2 #3 GPIO_EM4WU5

5.5.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.14. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_O	PE13			PB11				Analog comparator ACMP0, digital output.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0				PF2				Clock Management Unit, clock output number 0.
CMU_CLK1			PE12	PB11				Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL					PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0				PC0	PF0	PE12	I2C0 Serial Data input / output.
LEU0_RX		PB14		PF1	PA0	PC15		LEUART0 Receive input.
LEU0_TX		PB13		PF0	PF2	PC14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN			PC0		PA0			Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1		PB11			Pulse Counter PCNT0 input number 1.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
PRS_CH0	PA0		PC14	PF2				Peripheral Reflex System PRS, channel 0.
PRS_CH1			PC15	PE12				Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0			PE13				Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1			PA0				Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1					PC0	PF1	PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2					PC1	PF2	PF2	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI1		PC14					PC14	Timer 0 Complimentary Dead Time Insertion channel 1.
TIM0_CDTI2		PC15					PC15	Timer 0 Complimentary Dead Time Insertion channel 2.
TIM1_CC0				PB7				Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14			PB8				Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11				Timer 1 Capture Compare input / output channel 2.
TIM2_CC0				PF2				Timer 2 Capture Compare input / output channel 0.
TIM2_CC1				PE12				Timer 2 Capture Compare input / output channel 1.
TIM2_CC2				PE13				Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12			PC15	PB13	PB13	PE12	USART0 clock input / output.
US0_CS	PE13			PC14	PB14	PB14	PE13	USART0 chip select input / output.
US0_RX				PE12	PB8	PC1	PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX				PE13	PB7	PC0	PC0	USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7		PF0	PC15	PB11			USART1 clock input / output.
US1_CS	PB8		PF1	PC14	PC14	PC0		USART1 chip select input / output.
US1_RX	PC1				PA0			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0				PF2	PC1		USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PC14							USB D- pin.
USB_DMPU	PA0							USB D- Pullup control.
USB_DP	PC15							USB D+ pin.
USB_VREGI	USB_VREGI							USB Input to internal 3.3 V regulator

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
USB_VREGO	USB_VREGO							USB Decoupling for internal 3.3 V USB regulator and regulator output

5.5.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32HG309 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.15. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	PA0
Port B	-	PB14	PB13	-	PB11	-	-	PB8	PB7	-	-	-	-	-	-	-
Port C	PC15	PC14	-	-	-	-	-	-	-	-	-	-	-	-	PC1	PC0
Port D	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
Port E	-	-	PE13	PE12	-	-	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	-	-	-	PF2	PF1	PF0

5.6 EFM32HG309 (QFN24)

5.6.1 Pinout

The EFM32HG309 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

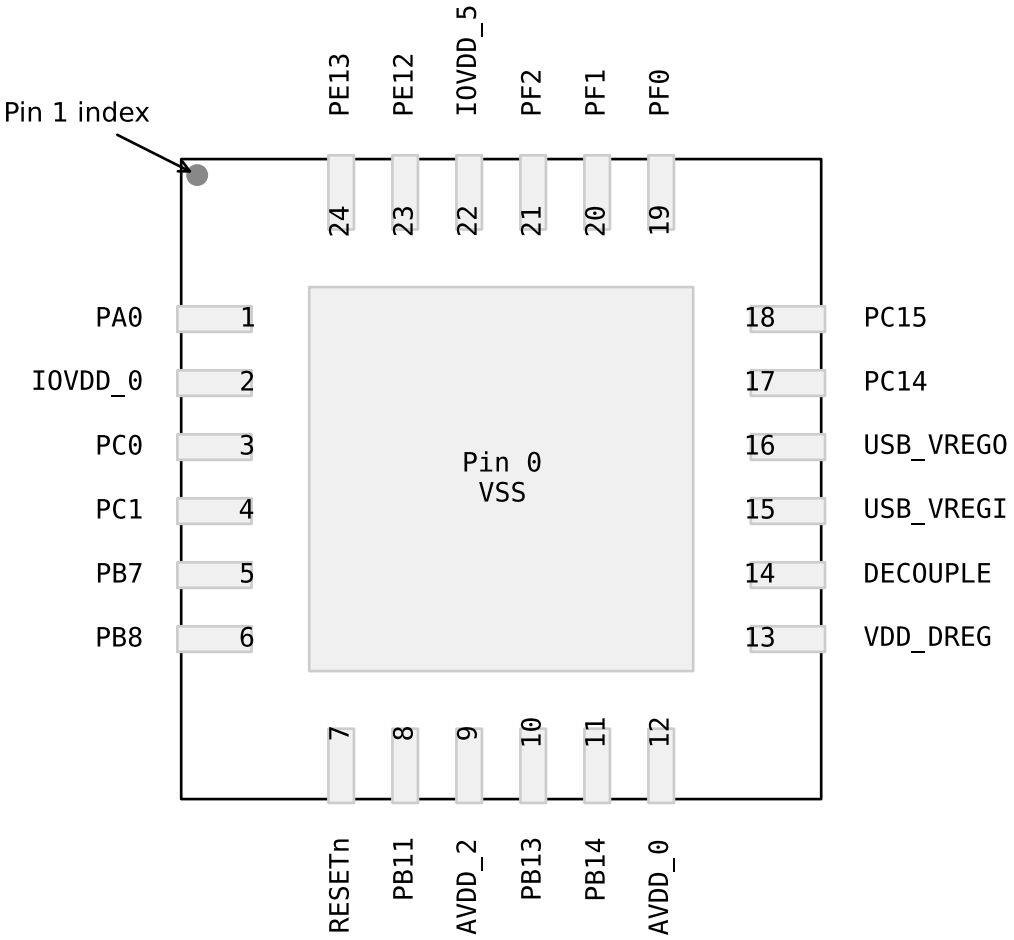


Figure 5.6. EFM32HG309 Pinout (top view, not to scale)

Table 5.16. Device Pinout

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
0	VSS	Ground.			
1	PA0		TIM0_CC1 #6 TIM0_CC0 #0/1/4 PCNT0_S0IN #4	USB_DMPU #0 US1_RX #4 LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 PRS_CH3 #3 GPIO_EM4WU0

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
2	IOVDD_0	Digital IO power supply 0.			
3	PC0	ACMP0_CH0	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5/6 US1_TX #0 US1_CS #5 I2C0_SDA #4	PRS_CH2 #0
4	PC1	ACMP0_CH1	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5/6 US1_TX #5 US1_RX #0 I2C0_SCL #4	PRS_CH3 #0
5	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
6	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
7	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
8	PB11	IDAC0_OUT	TIM1_CC2 #3 PCNT0_S1IN #4	US1_CLK #4	CMU_CLK1 #3 ACMP0_O #3
9	AVDD_2	Analog power supply 2.			
10	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
11	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
12	AVDD_0	Analog power supply 0.			
13	VDD_DREG	Power supply for on-chip voltage regulator.			
14	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
15	USB_VREGI				
16	USB_VREGO				
17	PC14		TIM0_CDTI1 #1/6 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 US1_CS #3/4 LEU0_TX #5 USB_DM	PRS_CH0 #2
18	PC15		TIM0_CDTI2 #1/6 TIM1_CC2 #0	US0_CLK #3 US1_CLK #3 LEU0_RX #5 USB_DP	PRS_CH1 #2

QFN24 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
19	PF0		TIM0_CC0 #5	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0 BOOT_TX
20	PF1		TIM0_CC1 #5	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0 GPIO_EM4WU3 BOOT_RX
21	PF2		TIM0_CC2 #5/6 TIM2_CC0 #3	US1_TX #4 LEU0_TX #4	CMU_CLK0 #3 PRS_CH0 #3 GPIO_EM4WU4
22	IOVDD_5	Digital IO power supply 5.			
23	PE12	ADC0_CH0	TIM1_CC2 #1 TIM2_CC1 #3	US0_RX #3 US0_CLK #0/6 I2C0_SDA #6	CMU_CLK1 #2 PRS_CH1 #3
24	PE13	ADC0_CH1	TIM2_CC2 #3	US0_TX #3 US0_CS #0/6 I2C0_SCL #6	ACMP0_O #0 PRS_CH2 #3 GPIO_EM4WU5

5.6.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.17. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_O	PE13			PB11				Analog comparator ACMP0, digital output.
ADC0_CH0	PE12							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PE13							Analog to digital converter ADC0, input channel number 1.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0				PF2				Clock Management Unit, clock output number 0.
CMU_CLK1			PE12	PB11				Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL					PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0				PC0	PF0	PE12	I2C0 Serial Data input / output.
IDAC0_OUT	PB11							IDAC0 output.
LEU0_RX		PB14		PF1	PA0	PC15		LEUART0 Receive input.
LEU0_TX		PB13		PF0	PF2	PC14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN			PC0		PA0			Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1		PB11			Pulse Counter PCNT0 input number 1.
PRS_CH0	PA0		PC14	PF2				Peripheral Reflex System PRS, channel 0.
PRS_CH1			PC15	PE12				Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0			PE13				Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1			PA0				Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1					PC0	PF1	PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2					PC1	PF2	PF2	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI1		PC14					PC14	Timer 0 Complimentary Dead Time Insertion channel 1.
TIM0_CDTI2		PC15					PC15	Timer 0 Complimentary Dead Time Insertion channel 2.
TIM1_CC0				PB7				Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14			PB8				Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11				Timer 1 Capture Compare input / output channel 2.
TIM2_CC0				PF2				Timer 2 Capture Compare input / output channel 0.
TIM2_CC1				PE12				Timer 2 Capture Compare input / output channel 1.
TIM2_CC2				PE13				Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12			PC15	PB13	PB13	PE12	USART0 clock input / output.
US0_CS	PE13			PC14	PB14	PB14	PE13	USART0 chip select input / output.
US0_RX				PE12	PB8	PC1	PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX				PE13	PB7	PC0	PC0	USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7		PF0	PC15	PB11			USART1 clock input / output.
US1_CS	PB8		PF1	PC14	PC14	PC0		USART1 chip select input / output.
US1_RX	PC1				PA0			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0				PF2	PC1		USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PC14							USB D- pin.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
USB_DMPU	PA0							USB D- Pullup control.
USB_DP	PC15							USB D+ pin.
USB_VREGI	USB_VREGI							USB Input to internal 3.3 V regulator
USB_VREGO	USB_VREGO							USB Decoupling for internal 3.3 V USB regulator and regulator output

5.6.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32HG309 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.18. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	PA0
Port B	-	PB14	PB13	-	PB11	-	-	PB8	PB7	-	-	-	-	-	-	-
Port C	PC15	PC14	-	-	-	-	-	-	-	-	-	-	-	-	PC1	PC0
Port D	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
Port E	-	-	PE13	PE12	-	-	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	-	-	-	PF2	PF1	PF0

5.7 EFM32HG310 (QFN32)

5.7.1 Pinout

The EFM32HG310 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

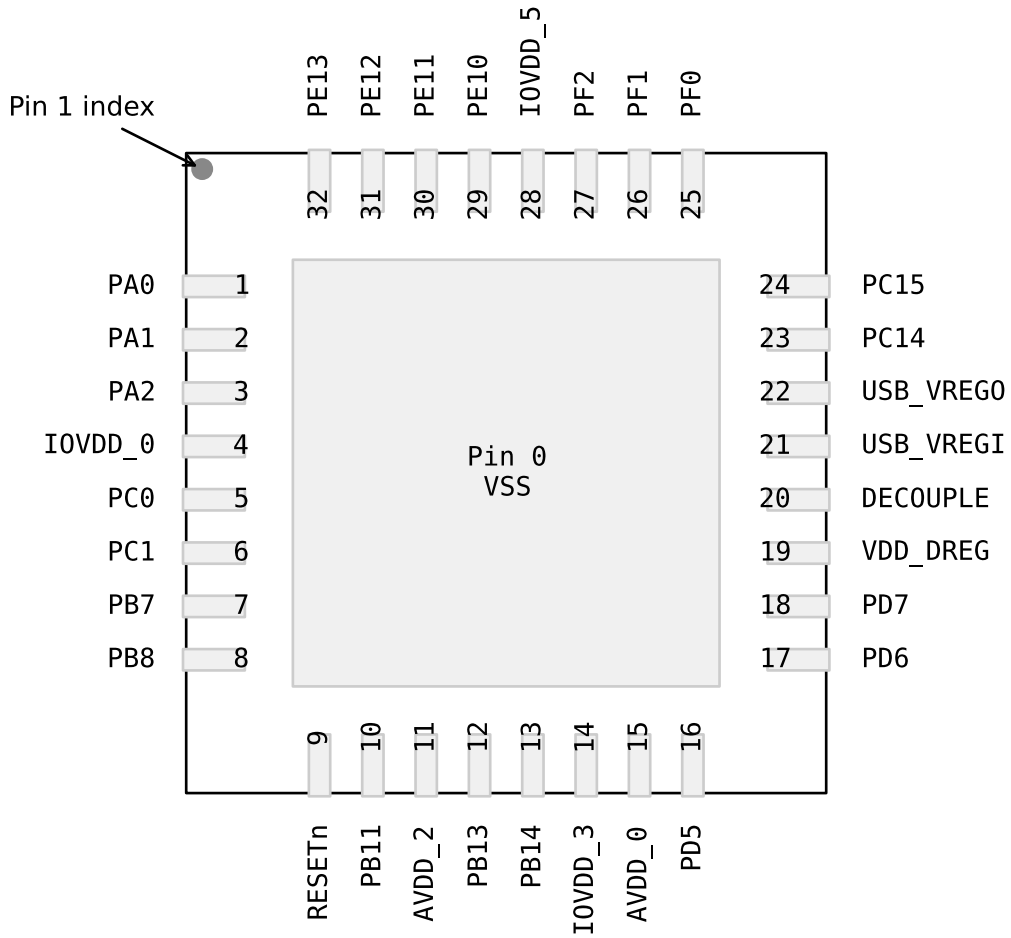


Figure 5.7. EFM32HG310 Pinout (top view, not to scale)

Table 5.19. Device Pinout

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
0	VSS	Ground.			
1	PA0		TIM0_CC1 #6 TIM0_CC0 #0/1/4 PCNT0_S0IN #4	USB_DMPU #0 US1_RX #4 LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 PRS_CH3 #3 GPIO_EM4WU0

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
2	PA1		TIM0_CC0 #6 TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
3	PA2		TIM0_CC2 #0/1		CMU_CLK0 #0
4	IOVDD_0	Digital IO power supply 0.			
5	PC0	ACMP0_CH0	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5/6 US1_TX #0 US1_CS #5 I2C0_SDA #4	PRS_CH2 #0
6	PC1	ACMP0_CH1	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5/6 US1_TX #5 US1_RX #0 I2C0_SCL #4	PRS_CH3 #0
7	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
8	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
9	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
10	PB11	IDAC0_OUT	TIM1_CC2 #3 PCNT0_S1IN #4	US1_CLK #4	CMU_CLK1 #3 ACMP0_O #3
11	AVDD_2	Analog power supply 2.			
12	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
13	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
14	IOVDD_3	Digital IO power supply 3.			
15	AVDD_0	Analog power supply 0.			
16	PD5	ADC0_CH5		LEU0_RX #0	
17	PD6	ADC0_CH6	TIM1_CC0 #4 PCNT0_S0IN #3	US1_RX #2/3 I2C0_SDA #1	ACMP0_O #2
18	PD7	ADC0_CH7	TIM1_CC1 #4 PCNT0_S1IN #3	US1_TX #2/3 I2C0_SCL #1	CMU_CLK0 #2
19	VDD_DREG	Power supply for on-chip voltage regulator.			
20	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
21	USB_VREGI				
22	USB_VREGO				

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
23	PC14		TIM0_CDTI1 #1/6 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 US1_CS #3/4 LEU0_TX #5 USB_DM	PRS_CH0 #2
24	PC15		TIM0_CDTI2 #1/6 TIM1_CC2 #0	US0_CLK #3 US1_CLK #3 LEU0_RX #5 USB_DP	PRS_CH1 #2
25	PF0		TIM0_CC0 #5	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0 BOOT_TX
26	PF1		TIM0_CC1 #5	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0 GPIO_EM4WU3 BOOT_RX
27	PF2		TIM0_CC2 #5/6 TIM2_CC0 #3	US1_TX #4 LEU0_TX #4	CMU_CLK0 #3 PRS_CH0 #3 GPIO_EM4WU4
28	IOVDD_5	Digital IO power supply 5.			
29	PE10		TIM1_CC0 #1	US0_TX #0	PRS_CH2 #2
30	PE11		TIM1_CC1 #1	US0_RX #0	PRS_CH3 #2
31	PE12	ADC0_CH0	TIM1_CC2 #1 TIM2_CC1 #3	US0_RX #3 US0_CLK #0/6 I2C0_SDA #6	CMU_CLK1 #2 PRS_CH1 #3
32	PE13	ADC0_CH1	TIM2_CC2 #3	US0_TX #3 US0_CS #0/6 I2C0_SCL #6	ACMP0_O #0 PRS_CH2 #3 GPIO_EM4WU5

5.7.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.20. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_O	PE13		PD6	PB11				Analog comparator ACMP0, digital output.
ADC0_CH0	PE12							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PE13							Analog to digital converter ADC0, input channel number 1.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0	PA2		PD7	PF2				Clock Management Unit, clock output number 0.
CMU_CLK1	PA1		PE12	PB11				Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7			PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6			PC0	PF0	PE12	I2C0 Serial Data input / output.
IDAC0_OUT	PB11							IDAC0 output.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LEU0_RX	PD5	PB14		PF1	PA0	PC15		LEUART0 Receive input.
LEU0_TX		PB13		PF0	PF2	PC14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN			PC0	PD6	PA0			Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1	PD7	PB11			Pulse Counter PCNT0 input number 1.
PRS_CH0	PA0		PC14	PF2				Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1		PC15	PE12				Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0		PE10	PE13				Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1		PE11	PA0				Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0	PA1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1			PC0	PF1	PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2			PC1	PF2	PF2	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI1		PC14					PC14	Timer 0 Complimentary Dead Time Insertion channel 1.
TIM0_CDTI2		PC15					PC15	Timer 0 Complimentary Dead Time Insertion channel 2.
TIM1_CC0		PE10		PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11		PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11				Timer 1 Capture Compare input / output channel 2.
TIM2_CC0				PF2				Timer 2 Capture Compare input / output channel 0.
TIM2_CC1				PE12				Timer 2 Capture Compare input / output channel 1.
TIM2_CC2				PE13				Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12			PC15	PB13	PB13	PE12	USART0 clock input / output.
US0_CS	PE13			PC14	PB14	PB14	PE13	USART0 chip select input / output.
US0_RX	PE11			PE12	PB8	PC1	PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10			PE13	PB7	PC0	PC0	USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7		PF0	PC15	PB11			USART1 clock input / output.
US1_CS	PB8		PF1	PC14	PC14	PC0		USART1 chip select input / output.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
US1_RX	PC1		PD6	PD6	PA0			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0		PD7	PD7	PF2	PC1		USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PC14							USB D- pin.
USB_DMPU	PA0							USB D- Pullup control.
USB_DP	PC15							USB D+ pin.
USB_VREGI	USB_VREGI							USB Input to internal 3.3 V regulator
USB_VREGO	USB_VREGO							USB Decoupling for internal 3.3 V USB regulator and regulator output

5.7.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32HG310 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.21. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	-	-	-	PA2	PA1	PA0
Port B	-	PB14	PB13	-	PB11	-	-	PB8	PB7	-	-	-	-	-	-	-
Port C	PC15	PC14	-	-	-	-	-	-	-	-	-	-	-	-	PC1	PC0
Port D	-	-	-	-	-	-	-	-	PD7	PD6	PD5	-	-	-	-	-
Port E	-	-	PE13	PE12	PE11	PE10	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	-	-	-	PF2	PF1	PF0

5.8 EFM32HG321 (TQFP48)

5.8.1 Pinout

The EFM32HG321 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

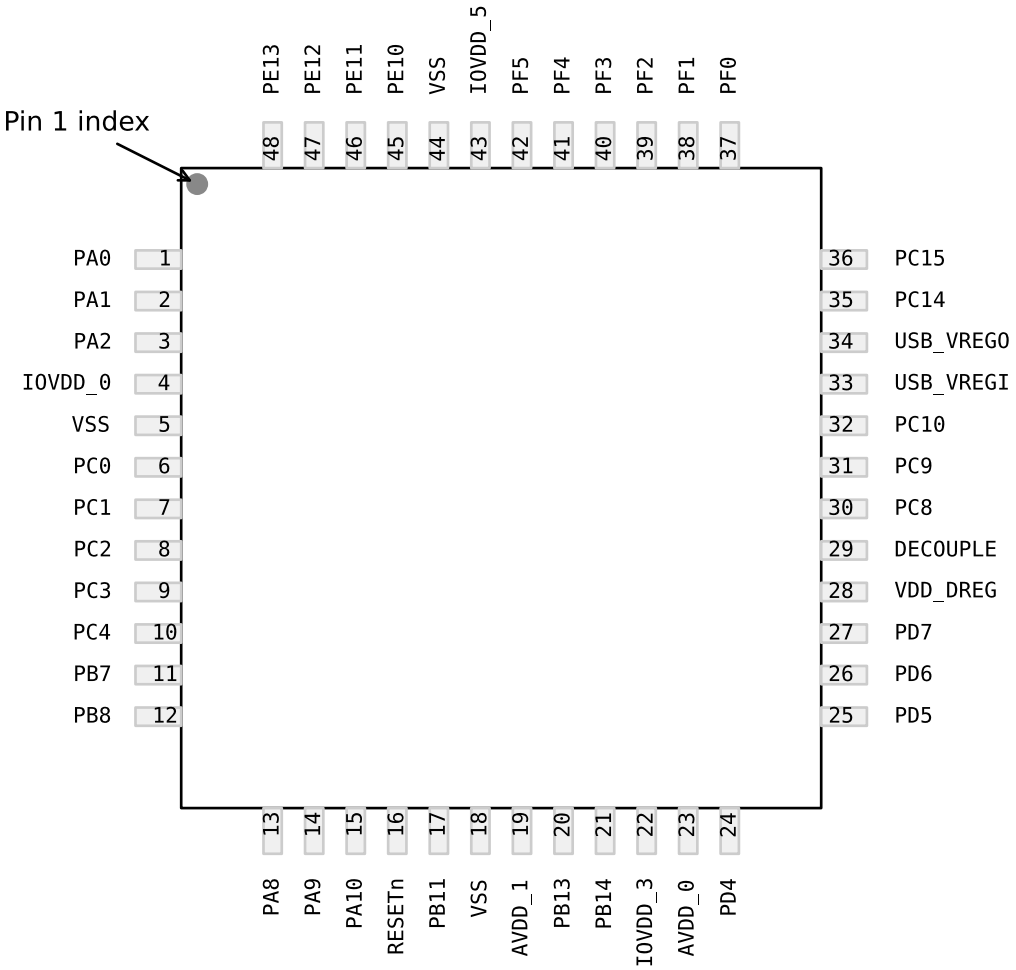


Figure 5.8. EFM32HG321 Pinout (top view, not to scale)

Table 5.22. Device Pinout

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	**Pin Name**	**Analog**	**Timers**	**Communication**	**Other**
1	PA0		TIM0_CC1 #6 TIM0_CC0 #0/1/4 PCNT0_S0IN #4	USB_DMPU #0 US1_RX #4 LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 PRS_CH3 #3 GPIO_EM4WU0

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
2	PA1		TIM0_CC0 #6 TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
3	PA2		TIM0_CC2 #0/1		CMU_CLK0 #0
4	IOVDD_0	Digital IO power supply 0.			
5	VSS	Ground.			
6	PC0	ACMP0_CH0	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5/6 US1_TX #0 US1_CS #5 I2C0_SDA #4	PRS_CH2 #0
7	PC1	ACMP0_CH1	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5/6 US1_TX #5 US1_RX #0 I2C0_SCL #4	PRS_CH3 #0
8	PC2	ACMP0_CH2	TIM0_CDTI0 #4	US1_RX #5	
9	PC3	ACMP0_CH3	TIM0_CDTI1 #4	US1_CLK #5	
10	PC4	ACMP0_CH4	TIM0_CDTI2 #4		GPIO_EM4WU6
11	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
12	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
13	PA8		TIM2_CC0 #0		
14	PA9		TIM2_CC1 #0		
15	PA10		TIM2_CC2 #0		
16	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
17	PB11	IDAC0_OUT	TIM1_CC2 #3 PCNT0_S1IN #4	US1_CLK #4	CMU_CLK1 #3 ACMP0_O #3
18	VSS	Ground.			
19	AVDD_1	Analog power supply 1.			
20	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
21	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
22	IOVDD_3	Digital IO power supply 3.			
23	AVDD_0	Analog power supply 0.			
24	PD4	ADC0_CH4		LEU0_TX #0	

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
25	PD5	ADC0_CH5		LEU0_RX #0	
26	PD6	ADC0_CH6	TIM1_CC0 #4 PCNT0_S0IN #3	US1_RX #2/3 I2C0_SDA #1	ACMP0_O #2
27	PD7	ADC0_CH7	TIM1_CC1 #4 PCNT0_S1IN #3	US1_TX #2/3 I2C0_SCL #1	CMU_CLK0 #2
28	VDD_DREG	Power supply for on-chip voltage regulator.			
29	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
30	PC8		TIM2_CC0 #2	US0_CS #2	
31	PC9		TIM2_CC1 #2	US0_CLK #2	GPIO_EM4WU2
32	PC10		TIM2_CC2 #2	US0_RX #2	
33	USB_VREGI				
34	USB_VREGO				
35	PC14		TIM0_CDTI1 #1/6 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 US1_CS #3/4 LEU0_TX #5 USB_DM	PRS_CH0 #2
36	PC15		TIM0_CDTI2 #1/6 TIM1_CC2 #0	US0_CLK #3 US1_CLK #3 LEU0_RX #5 USB_DP	PRS_CH1 #2
37	PF0		TIM0_CC0 #5	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0 BOOT_TX
38	PF1		TIM0_CC1 #5	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0 GPIO_EM4WU3 BOOT_RX
39	PF2		TIM0_CC2 #5/6 TIM2_CC0 #3	US1_TX #4 LEU0_TX #4	CMU_CLK0 #3 PRS_CH0 #3 GPIO_EM4WU4
40	PF3		TIM0_CDTI0 #5		PRS_CH0 #1
41	PF4		TIM0_CDTI1 #5		PRS_CH1 #1
42	PF5		TIM0_CDTI2 #5		PRS_CH2 #1
43	IOVDD_5	Digital IO power supply 5.			
44	VSS	Ground.			
45	PE10		TIM1_CC0 #1	US0_TX #0	PRS_CH2 #2

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
46	PE11		TIM1_CC1 #1	US0_RX #0	PRS_CH3 #2
47	PE12	ADC0_CH0	TIM1_CC2 #1 TIM2_CC1 #3	US0_RX #3 US0_CLK #0/6 I2C0_SDA #6	CMU_CLK1 #2 PRS_CH1 #3
48	PE13	ADC0_CH1	TIM2_CC2 #3	US0_TX #3 US0_CS #0/6 I2C0_SCL #6	ACMP0_O #0 PRS_CH2 #3 GPIO_EM4WU5

5.8.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.23. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2							Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3							Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4							Analog comparator ACMP0, channel 4.
ACMP0_O	PE13		PD6	PB11				Analog comparator ACMP0, digital output.
ADC0_CH0	PE12							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PE13							Analog to digital converter ADC0, input channel number 1.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0	PA2		PD7	PF2				Clock Management Unit, clock output number 0.
CMU_CLK1	PA1		PE12	PB11				Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
GPIO_EM4WU6	PC4							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7			PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6			PC0	PF0	PE12	I2C0 Serial Data input / output.
IDAC0_OUT	PB11							IDAC0 output.
LEU0_RX	PD5	PB14		PF1	PA0	PC15		LEUART0 Receive input.
LEU0_TX	PD4	PB13		PF0	PF2	PC14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN			PC0	PD6	PA0			Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1	PD7	PB11			Pulse Counter PCNT0 input number 1.
PRS_CH0	PA0	PF3	PC14	PF2				Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1	PF4	PC15	PE12				Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0	PF5	PE10	PE13				Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1		PE11	PA0				Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0	PA1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1			PC0	PF1	PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2			PC1	PF2	PF2	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0					PC2	PF3		Timer 0 Complimentary Dead Time Insertion channel 0.
TIM0_CDTI1		PC14			PC3	PF4	PC14	Timer 0 Complimentary Dead Time Insertion channel 1.
TIM0_CDTI2		PC15			PC4	PF5	PC15	Timer 0 Complimentary Dead Time Insertion channel 2.
TIM1_CC0		PE10		PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11		PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11				Timer 1 Capture Compare input / output channel 2.
TIM2_CC0	PA8		PC8	PF2				Timer 2 Capture Compare input / output channel 0.
TIM2_CC1	PA9		PC9	PE12				Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10		PC10	PE13				Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12		PC9	PC15	PB13	PB13	PE12	USART0 clock input / output.
US0_CS	PE13		PC8	PC14	PB14	PB14	PE13	USART0 chip select input / output.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
US0_RX	PE11		PC10	PE12	PB8	PC1	PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10			PE13	PB7	PC0	PC0	USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7		PF0	PC15	PB11	PC3		USART1 clock input / output.
US1_CS	PB8		PF1	PC14	PC14	PC0		USART1 chip select input / output.
US1_RX	PC1		PD6	PD6	PA0	PC2		USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0		PD7	PD7	PF2	PC1		USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PC14							USB D- pin.
USB_DMPU	PA0							USB D- Pullup control.
USB_DP	PC15							USB D+ pin.
USB_VREGI	USB_VREGI							USB Input to internal 3.3 V regulator
USB_VREGO	USB_VREGO							USB Decoupling for internal 3.3 V USB regulator and regulator output

5.8.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32HG321 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.24. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	PA10	PA9	PA8	-	-	-	-	-	PA2	PA1	PA0
Port B	-	PB14	PB13	-	PB11	-	-	PB8	PB7	-	-	-	-	-	-	-
Port C	PC15	PC14	-	-	-	PC10	PC9	PC8	-	-	-	PC4	PC3	PC2	PC1	PC0
Port D	-	-	-	-	-	-	-	-	PD7	PD6	PD5	PD4	-	-	-	-
Port E	-	-	PE13	PE12	PE11	PE10	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	PF5	PF4	PF3	PF2	PF1	PF0

5.9 EFM32HG322 (TQFP48)

5.9.1 Pinout

The EFM32HG322 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

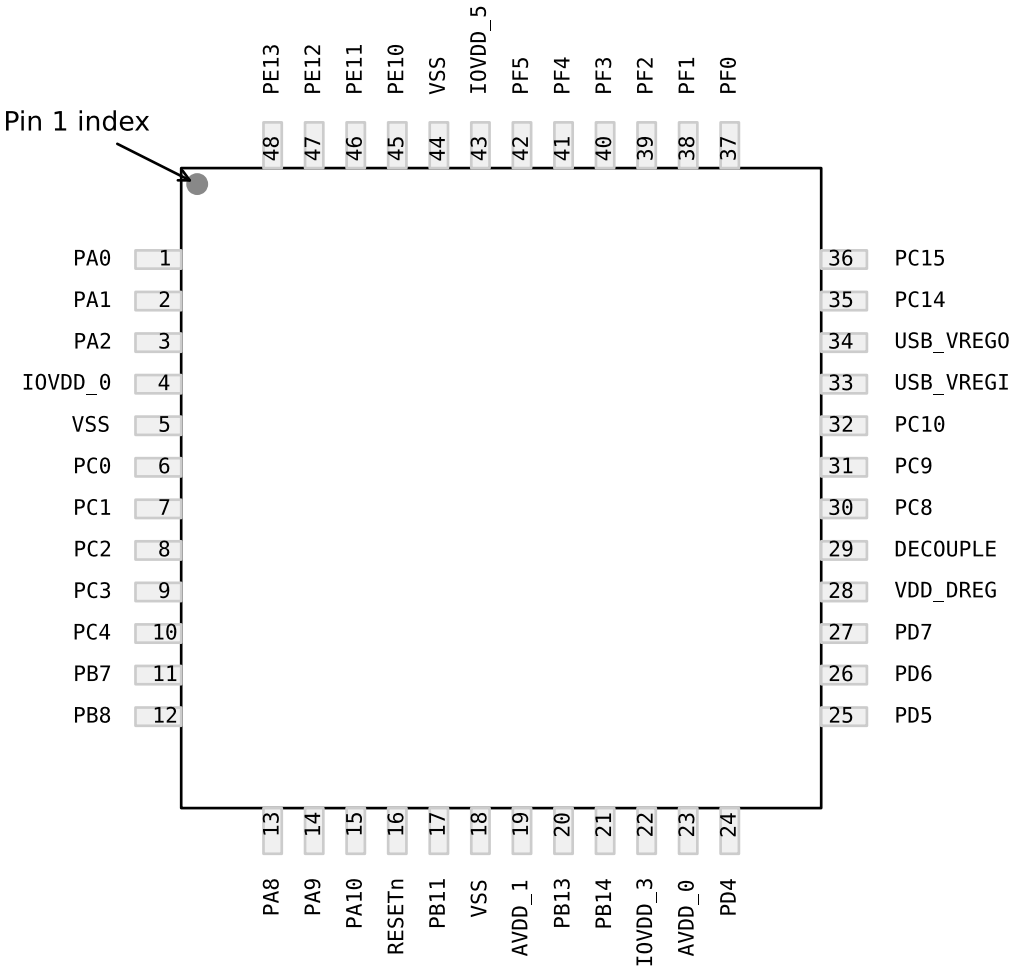


Figure 5.9. EFM32HG322Pinout (top view, not to scale)

Table 5.25. Device Pinout

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	**Pin Name**	**Analog**	**Timers**	**Communication**	**Other**
1	PA0		TIM0_CC1 #6 TIM0_CC0 #0/1/4 PCNT0_S0IN #4	USB_DMPU #0 US1_RX #4 LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 PRS_CH3 #3 GPIO_EM4WU0

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
2	PA1		TIM0_CC0 #6 TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
3	PA2		TIM0_CC2 #0/1		CMU_CLK0 #0
4	IOVDD_0	Digital IO power supply 0.			
5	VSS	Ground.			
6	PC0	ACMP0_CH0	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5/6 US1_TX #0 US1_CS #5 I2C0_SDA #4	PRS_CH2 #0
7	PC1	ACMP0_CH1	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5/6 US1_TX #5 US1_RX #0 I2C0_SCL #4	PRS_CH3 #0
8	PC2	ACMP0_CH2	TIM0_CDTI0 #4	US1_RX #5	
9	PC3	ACMP0_CH3	TIM0_CDTI1 #4	US1_CLK #5	
10	PC4	ACMP0_CH4	TIM0_CDTI2 #4		GPIO_EM4WU6
11	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
12	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	
13	PA8		TIM2_CC0 #0		
14	PA9		TIM2_CC1 #0		
15	PA10		TIM2_CC2 #0		
16	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
17	PB11	IDAC0_OUT	TIM1_CC2 #3 PCNT0_S1IN #4	US1_CLK #4	CMU_CLK1 #3 ACMP0_O #3
18	VSS	Ground.			
19	AVDD_1	Analog power supply 1.			
20	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
21	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
22	IOVDD_3	Digital IO power supply 3.			
23	AVDD_0	Analog power supply 0.			
24	PD4	ADC0_CH4		LEU0_TX #0	

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
25	PD5	ADC0_CH5		LEU0_RX #0	
26	PD6	ADC0_CH6	TIM1_CC0 #4 PCNT0_S0IN #3	US1_RX #2/3 I2C0_SDA #1	ACMP0_O #2
27	PD7	ADC0_CH7	TIM1_CC1 #4 PCNT0_S1IN #3	US1_TX #2/3 I2C0_SCL #1	CMU_CLK0 #2
28	VDD_DREG	Power supply for on-chip voltage regulator.			
29	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
30	PC8		TIM2_CC0 #2	US0_CS #2	
31	PC9		TIM2_CC1 #2	US0_CLK #2	GPIO_EM4WU2
32	PC10		TIM2_CC2 #2	US0_RX #2	
33	USB_VREGI				
34	USB_VREGO				
35	PC14		TIM0_CDTI1 #1/6 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 US1_CS #3/4 LEU0_TX #5 USB_DM	PRS_CH0 #2
36	PC15		TIM0_CDTI2 #1/6 TIM1_CC2 #0	US0_CLK #3 US1_CLK #3 LEU0_RX #5 USB_DP	PRS_CH1 #2
37	PF0		TIM0_CC0 #5	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0 BOOT_TX
38	PF1		TIM0_CC1 #5	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0 GPIO_EM4WU3 BOOT_RX
39	PF2		TIM0_CC2 #5/6 TIM2_CC0 #3	US1_TX #4 LEU0_TX #4	CMU_CLK0 #3 PRS_CH0 #3 GPIO_EM4WU4
40	PF3		TIM0_CDTI0 #5		PRS_CH0 #1
41	PF4		TIM0_CDTI1 #5		PRS_CH1 #1
42	PF5		TIM0_CDTI2 #5		PRS_CH2 #1
43	IOVDD_5	Digital IO power supply 5.			
44	VSS	Ground.			
45	PE10		TIM1_CC0 #1	US0_TX #0	PRS_CH2 #2

QFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
46	PE11		TIM1_CC1 #1	US0_RX #0	PRS_CH3 #2
47	PE12	ADC0_CH0	TIM1_CC2 #1 TIM2_CC1 #3	US0_RX #3 US0_CLK #0/6 I2C0_SDA #6	CMU_CLK1 #2 PRS_CH1 #3
48	PE13	ADC0_CH1	TIM2_CC2 #3	US0_TX #3 US0_CS #0/6 I2C0_SCL #6	ACMP0_O #0 PRS_CH2 #3 GPIO_EM4WU5

5.9.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.26. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2							Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3							Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4							Analog comparator ACMP0, channel 4.
ACMP0_O	PE13		PD6	PB11				Analog comparator ACMP0, digital output.
ADC0_CH0	PE12							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PE13							Analog to digital converter ADC0, input channel number 1.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0	PA2		PD7	PF2				Clock Management Unit, clock output number 0.
CMU_CLK1	PA1		PE12	PB11				Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
GPIO_EM4WU6	PC4							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7			PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6			PC0	PF0	PE12	I2C0 Serial Data input / output.
IDAC0_OUT	PB11							IDAC0 output.
LEU0_RX	PD5	PB14		PF1	PA0	PC15		LEUART0 Receive input.
LEU0_TX	PD4	PB13		PF0	PF2	PC14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN			PC0	PD6	PA0			Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1	PD7	PB11			Pulse Counter PCNT0 input number 1.
PRS_CH0	PA0	PF3	PC14	PF2				Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1	PF4	PC15	PE12				Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0	PF5	PE10	PE13				Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1		PE11	PA0				Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0	PA1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1			PC0	PF1	PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2			PC1	PF2	PF2	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0					PC2	PF3		Timer 0 Complimentary Dead Time Insertion channel 0.
TIM0_CDTI1		PC14			PC3	PF4	PC14	Timer 0 Complimentary Dead Time Insertion channel 1.
TIM0_CDTI2		PC15			PC4	PF5	PC15	Timer 0 Complimentary Dead Time Insertion channel 2.
TIM1_CC0		PE10		PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11		PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11				Timer 1 Capture Compare input / output channel 2.
TIM2_CC0	PA8		PC8	PF2				Timer 2 Capture Compare input / output channel 0.
TIM2_CC1	PA9		PC9	PE12				Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10		PC10	PE13				Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12		PC9	PC15	PB13	PB13	PE12	USART0 clock input / output.
US0_CS	PE13		PC8	PC14	PB14	PB14	PE13	USART0 chip select input / output.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
US0_RX	PE11		PC10	PE12	PB8	PC1	PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10			PE13	PB7	PC0	PC0	USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7		PF0	PC15	PB11	PC3		USART1 clock input / output.
US1_CS	PB8		PF1	PC14	PC14	PC0		USART1 chip select input / output.
US1_RX	PC1		PD6	PD6	PA0	PC2		USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0		PD7	PD7	PF2	PC1		USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PC14							USB D- pin.
USB_DMPU	PA0							USB D- Pullup control.
USB_DP	PC15							USB D+ pin.
USB_VREGI	USB_VREGI							USB Input to internal 3.3 V regulator
USB_VREGO	USB_VREGO							USB Decoupling for internal 3.3 V USB regulator and regulator output

5.9.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32HG322 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.27. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	PA10	PA9	PA8	-	-	-	-	-	PA2	PA1	PA0
Port B	-	PB14	PB13	-	PB11	-	-	PB8	PB7	-	-	-	-	-	-	-
Port C	PC15	PC14	-	-	-	PC10	PC9	PC8	-	-	-	PC4	PC3	PC2	PC1	PC0
Port D	-	-	-	-	-	-	-	-	PD7	PD6	PD5	PD4	-	-	-	-
Port E	-	-	PE13	PE12	PE11	PE10	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	PF5	PF4	PF3	PF2	PF1	PF0

5.10 EFM32HG350 (CSP36)

5.10.1 Pinout

The EFM32HG350 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

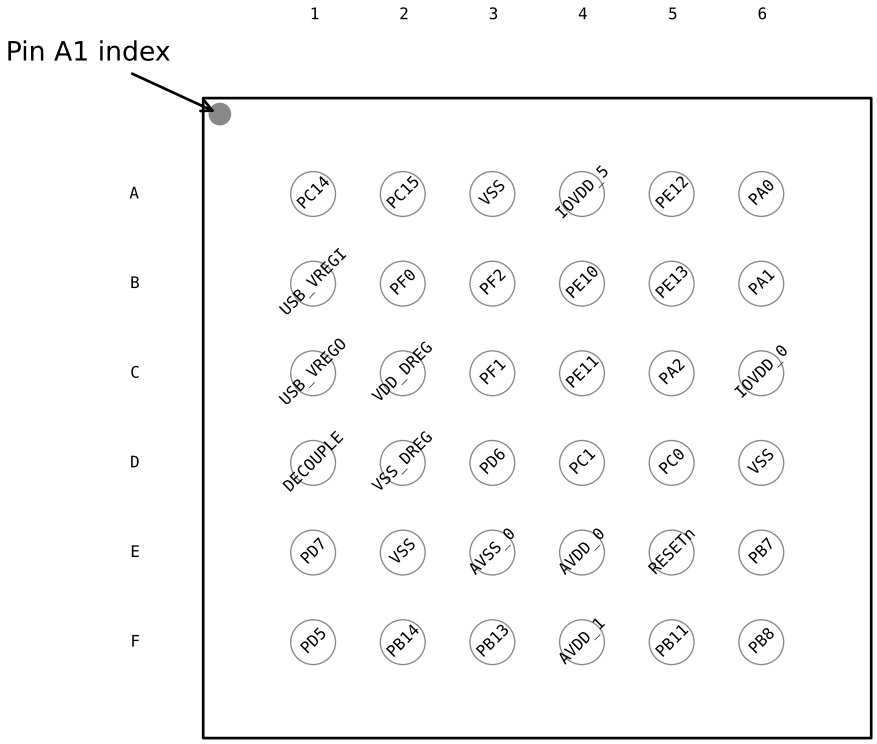


Figure 5.10. EFM32HG350 Pinout (top view, not to scale)

Table 5.28. Device Pinout

CSP36 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	**Pin Name**	**Analog**	**Timers**	**Communication**	**Other**
A1	PC14		TIM0_CDTI1 #1/6 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 US1_CS #3/4 LEU0_TX #5 USB_DM	PRS_CH0 #2

CSP36 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
A2	PC15		TIM0_CDTI2 #1/6 TIM1_CC2 #0	US0_CLK #3 US1_CLK #3 LEU0_RX #5 USB_DP	PRS_CH1 #2
A3	VSS	Ground.			
A4	IOVDD_5	Digital IO power supply 5.			
A5	PE12	ADC0_CH0	TIM1_CC2 #1 TIM2_CC1 #3	US0_RX #3 US0_CLK #0/6 I2C0_SDA #6	CMU_CLK1 #2 PRS_CH1 #3
A6	PA0		TIM0_CC1 #6 TIM0_CC0 #0/1/4 PCNT0_S0IN #4	USB_DMPU #0 US1_RX #4 LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 PRS_CH3 #3 GPIO_EM4WU0
B1	USB_VREGI				
B2	PF0		TIM0_CC0 #5	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0 BOOT_TX
B3	PF2		TIM0_CC2 #5/6 TIM2_CC0 #3	US1_TX #4 LEU0_TX #4	CMU_CLK0 #3 PRS_CH0 #3 GPIO_EM4WU4
B4	PE10		TIM1_CC0 #1	US0_TX #0	PRS_CH2 #2
B5	PE13	ADC0_CH1	TIM2_CC2 #3	US0_TX #3 US0_CS #0/6 I2C0_SCL #6	ACMP0_O #0 PRS_CH2 #3 GPIO_EM4WU5
B6	PA1		TIM0_CC0 #6 TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
C1	USB_VREGO				
C2	VDD_DREG	Power supply for on-chip voltage regulator.			
C3	PF1		TIM0_CC1 #5	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0 GPIO_EM4WU3 BOOT_RX
C4	PE11		TIM1_CC1 #1	US0_RX #0	PRS_CH3 #2
C5	PA2		TIM0_CC2 #0/1		CMU_CLK0 #0
C6	IOVDD_0	Digital IO power supply 0.			
D1	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			

CSP36 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
D2	VSS_DREG	Ground for on-chip voltage regulator.			
D3	PD6	ADC0_CH6	TIM1_CC0 #4 PCNT0_S0IN #3	US1_RX #2/3 I2C0_SDA #1	ACMP0_O #2
D4	PC1	ACMP0_CH1	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5/6 US1_TX #5 US1_RX #0 I2C0_SCL #4	PRS_CH3 #0
D5	PC0	ACMP0_CH0	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5/6 US1_TX #0 US1_CS #5 I2C0_SDA #4	PRS_CH2 #0
D6	VSS	Ground.			
E1	PD7	ADC0_CH7	TIM1_CC1 #4 PCNT0_S1IN #3	US1_TX #2/3 I2C0_SCL #1	CMU_CLK0 #2
E2	VSS	Ground.			
E3	AVSS_0	Analog ground 0.			
E4	AVDD_0	Analog power supply 0.			
E5	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
E6	PB7	LFXTAL_P	TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
F1	PD5	ADC0_CH5		LEU0_RX #0	
F2	PB14	HFXTAL_N		US0_CS #4/5 LEU0_RX #1	
F3	PB13	HFXTAL_P		US0_CLK #4/5 LEU0_TX #1	
F4	AVDD_1	Analog power supply 1.			
F5	PB11	IDAC0_OUT	TIM1_CC2 #3 PCNT0_S1IN #4	US1_CLK #4	CMU_CLK1 #3 ACMP0_O #3
F6	PB8	LFXTAL_N	TIM1_CC1 #3	US0_RX #4 US1_CS #0	

5.10.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.29. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_O	PE13		PD6	PB11				Analog comparator ACMP0, digital output.
ADC0_CH0	PE12							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PE13							Analog to digital converter ADC0, input channel number 1.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PF1							Bootloader RX.
BOOT_TX	PF0							Bootloader TX.
CMU_CLK0	PA2		PD7	PF2				Clock Management Unit, clock output number 0.
CMU_CLK1	PA1		PE12	PB11				Clock Management Unit, clock output number 1.
DBG_SWCLK	PF0							Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1							Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7			PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6			PC0	PF0	PE12	I2C0 Serial Data input / output.
IDAC0_OUT	PB11							IDAC0 output.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LEU0_RX	PD5	PB14		PF1	PA0	PC15		LEUART0 Receive input.
LEU0_TX		PB13		PF0	PF2	PC14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN			PC0	PD6	PA0			Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1	PD7	PB11			Pulse Counter PCNT0 input number 1.
PRS_CH0	PA0		PC14	PF2				Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1		PC15	PE12				Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0		PE10	PE13				Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1		PE11	PA0				Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0			PA0	PF0	PA1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1			PC0	PF1	PA0	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2			PC1	PF2	PF2	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI1		PC14					PC14	Timer 0 Complimentary Dead Time Insertion channel 1.
TIM0_CDTI2		PC15					PC15	Timer 0 Complimentary Dead Time Insertion channel 2.
TIM1_CC0		PE10		PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11		PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11				Timer 1 Capture Compare input / output channel 2.
TIM2_CC0				PF2				Timer 2 Capture Compare input / output channel 0.
TIM2_CC1				PE12				Timer 2 Capture Compare input / output channel 1.
TIM2_CC2				PE13				Timer 2 Capture Compare input / output channel 2.
US0_CLK	PE12			PC15	PB13	PB13	PE12	USART0 clock input / output.
US0_CS	PE13			PC14	PB14	PB14	PE13	USART0 chip select input / output.
US0_RX	PE11			PE12	PB8	PC1	PC1	USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10			PE13	PB7	PC0	PC0	USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7		PF0	PC15	PB11			USART1 clock input / output.
US1_CS	PB8		PF1	PC14	PC14	PC0		USART1 chip select input / output.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
US1_RX	PC1		PD6	PD6	PA0			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0		PD7	PD7	PF2	PC1		USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PC14							USB D- pin.
USB_DMPU	PA0							USB D- Pullup control.
USB_DP	PC15							USB D+ pin.
USB_VREGI	USB_VREGI							USB Input to internal 3.3 V regulator
USB_VREGO	USB_VREGO							USB Decoupling for internal 3.3 V USB regulator and regulator output

5.10.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32HG350 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.30. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	-	-	-	-	-	-	-	-	-	-	-	-	-	PA2	PA1	PA0
Port B	-	PB14	PB13	-	PB11	-	-	PB8	PB7	-	-	-	-	-	-	-
Port C	PC15	PC14	-	-	-	-	-	-	-	-	-	-	-	-	PC1	PC0
Port D	-	-	-	-	-	-	-	-	PD7	PD6	PD5	-	-	-	-	-
Port E	-	-	PE13	PE12	PE11	PE10	-	-	-	-	-	-	-	-	-	-
Port F	-	-	-	-	-	-	-	-	-	-	-	-	-	PF2	PF1	PF0

6. CSP36 Package Specifications

6.1 CSP36 Package Dimensions

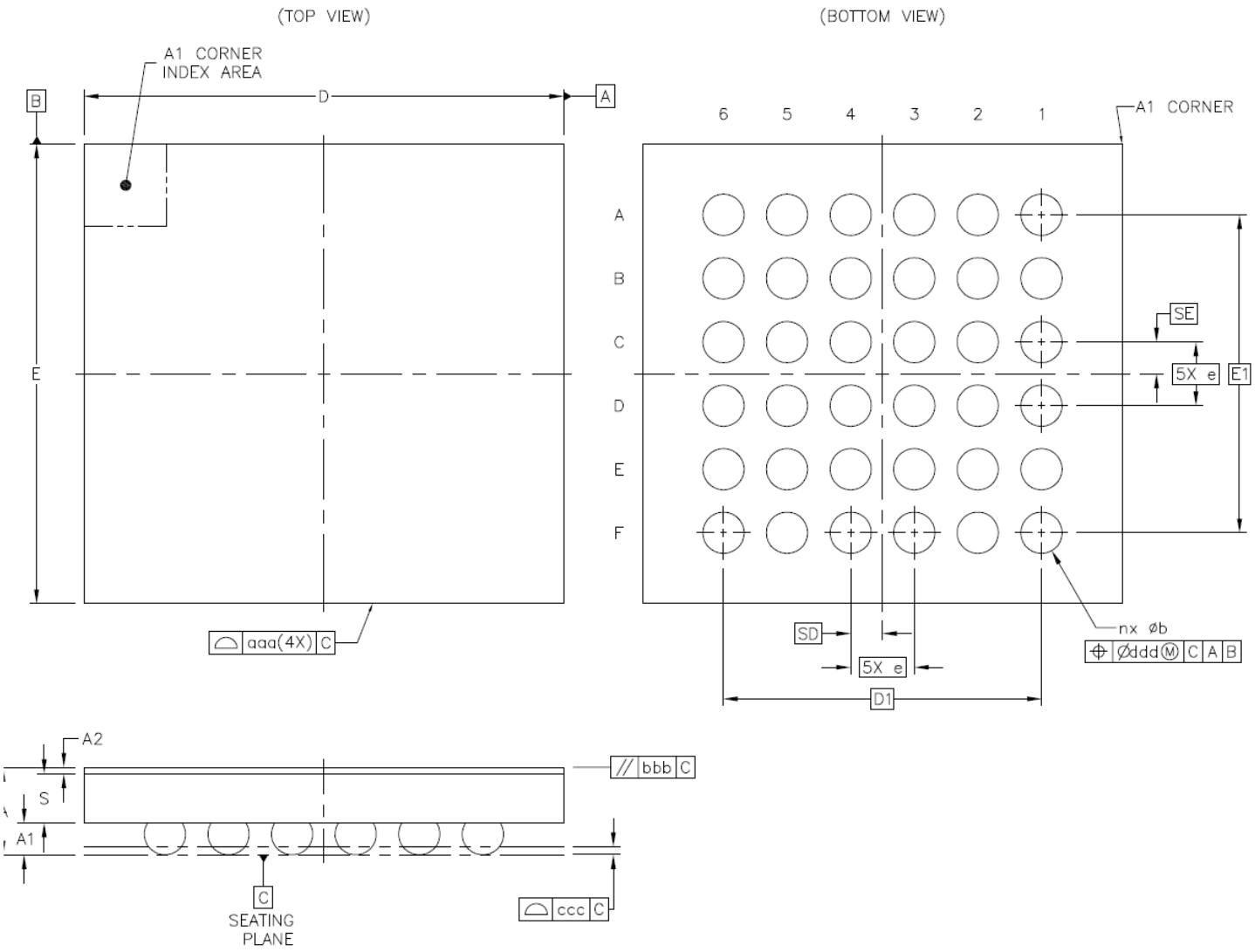


Figure 6.1. CSP81

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. Primary datum “C” and seating plane are defined by the spherical crowns of the solder balls.
4. Dimension “b” is measured at the maximum solder bump diameter, parallel to primary datum “C”.
5. Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

Table 6.1. CSP36 (Dimensions in mm)

Symbol	A	A1	A2	b	S	D	E	e	D1	E1	SD	SE	n	aaa	bbb	ccc	ddd
Min	0.491	0.17	0.036	0.23	0.3075	3.016 BSC.	2.891 BSC.	0.40 BSC.	2.00 BSC.	2.00 BSC.	0.2	0.2	36	0.03	0.06	0.05	0.015
Nom	0.55	-	0.040	-	0.31												
Max	0.609	0.23	0.044	0.29	0.3125												

All EFM32 packages are RoHS compliant and free of Bromine (Br) and Antimony (Sb).

For additional Quality and Environmental information, please see: http://www.silabs.com/support/quality/pages/default.aspx.

6.2 CSP36 PCB Layout

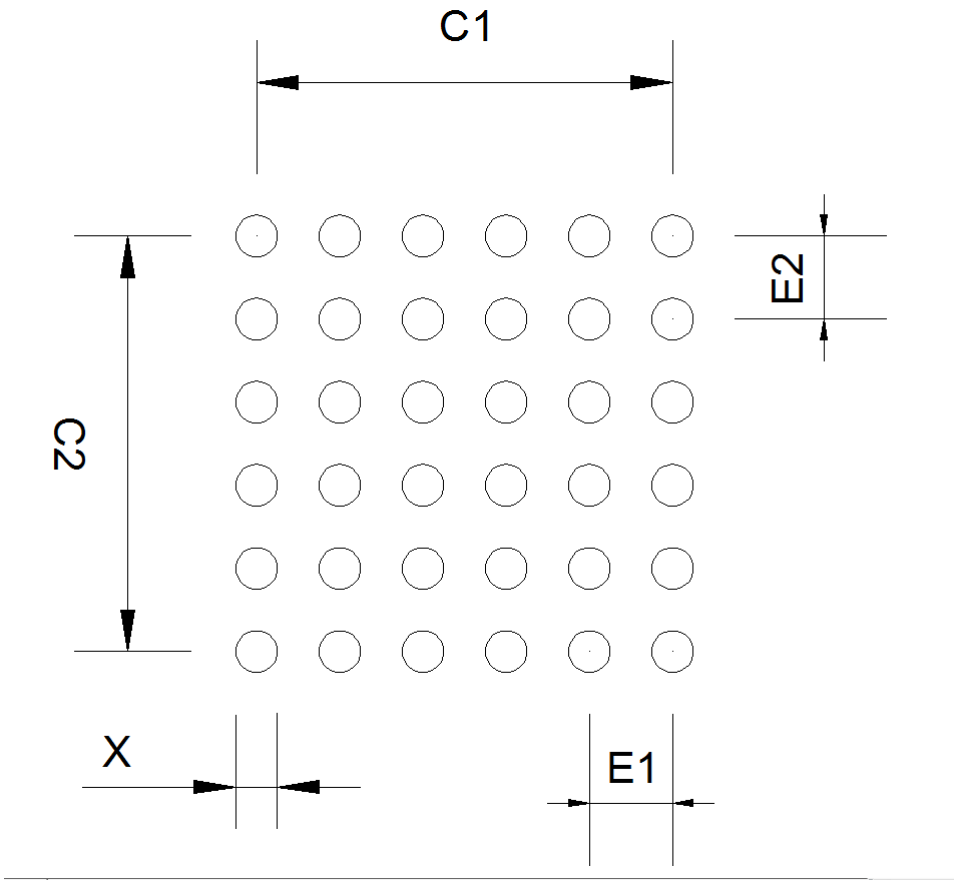


Figure 6.2. CSP36 PCB Land Pattern

Table 6.2. CSP36 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
X	0.20
C1	2.00
C2	2.00
E1	0.40
E2	0.40

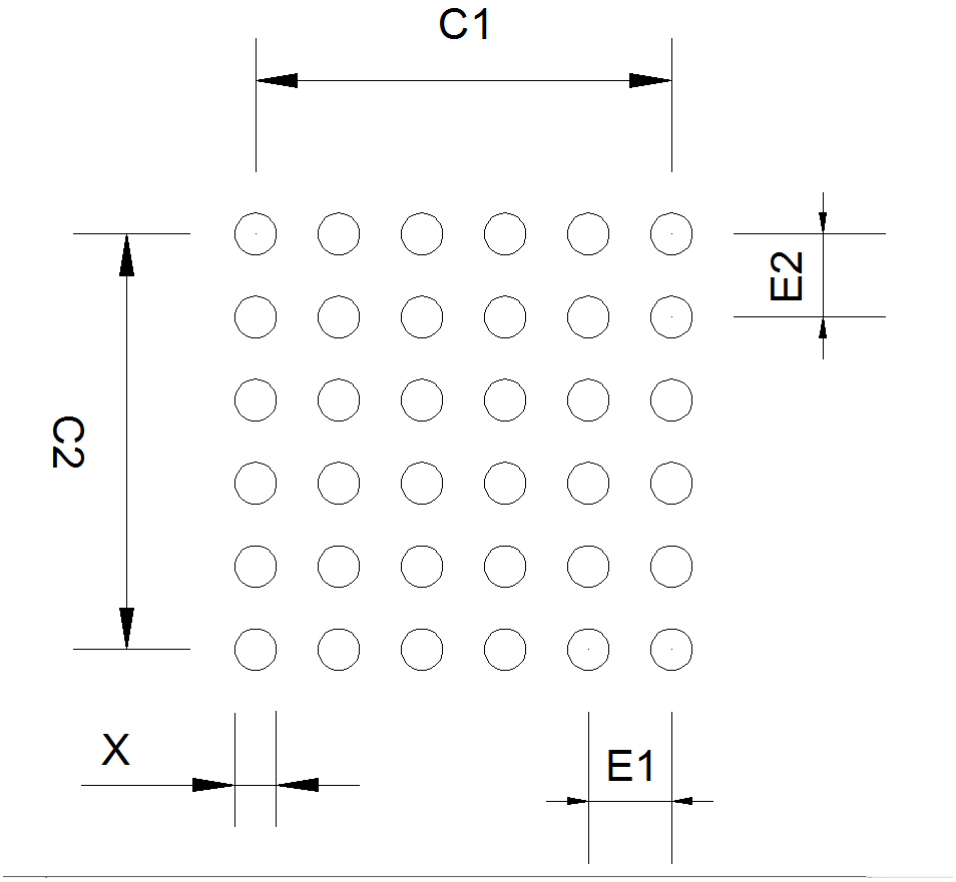


Figure 6.3. CSP36 PCB Solder Mask

Table 6.3. CSP36 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
X	0.26
C1	2.00
C2	2.00
E1	0.40
E2	0.40

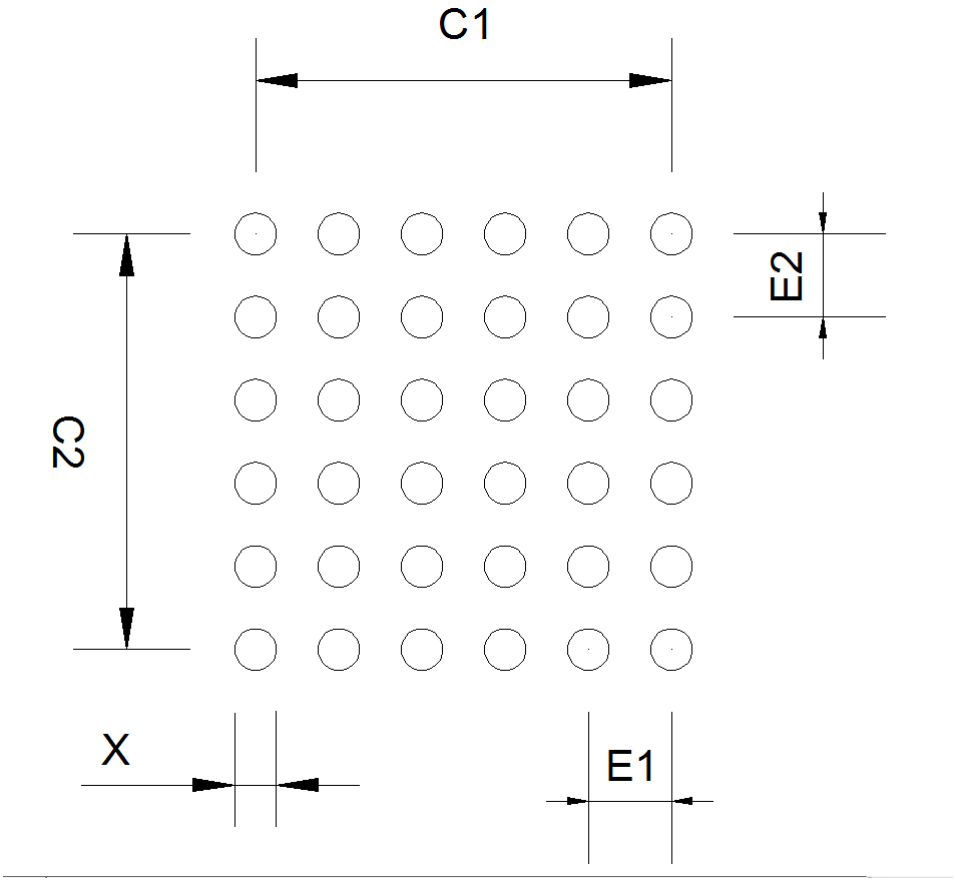


Figure 6.4. CSP36 PCB Stencil Design

Table 6.4. CSP36 PCB Stencil Design Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
X	0.20
C1	2.00
C2	2.00
E1	0.40
E2	0.40

Note:

1. The drawings are not to scale.
2. All dimensions are in millimeters.
3. All drawings are subject to change without notice.
4. The PCB Land Pattern drawing is in compliance with IPC-7351B.
5. Stencil thickness 0.075 mm (3 mils).
6. For detailed pin-positioning, see Pin Definitions.

6.3 CSP36 Chip Marking

In the illustration below package fields and position are shown.

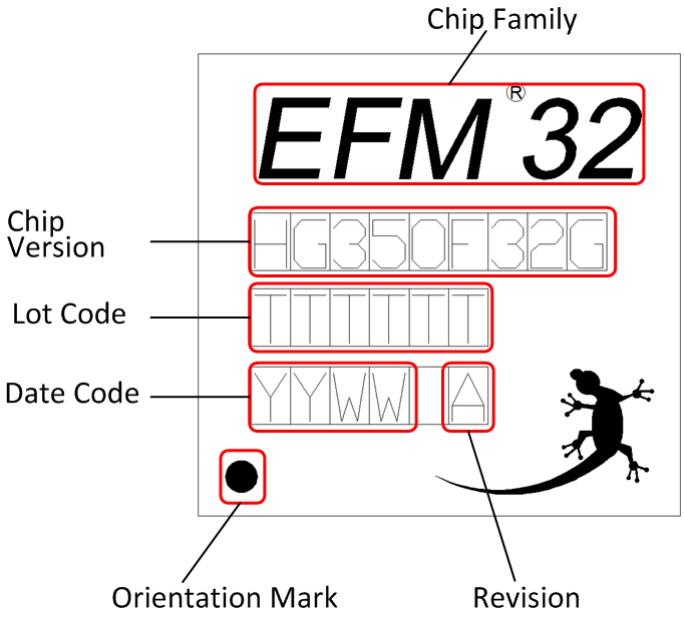


Figure 6.5. Example Chip Marking (Top View)

6.4 CSP36 Environmental

WLCSP devices can be handled and soldered using industry standard surface mount assembly techniques. However, because WLCSP devices are essentially a piece of silicon and are not encapsulated in plastic, they are susceptible to mechanical damage and may be sensitive to light. When WLCSPs must be used in an environment exposed to light, it may be necessary to cover the top and sides with an opaque material.

7. QFN24 Package Specifications

7.1 QFN24 Package Dimensions

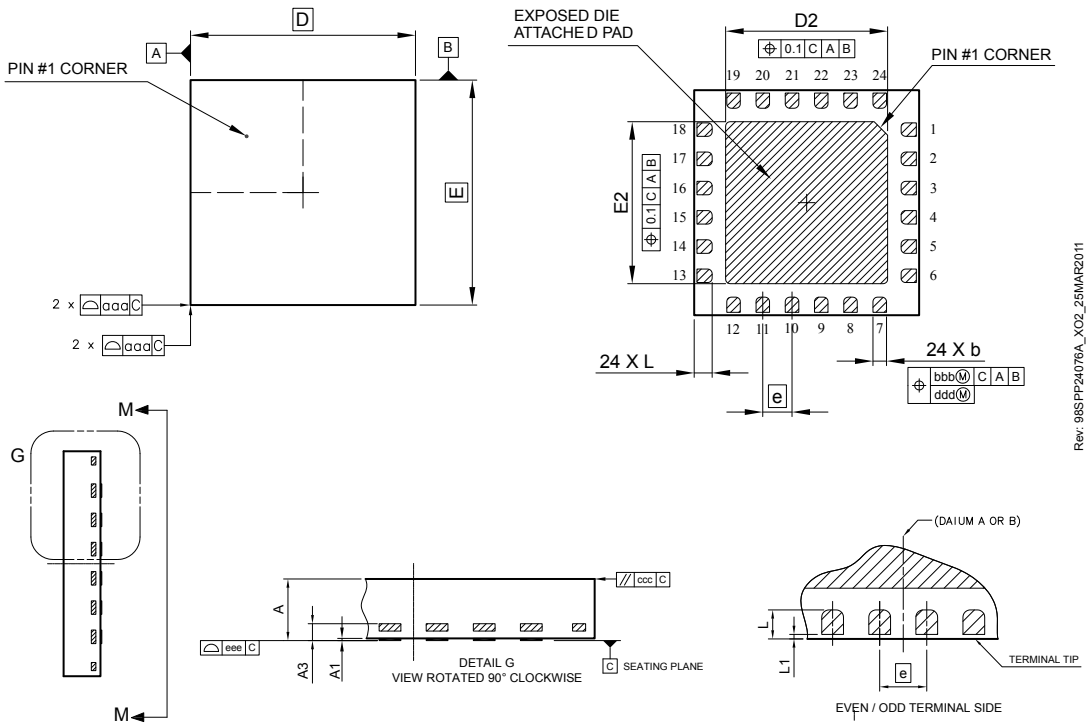


Figure 7.1. QFN24

Note:

1. Dimensioning & tolerancing confirm to ASME Y14.5M-1994.
2. All dimensions are in millimeters. Angles are in degrees.
3. Dimension 'b' applies to metallized terminal and is measured between 0.25 mm and 0.30 mm from the terminal tip. Dimension L1 represents terminal full back from package edge up to 0.1 mm is acceptable.
4. Coplanarity applies to the exposed heat slug as well as the terminal.
5. Radius on terminal is optional.

Table 7.1. QFN (Dimensions in mm)

Symbol	A	A1	A3	b	D	E	D2	E2	e	L	L1	aaa	bbb	ccc	ddd	eee
Min	0.80	0.00	0.203 REF	0.25	5.00 BSC	5.00 BSC	3.50	3.50	0.65 BSC	0.35	0.00	0.10	0.10	0.10	0.05	0.08
Nom	0.85	—		0.30			3.60	3.60		0.40						
Max	0.90	0.05		0.35			3.70	3.70		0.45	0.10					

The QFN24 package uses matte-Sn post plated leadframe.

All EFM32 packages are RoHS compliant and free of Bromine (Br) and Antimony (Sb).

For additional Quality and Environmental information, please see: http://www.silabs.com/support/quality/pages/default.aspx.

7.2 QFN24 PCB Layout

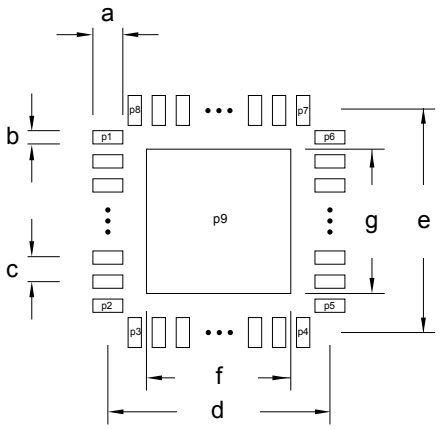


Figure 7.2. QFN24 PCB Land Pattern

Table 7.2. QFN24 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Pin Number	Symbol	Pin Number
a	0.80	P1	1	P8	24
b	0.30	P2	6	P9	0
c	0.65	P3	7	-	-
d	5.00	P4	12	-	-
e	5.00	P5	13	-	-
f	3.60	P6	18	-	-
g	3.60	P7	19	-	-

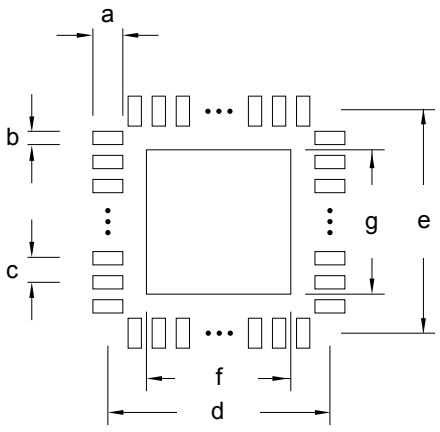


Figure 7.3. QFN24 PCB Solder Mask

Table 7.3. QFN24 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	0.92
b	0.42
c	0.65

Symbol	Dim. (mm)
d	5.00
e	5.00
f	3.72
g	3.72

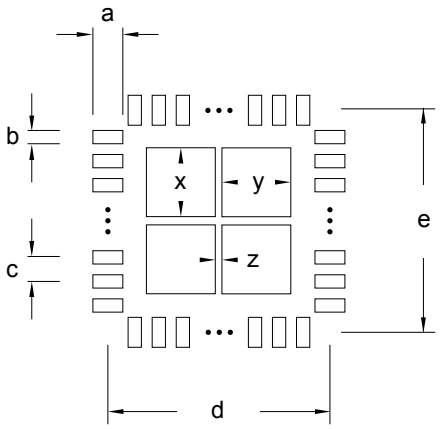


Figure 7.4. QFN24 PCB Stencil Design

Table 7.4. QFN24 PCB Stencil Design Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	0.60
b	0.25
c	0.65
d	5.00
e	5.00
x	1.00
y	1.00
z	0.50

Note:

1. The drawings are not to scale.
2. All dimensions are in millimeters.
3. All drawings are subject to change without notice.
4. The PCB Land Pattern drawing is in compliance with IPC-7351B.
5. Stencil thickness 0.125 mm.
6. For detailed pin-positioning, see Pin Definitions.

7.3 QFN24 Package Marking

In the illustration below package fields and position are shown.

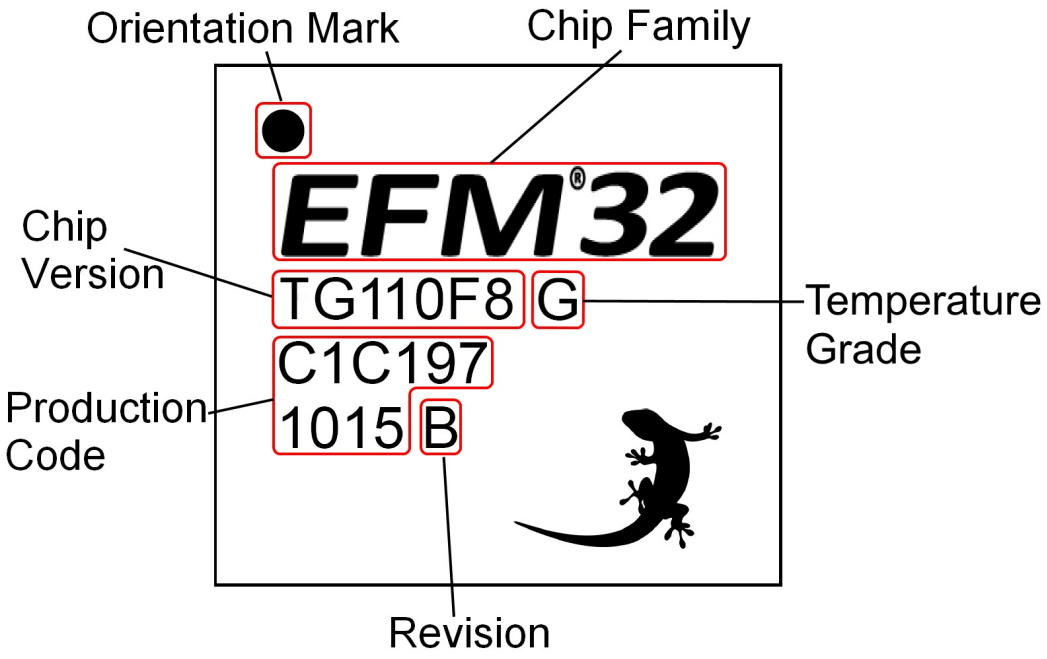


Figure 7.5. Example Chip Marking (Top View)

8. QFN32 Package Specifications

8.1 QFN32 Package Dimensions

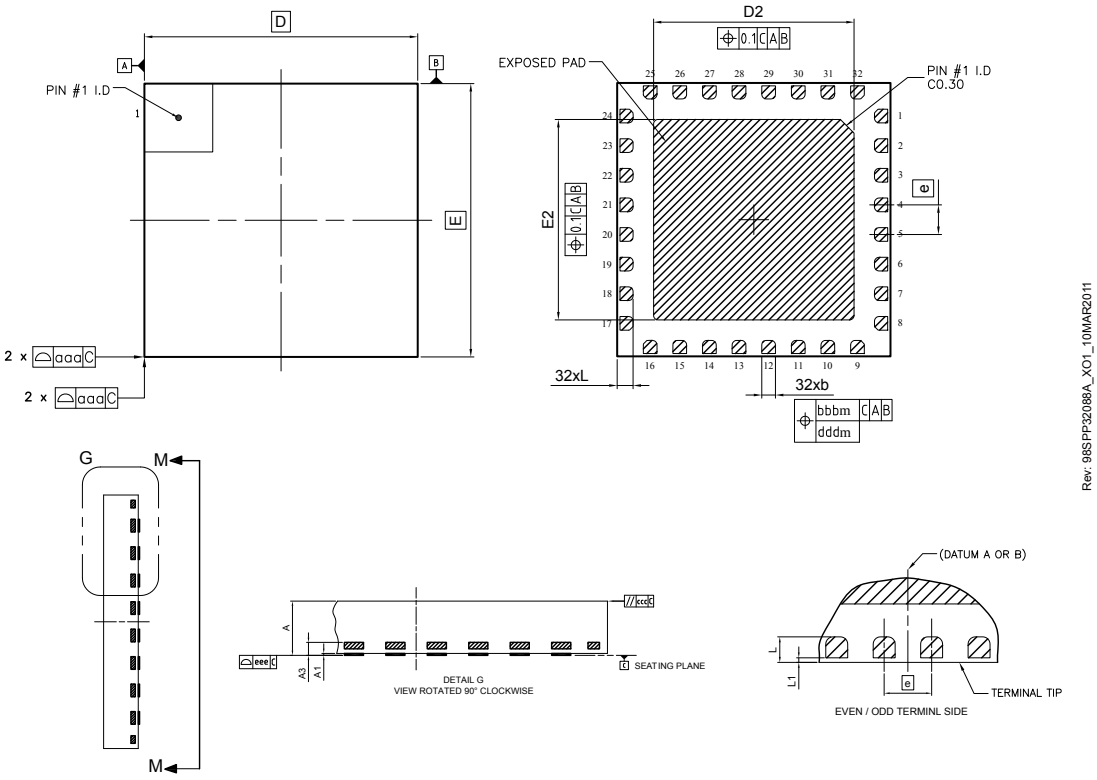


Figure 8.1. QFN32

Note:

1. Dimensioning & tolerancing confirm to ASME Y14.5M-1994.
2. All dimensions are in millimeters. Angles are in degrees.
3. Dimension 'b' applies to metallized terminal and is measured between 0.25 mm and 0.30 mm from the terminal tip. Dimension L1 represents terminal full back from package edge up to 0.1 mm is acceptable.
4. Coplanarity applies to the exposed heat slug as well as the terminal.
5. Radius on terminal is optional.

Table 8.1. QFN32 (Dimensions in mm)

Symbol	A	A1	A3	b	D	E	D2	E2	e	L	L1	aaa	bbb	ccc	ddd	eee
Min	0.80	0.00	0.203 REF	0.25	6.00 BSC	6.00 BSC	4.30	4.30	0.65 BSC	0.30	0.00	0.10	0.10	0.10	0.05	0.08
Nom	0.85	—		0.30			4.40	4.40		0.35						
Max	0.90	0.05		0.35			4.50	4.50		0.40	0.10					

The QFN32 package uses matte-Sn post plated leadframe.

All EFM32 packages are RoHS compliant and free of Bromine (Br) and Antimony (Sb).

For additional Quality and Environmental information, please see: http://www.silabs.com/support/quality/pages/default.aspx.

8.2 QFN32 PCB Layout

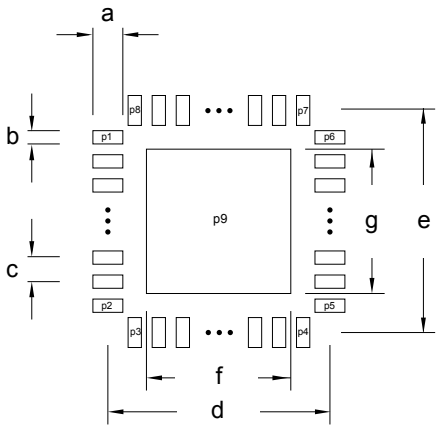


Figure 8.2. QFN32 PCB Land Pattern

Table 8.2. QFN32 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Pin Number	Symbol	Pin Number
a	0.80	P1	1	P6	24
b	0.35	P2	8	P7	25
c	0.65	P3	26	P8	32
d	6.00	P4	16	P9	0
e	6.00	P5	17		
f	4.40				
g	4.40				

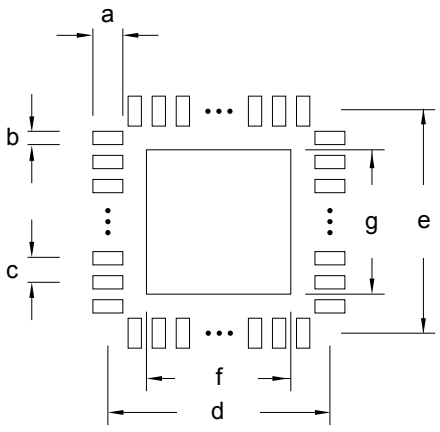


Figure 8.3. QFN32 PCB Solder Mask

Table 8.3. QFN32 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	0.92
b	0.47
c	0.65

Symbol	Dim. (mm)
d	6.00
e	6.00
f	4.52
g	4.52

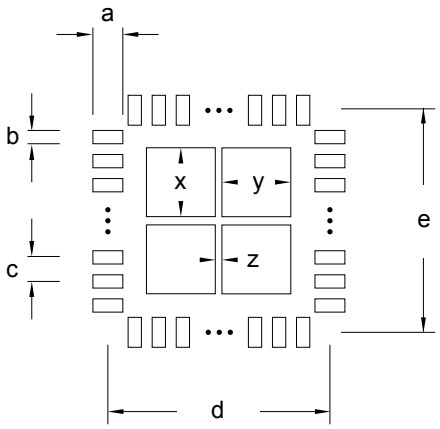


Figure 8.4. QFN32 PCB Stencil Design

Table 8.4. QFN32 PCB Stencil Design Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	0.70
b	0.25
c	0.65
d	6.00
e	6.00
x	1.30
y	1.30
z	0.50

Note:

1. The drawings are not to scale.
2. All dimensions are in millimeters.
3. All drawings are subject to change without notice.
4. The PCB Land Pattern drawing is in compliance with IPC-7351B.
5. Stencil thickness 0.125 mm.
6. For detailed pin-positioning, see Pin Definitions.

8.3 QFN32 Package Marking

In the illustration below package fields and position are shown.

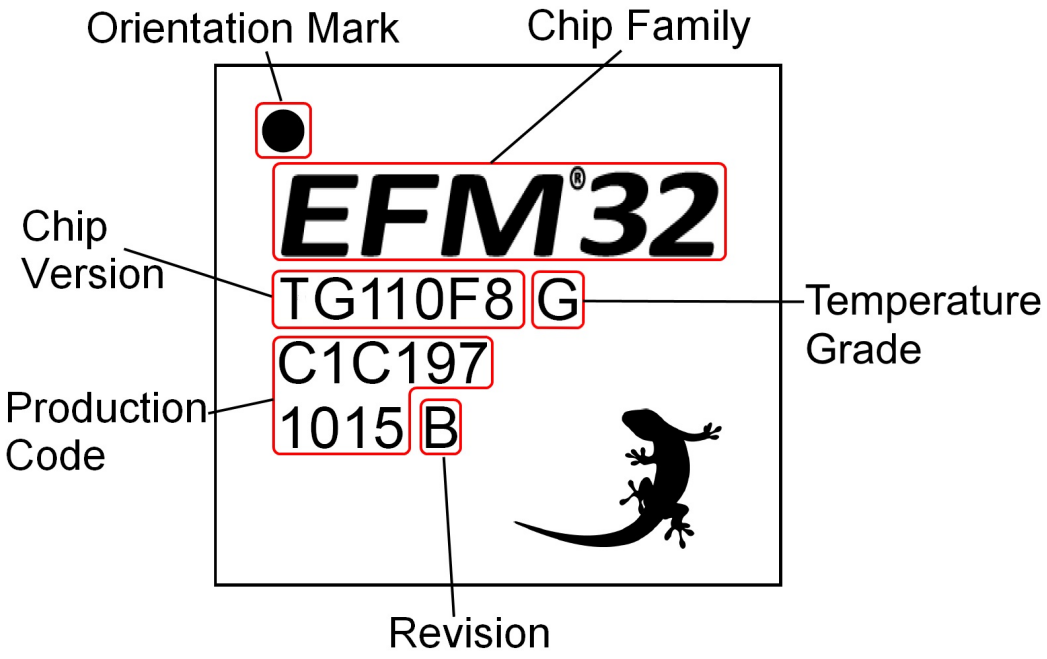


Figure 8.5. Example Chip Marking (Top View)

9. TQFP48 Package Specifications

9.1 TQFP48 Package Dimensions

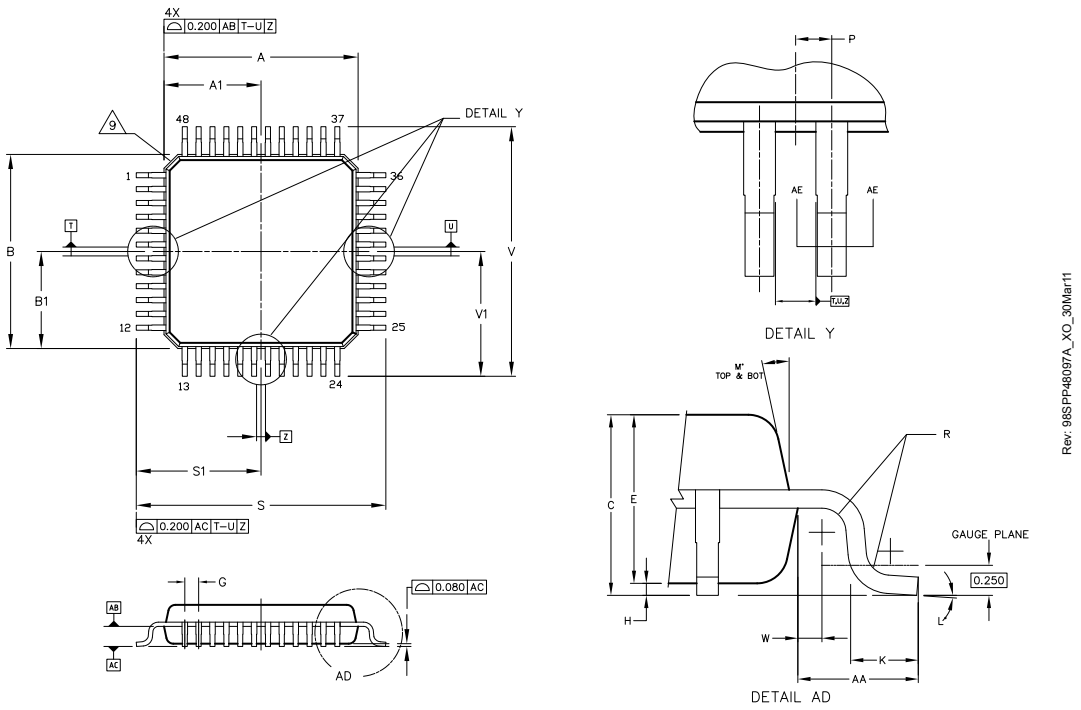


Figure 9.1. TQFP48

Note:

1. Dimensions and tolerance per ASME Y14.5M-1994.
2. Control dimension: Millimeter.
3. Datum plane AB is located at bottom of lead and is coincident with the lead where the lead exists from the plastic body at the bottom of the parting line.
4. Datums T, U and Z to be determined at datum plane AB.
5. Dimensions S and V to be determined at seating plane AC.
6. Dimensions A and B do not include mold protrusion. Allowable protrusion is 0.250 per side. Dimensions A and B do include mold mismatch and are determined at datum AB.
7. Dimension D does not include dambar protrusion. Dambar protrusion shall not cause the D dimension to exceed 0.350.
8. Minimum solder plate thickness shall be 0.0076.
9. Exact shape of each corner is optional.

Table 9.1. QFP48 (Dimensions in mm)

DIM	MIN	NOM	MAX	DIM	MIN	NOM	MAX
A	—	7.000 BSC	—	M	—	12DEG REF	
A1	—	3.500 BSC	—	N	0.090	—	0.160
B	—	7.000 BSC	—	P	—	0.250 BSC	—
B1	—	3.500 BSC	—	R	0.150	—	0.250
C	1.000	—	1.200	S	—	9.000 BSC	—

DIM	MIN	NOM	MAX	DIM	MIN	NOM	MAX
D	0.170	—	0.270	S1	—	4.500 BSC	—
E	0.950	—	1.050	V	—	9.000 BSC	—
F	0.170	—	0.230	V1	—	4.5000 BSC	—
G	—	0.500 BSC	—	W	—	0.200 BSC	—
H	0.050	—	0.150	AA	—	1.000BSC	—
J	0.090	—	0.200				
K	0.500	—	0.700				
L	0DEG	—	7DEG				

The TQFP48 package is 7 by 7 mm in size and has a 0.5 mm pin pitch.

The TQFP48 package uses matte-Sn post plated leadframe.

All EFM32 packages are RoHS compliant and free of Bromine (Br) and Antimony (Sb).

For additional Quality and Environmental information, please see: http://www.silabs.com/support/quality/pages/default.aspx.

9.2 TQFP48 PCB Layout

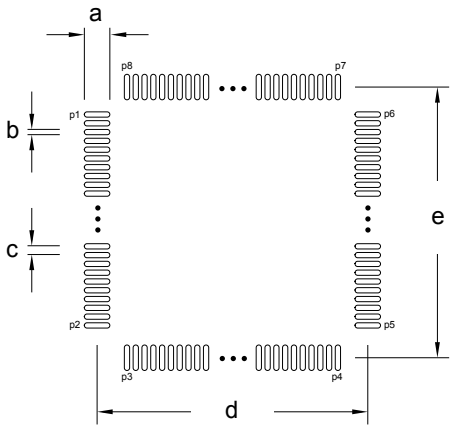


Figure 9.2. TQFP48 PCB Land Pattern

Table 9.2. TQFP48 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Pin Number	Symbol	Pin Number
a	1.60	P1	1	P6	36
b	0.30	P2	12	P7	37
c	0.50	P3	13	P8	48
d	8.50	P4	24		
e	8.50	P5	25		

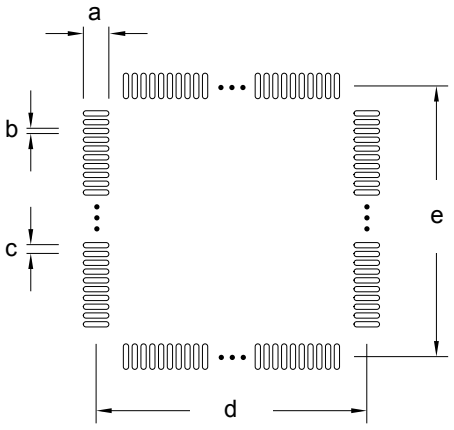


Figure 9.3. TQFP48 PCB Solder Mask

Table 9.3. TQFP48 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	1.72
b	0.42
c	0.50
d	8.50
e	8.50

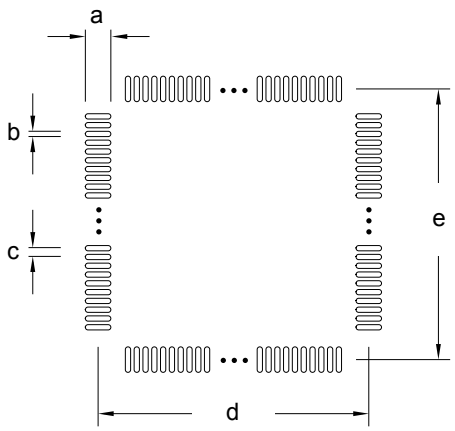


Figure 9.4. TQFP48 PCB Stencil Design

Table 9.4. TQFP48 PCB Stencil Design Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	1.50
b	0.20
c	0.50
d	8.50
e	8.50

Note:

1. The drawings are not to scale.
2. All dimensions are in millimeters.
3. All drawings are subject to change without notice.
4. The PCB Land Pattern drawing is in compliance with IPC-7351B.
5. Stencil thickness 0.125 mm.
6. For detailed pin-positioning, see Pin Definitions.

9.3 TQFP48 Package Marking

In the illustration below package fields and position are shown.

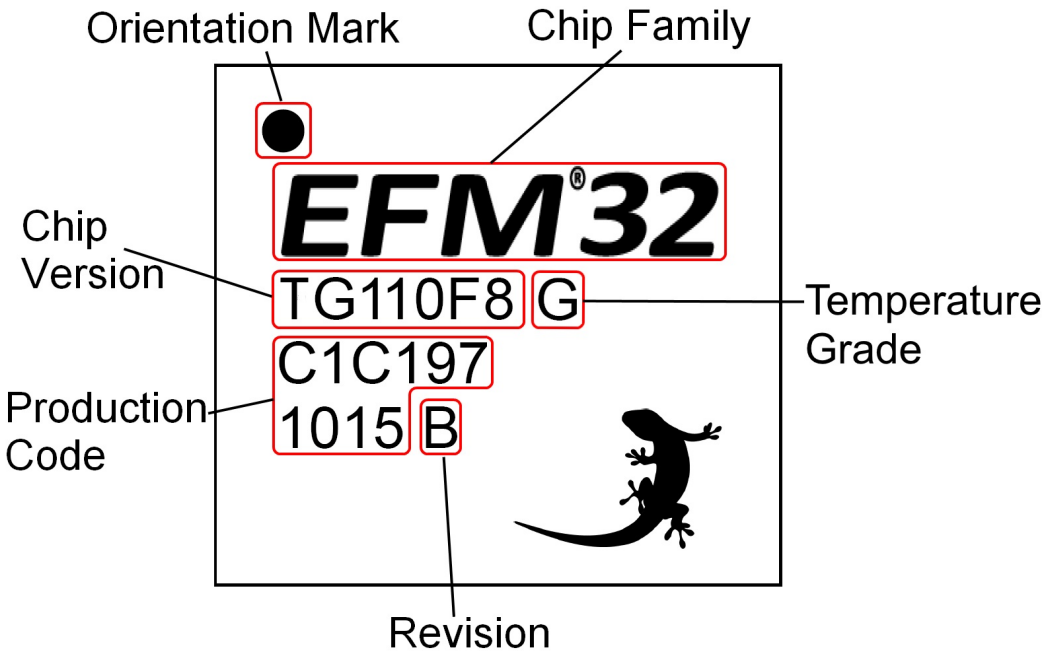


Figure 9.5. Example Chip Marking (Top View)

10. Chip Revision, Solder Information, Errata

10.1 Chip Revision

The revision of a chip can be determined from the "Revision" field in the package marking.

10.2 Soldering Information

The latest IPC/JEDEC J-STD-020 recommendations for Pb-Free reflow soldering should be followed.

10.3 Errata

Please see the errata document for description and resolution of device errata. This document is available in Simplicity Studio and online at: http://www.silabs.com/support/pages/document-library.aspx?p=MCUs--32-bit

11. Revision History

Revision 2.20

August, 2019

- Updated 2. Ordering Information for release of revision C devices.
- 4.8 Flash – Added word write cycles between erase (WWC_{FLASH}) specification.

Revision 2.10

October, 2018

- 1. Feature List – Added temperature range for EFM32HGxxxFxxN part numbers.
- 2. Ordering Information – Added EFM32HGxxxFxxN part numbers and updated ordering code decoder.
- Added ADC0_CH[1:0] to Configuration Summary sections:
  - 3.2.2 EFM32HG110
  - 3.2.3 EFM32HG210
  - 3.2.4 EFM32HG222
  - 3.2.6 EFM32HG309
  - 3.2.7 EFM32HG310
  - 3.2.8 EFM32HG321
  - 3.2.9 EFM32HG322
  - 3.2.10 EFM32HG350
- 4.2 Absolute Maximum Ratings - Removed footnote about storage temperature and added max sink/source current per I/O pin.
- 4.3 General Operating Conditions – Added ambient temperature range specification for EFM32HGxxxFxxN part numbers.
- 4.4 Thermal Characteristics – Added thermal characteristics for QFN24, QFN32 and TQFP48 packages.
- 4.5 Current Consumption – Updated EM0 current and EM1 current test conditions. Added EM2 current, EM3 current, and EM4 current specifications for EFM32HGxxxFxxN part numbers.
- 4.8 Flash – Updated flash page erase time and device erase time and added footnotes.
- 4.9 General Purpose Input Output – Added input leakage current specification for EFM32HGxxxFxxN part numbers.
- 4.10.4 HFRCO - Removed 24 MHz band.
- In 4.11 Analog Digital Converter (ADC):
  - Updated test conditions, updated specifications, and added footnote for average active current.
  - Added input bias current.
  - Added input offset current.
  - Updated ADC clock frequency.
  - Updated SNR, SINAD and SFDR.
  - Updated offset voltage.
  - Updated missing codes.
  - Added gain error drift and offset error drift.
  - Removed ADC internal voltage reference.
  - Added VREF output voltage, VREF voltage drift, VREF temperature drift, VREF current consumption, and ADC and DAC VREF matching.
- 7.2 QFN24 PCB Layout - Corrected pin number for symbol P9.
- 8.2 QFN32 PCB Layout - Corrected pin number for symbol P9.

Rev 2.00

March, 2018

- Consolidated all EFM32HG data sheets:
  - EFM32HG108
  - EFM32HG110
  - EFM32HG210
  - EFM32HG222
  - EFM32HG308
  - EFM32HG309
  - EFM32HG310
  - EFM32HG321
  - EFM32HG322
  - EFM32HG350
- Added a Feature List section.
- 2. Ordering Information – Added ordering code decoder.
- 3.3 Memory Map – Separated the Memory Map into two figures – one for core and code space listing and one for peripheral listing.
- New formatting throughout.

Revision 1.00

December 4th, 2015

- This revision applies the following devices:
  - EFM32HG108
  - EFM32HG110
  - EFM32HG210
  - EFM32HG222
  - EFM32HG308
  - EFM32HG309
  - EFM32HG310
  - EFM32HG321
  - EFM32HG322
  - EFM32HG350
- Updated all specs with results of full characterization.
- Updated part number to revision B.
- For devices with USB, added the USB electrical specifications table.

Revision 0.91

May 6th, 2015

- This revision applies the following devices:
  - EFM32HG290
  - EFM32HG295
  - EFM32HG390
  - EFM32HG395
  - EFM32HG890
  - EFM32HG895
  - EFM32HG990
  - EFM32HG995
- Updated current consumption table for energy modes.
- Updated GPIO max leakage current.
- Updated startup time for HFXO and LFXO.
- Updated current consumption for HFRCO and LFRCO.
- Updated ADC current consumption.
- Updated IDAC characteristics tables.
- Updated ACMP internal resistance.
- Updated VCMP current consumption.

Revision 0.90

March 16th, 2015

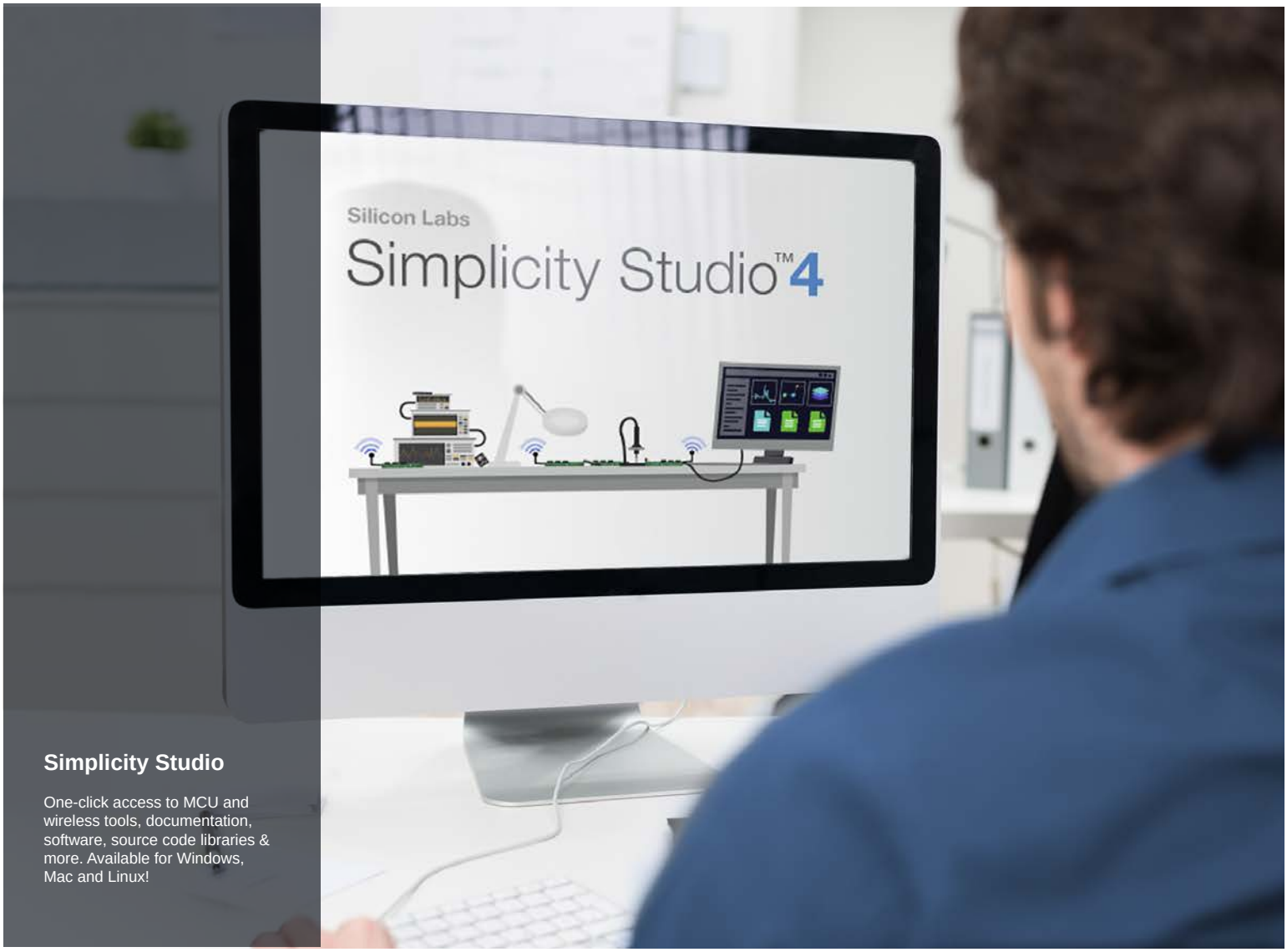
Note: This datasheet revision applies to a product under development. Its characteristics and specifications are subject to change without notice.

- This revision applies the following devices:
  - EFM32HG108
  - EFM32HG110
  - EFM32HG210
  - EFM32HG222
  - EFM32HG308
  - EFM32HG309
  - EFM32HG310
  - EFM32HG321
  - EFM32HG322
  - EFM32HG350
- Corrected EM2 current consumption condition in Electrical Characteristics section.
- Updated GPIO electrical characteristics.
- Updated Max ESR_{HFXO} value for Crystal Frequency of 25 MHz.
- Updated LFRCO plots.
- Updated HFRCO table and plots.
- Updated ADC table and temp sensor plot.
- Added DMA current in Digital Peripherals section.
- Updated block diagram.
- For QFN24 and QFN32 packages, updated package dimensions table.
- Corrected leadframe type to matte-Sn.

Revision 0.20

December 11th, 2014

- This revision applies the following devices:
  - EFM32HG108
  - EFM32HG110
  - EFM32HG210
  - EFM32HG222
  - EFM32HG308
  - EFM32HG309
  - EFM32HG310
  - EFM32HG321
  - EFM32HG322
  - EFM32HG350
- Preliminary Release.



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